

Table of Contents

Page	Title		Page	Title		Page	Title	
01			31	Sensor-uC		61	+1VSB	
02	CHANGE HISTORY		32	On Board-Sensors		62	+1.8VSB & Load SW	
03	BLOCK DIAGRAM		33	Debug Conn		63	CHARGER	
04	CLOCK DISTRIBUTION		34	Empty		64	+5V Load SW	
05	SIGNAL & RESET MAP		35	SM BUS		65	+3P3V Load SW	
06	POWER FLOW		36	EC-ITE 8528VG-1		66	VCPU Controller	
07	POWER DISTRIBUTION		37	EC-ITE 8528VG-2/SPI ROM		67	VCORE VCCSA	
08	POWER SEQUENCE		38	TPM		68	VCVGT	
09	I2C MAP		39	Temp Sensor/System Fan		69	EMPTY (was GTX Reg)	
10	CPU (1)_MISC,JTAG,DDI.EDP		40	REALTEK ALC298 CODEC		70	SL1 PWR/ BATT CONN.	
11	CPU (2)_LPDDR3		41	Audio Jack/Vol Button/Spkr		71	SL1 SIGNALS	
12	CPU (3)_SKL POWER1		42	Microphones		72	+3P3V_HPD/LCD backlight/TB	
13	CPU (4)_SKL_POWER2		43	M.2 SSD CONNECTOR		73	BLADE PWR	
14	CPU (5)_GND		44	Empty		74	BLADE	
15	CPU (6)_CFG_RESERVED		45	USB3.0		75	Power Protect	
16	LPDDR3 (1)_MEMORY DOWN		46	DP Dongle Control		76	Test Points	
17	LPDDR3 (2)_MEMORY DOWN		47	mDP				
18	XDP		48	SDXC				
19	LPDDR3 (3)_CA/DQ Voltage		49	Camera IR				
20	PCH (1)_SD,HDA,RTC, CLK		50	Wi-Fi_BT				
21	PCH (2)_CLK,SMB,LPC, SPI		51	Components for ME/EMI				
22	PCH (3)_SYS PWR CONTR		52	Camera Power				
23	PCH (4)_CCI, HWID		53	Camera Rear				
24	PCH (5)_PCIE,USB		54	Camera Front				
25	PCH (6)_CPU,GPIO,MISC		55	3P3VA & BKL PWR				
26	PCH (7)_POWER		56	+VCCIO & 0P85VSB				
27	PCH (8)_empty		57	eDP connector				
28	Power Monitor		58	+VCCEDRAM & +VCCEOPIO				
29	Empty		59	+5VSB & +3P3VSB				
30	Touch Con & Key		60	+1P2V_DUAL&+VTT				

CAD Note:
Default component footprint is SMD 0201, X5R, 1% resistors.

Property: BUILD-OPT
DNP = Do Not Place
Vinafix.com

S or DB = Replace after Debug

<Core Design>			
Title:		Table of Contents	
Engineer:		Surface	
Size	Project Name	Rev	
A3	U -- EV 1.90	1.90.2	
Date:	Monday, May 11, 2015	Sheet	1 of 76

Schematics Change History

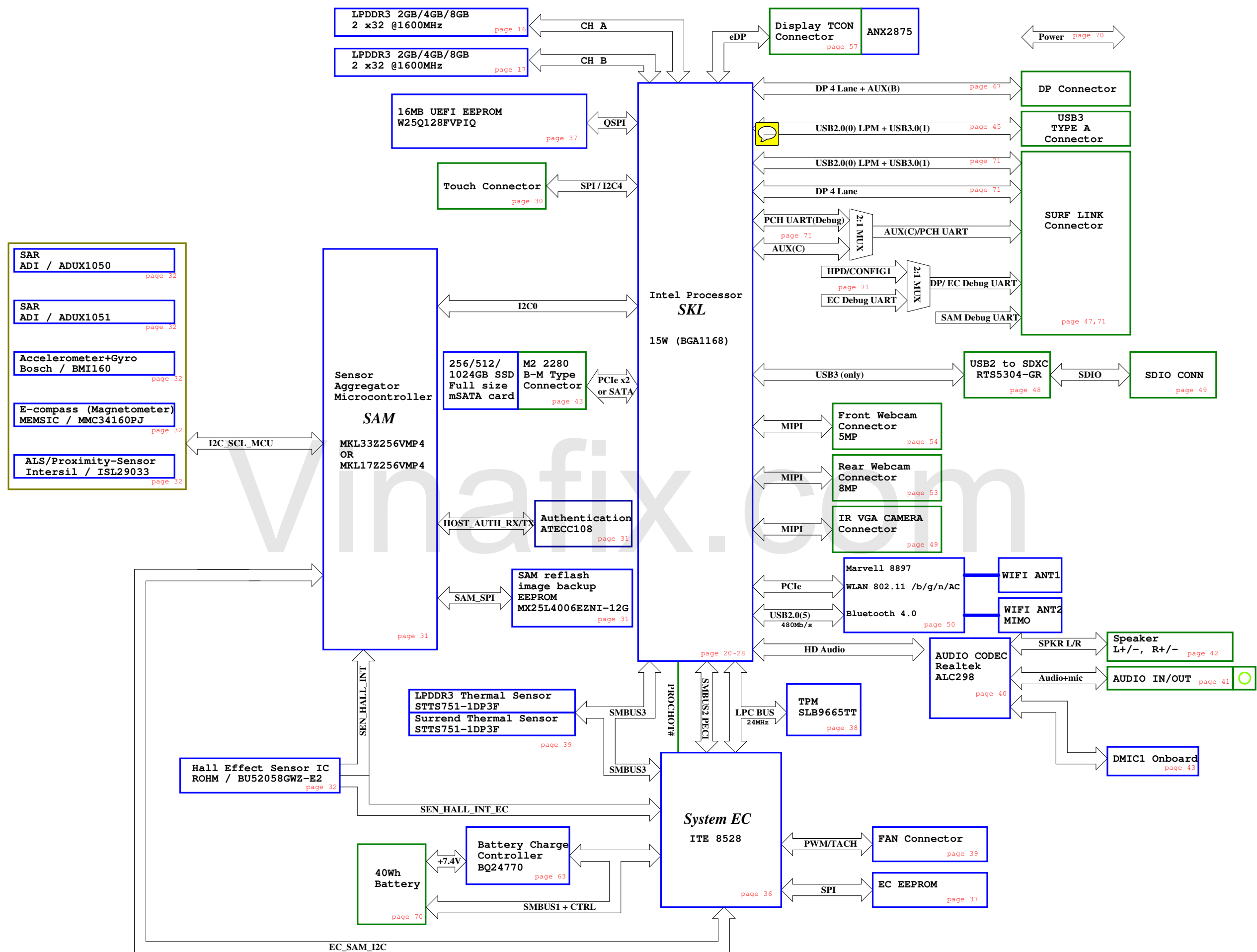
Rev.	Date	Comments
Op9	28 Oct 2014	1. Starting with G_EV1_1021-1630.DSN 2. Added SL schematic from page 72 ...\\T\\MB\\DV_RELEASED\\Schematic\\CASTLE2_DV_2014_1021_1100.DSN 3. Added External USB3 schematic from ...\\T\\MB\\DV_RELEASED\\Schematic\\CASTLE2_DV_2014_1021_1100.DSN 4. Added external DP ...\\T\\MB\\DV_RELEASED\\Schematic\\CASTLE2_DV_2014_1021_1100.DSN 5. Added IR_CAMERA from Front Camera...put in page 49 6. Removed page 73 PCIe GPU 7. Added Blade from T 8. Removed P72 T2B Pwr Transistors
Op10	3 Nov 2014	1. Changing to NVDC 2. Replaced GTX with GT, kept bypass caps 3. Replaced Charger with BQ24770
Op11	3 Nov 2014	1. Replace SKL-U with SKL-Y
Op12	11 Nov 2014	1. Model DDR connection from Intel SDS
Op13	18 Nov 2014	1. Added FUB information to all components 2. Changed Decretes.. sizing caps
Op14	20 Nov 2014	1. Added +5VA_SHA 2. Added T Cost Down/XCN's 3. Added SL +5V load Switch & Caps 4. Added Blade +5V load Switch & Caps
Op15	26 Nov 2014	1. Removed Boost 2. Re-adjusted usb ports on CPU 3. Removed Audio DSP
Op16	03 Dec 2014	1. changed +1VSB regulator 2. changed IR Camera/added diode 3. added power numbers from 0.91 PDG, Oct14 4. changed BLADE connector 5. cpu decoupling caps changed 6. changed +5V/+3V inductors (place holder)
Op17	05 Dec 2014	1. swapped M_A_CAA with MA_CAB on U1601/U1602 2. added two SAR chips, P32 3. remove tp's from csi lines on (p23) 4. change from 10 ceramic to 3 tantalum-poly on usb3 typeA (p45) 5. remove the RSENSE from output of +VCCIO(p56)/+0p85VSB(p56)/+VCCEDRAM (p58)/+VCCEOPIO (p58)/+1VSB(p61)/+1P8VSB(p62) 6. change RSENSE input to 0402 from 0603 for +VCCIO(p56)/+0p85VSB(p56)/+VCCEDRAM (p58)/+VCCEOPIO (p58)/+1VSB(p61)/+1P8VSB(p62) input regulator 7. change inductor for +VCCIO(p56)/+0p85VSB(p56)/+VCCEDRAM (p58) to HMLE20161B-1R0MDR-01 8. change RSENSE input to 0402 from 0603 for +5V_TS,+5V_SDXC,+5V_AUDIO,+5V, +5V_FAN(p64) 9. change RSENSE input to 0402 from 0603 for +3P3V_PANEL,+3P3V,+3P3V_SENSOR,+1P8V_DMIC (p65) 10. Replacing the SL connector with X908351-001 11. Replace PL5901 and PL5902 with CMLE042T-2R2MS-01 12. Replace 0402 1uF 6.3V with 0201 1uF 6.3V X5R 13. Replace L7201 with TOKO #A919CY-100M 14. Added VSYS -> BLADE FANG supply (p73)
Op18	09 Dec 2014	1. Reduced sizes of parts for Cameras (Resistors/Caps/Regulators)
Op19	12 Dec 2014	1. All 47uF caps become 0805/1mmZ 2. All 10uF caps become 0402...4V/6.3V
Op20	15 Dec 2014	1. changed SAM flash to reduce size to 2x3 from 5x4 2. Shui Changes 3. more Shui Changes
Op21	16 Dec 2014	1. changed SAM flash to reduce size to 2x3 from 5x5 2. changes from EV_schematic_issue_check_1216_JDM1.xlsx 3. changed name of +6_12 to +V_ALWAYS_ON 4. Removed 2 Mikes & Front Mike & added FPC conn 5. Added 2nd BLADE connector
Op22	17 Dec 2014	1. Replaced SD connector with AY531465T 2. changes from EV_schematic_issue_check_viola_1217_JDM1.xlsx
Op23 current		1. See apexUfixes_revXpXX.xlsx

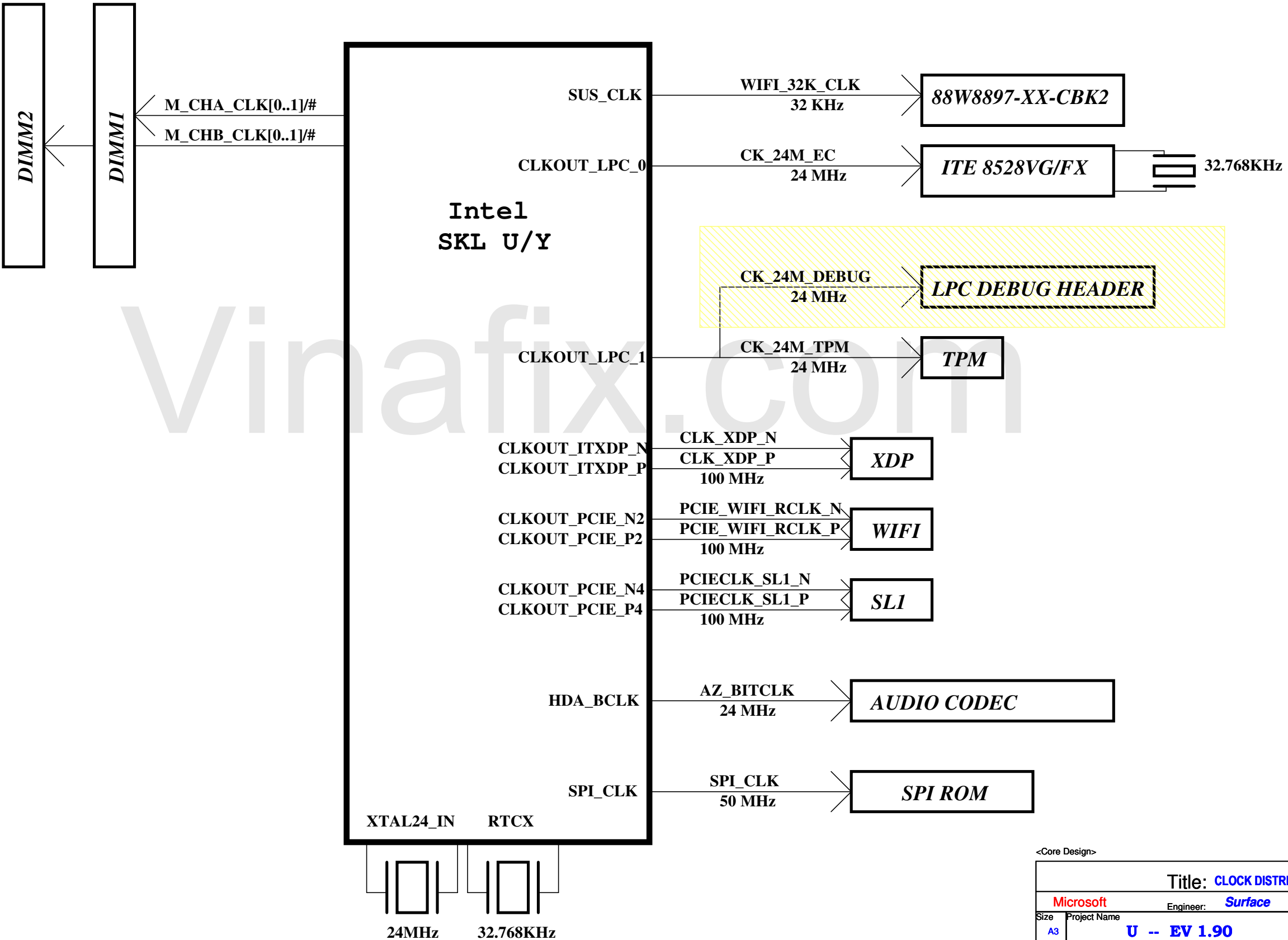
CAD Note:
Default component footprint is SMD 0201, X5R, 1% resistors S = Short after design fixed

Property: BUILD-OPT

DNP = Not Installed Part.

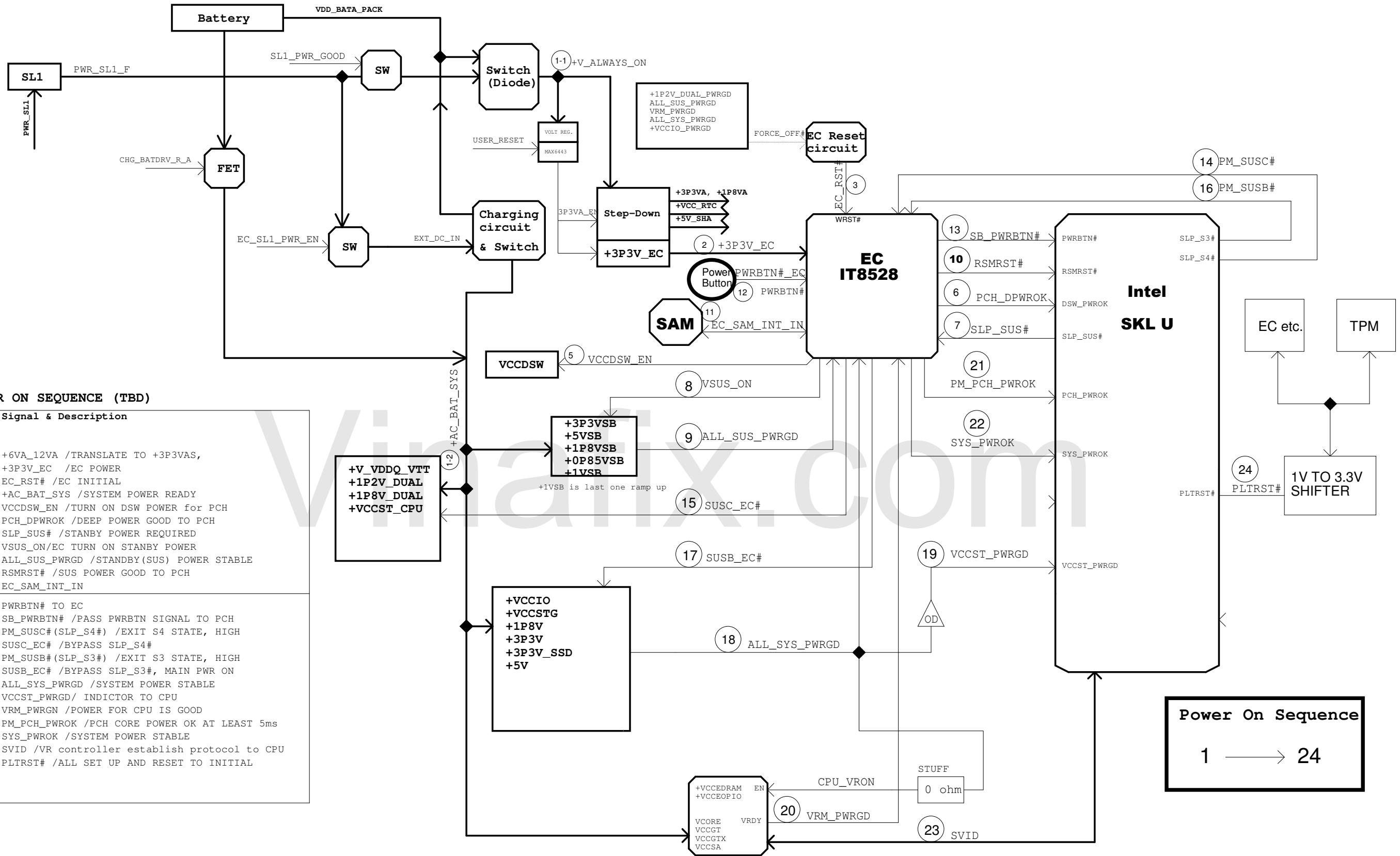
Title: CHANGE HISTORY-1		
Engineer: Surface		
Size A3	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015 Sheet 2 of 76		





POWER ON SEQUENCE (TBD)

STEP	Signal & Description
1	+6VA_12VA /TRANSLATE TO +3P3VAS,
2	+3P3V_EC /EC POWER
3	EC_RST# /EC INITIAL
4	+AC_BAT_SYS /SYSTEM POWER READY
5	VCCDSW_EN /TURN ON DSW POWER for PCH
6	PCH_DPWROK /DEEP POWER GOOD TO PCH
7	SLP_SUS# /STANBY POWER REQUIRED
8	VSUS_ON/EC TURN ON STANBY POWER
9	ALL_SUS_PWRGD /STANDBY(SUS) POWER STABLE
10	RSMRST# /SUS POWER GOOD TO PCH
11	EC_SAM_INT_IN
12	PWRBTN# TO EC
13	SB_PWRBTN# /PASS PWRBTN SIGNAL TO PCH
14	PM_SUSC#(SLP_S4#) /EXIT S4 STATE, HIGH
15	SUSC_EC# /BYPASS SLP_S4#
16	PM_SUSB#(SLP_S3#) /EXIT S3 STATE, HIGH
17	SUSB_EC# /BYPASS SLP_S3#, MAIN PWR ON
18	ALL_SYS_PWRGD /SYSTEM POWER STABLE
19	VCCST_PWRGD/ INDICATOR TO CPU
20	VRM_PWRGN /POWER FOR CPU IS GOOD
21	PM_PCH_PWROK /PCH CORE POWER OK AT LEAST 5ms
22	SYS_PWROK /SYSTEM POWER STABLE
23	SVID /VR controller establish protocol to CPU
24	PLTRST# /ALL SET UP AND RESET TO INITIAL

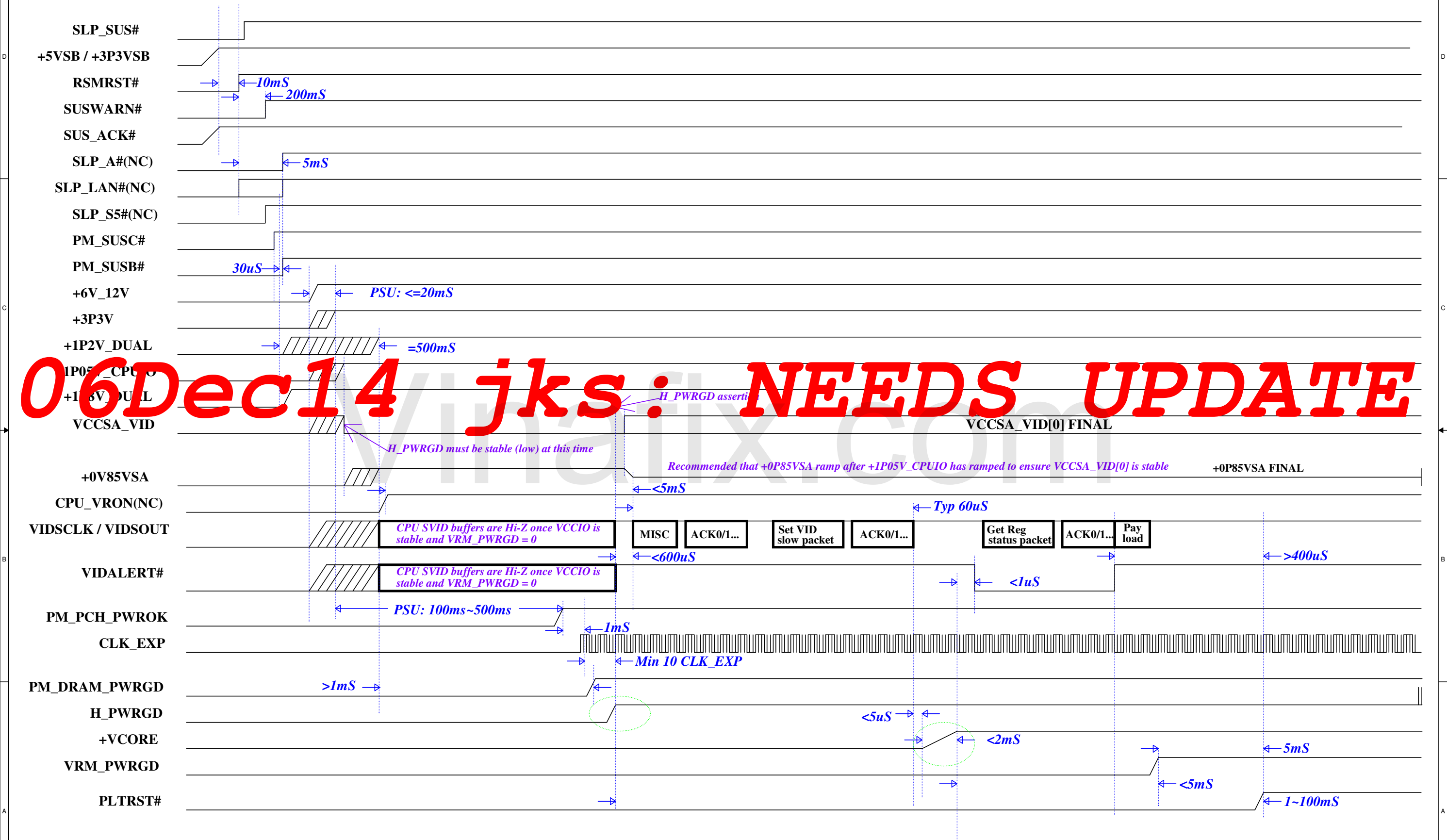


Power On Sequence

1 → 24



S5 to S0 Power Sequence



06Dec14 jks: NEEDS UPDATE

I2C & SMBUS Map

SML1_PCH_DATA
SML1_PCH_CLK

Q3501
Q3504

PCH_I2C1_SDA_3V3
PCH_I2C1_SCL_3V3

R3001
R3003

TS_A_I2C_SDA_CON
TS_A_I2C_SCL_CON

Touch Connector
CON3001 0x60

Surrend
TEMP Sensor
U3901 0x4B

Skin
TEMP Sensor
U3902 0x3B

Skin
TEMP Sensor
U3903 0x3A

Skin
TEMP Sensor
U3904 0x4A

SML3_EC_DATA
SML3_EC_CLK

SH_I2C_SDA
SH_I2C_SCL

Debug Connector
CON3302

U3501

SML0_EC_DATA
SML0_EC_CLK

EC
U3601 0x4E

I2C_SDA_MCU_R
I2C_SCL_MCU_R

R3122
R3124

I2C_SDA_MCU
I2C_SCL_MCU

TEMP Sensor
U3211 0x3A

SML1_EC_DATA
SML1_EC_CLK

CHG_SDA_A
CHG_SCL_A

Charger
U6301 0x12

PR6309
PR6310
0 ohm

R7032/L7005
R7033/L7006

EC_SMCLK_BAT
EC_SMDATA_BAT

Battery
Connector
CON7001 0x16

SAM
U3105 0x28

ADUX1050
U3206 0x2D

ADUX6

R3285
R3287

ADUX1050
U3207 0x2C

ADUX7

R3286
R3288

R3212
R3213

MAG2_X_SDA
MAG2_X_SCL

Accel & Gyro
U3202 0x68

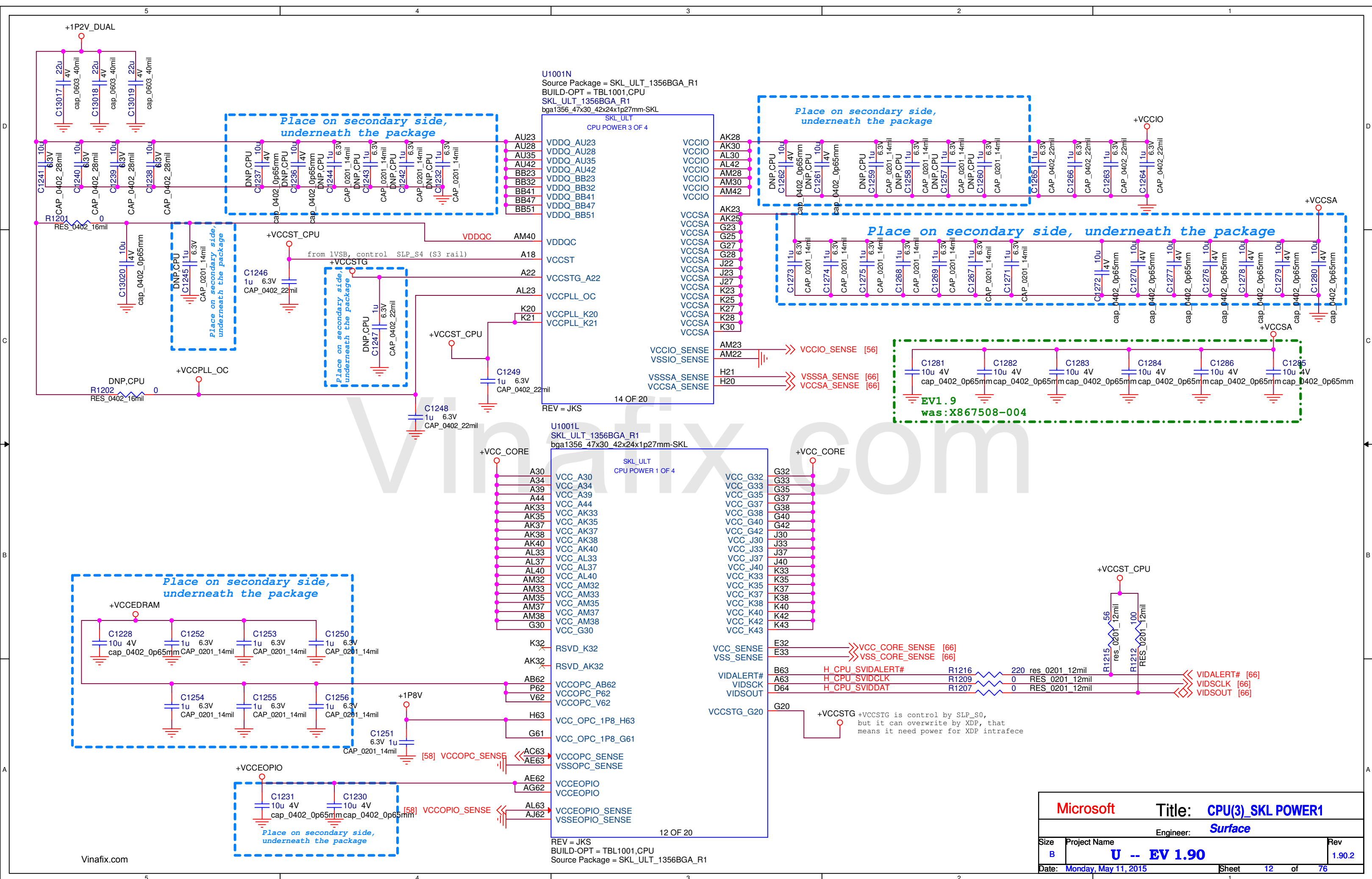
MAG2_SCL_3V3
MAG2_SDA_3V3

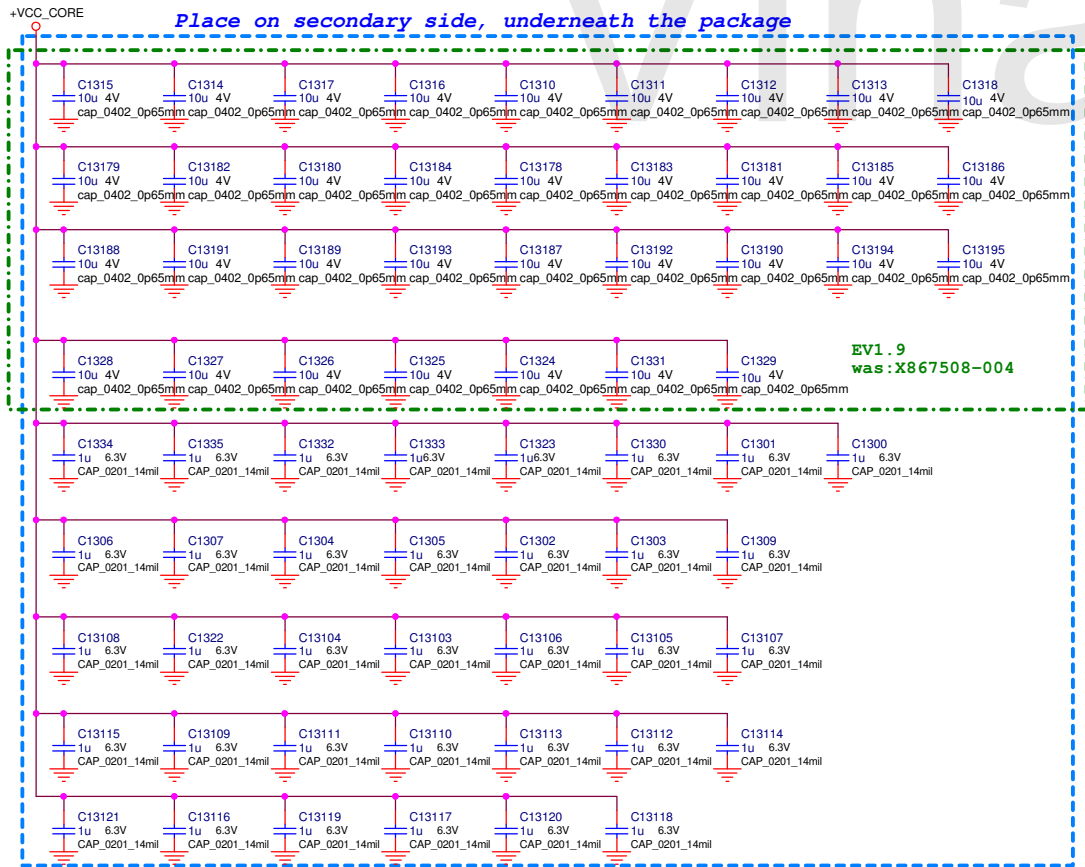
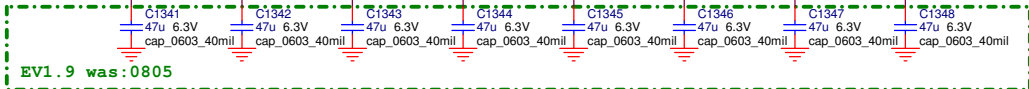
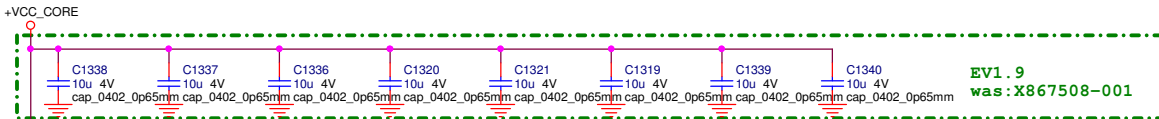
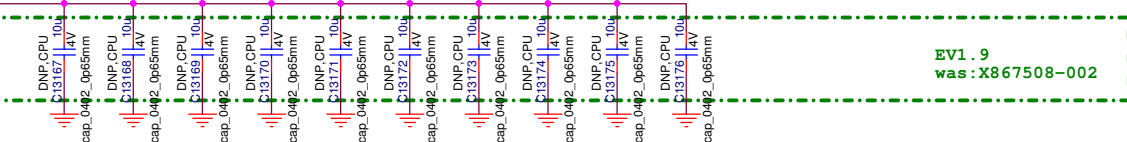
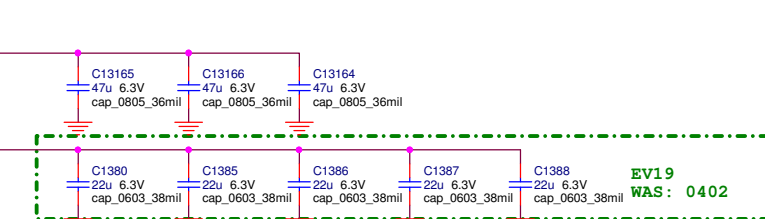
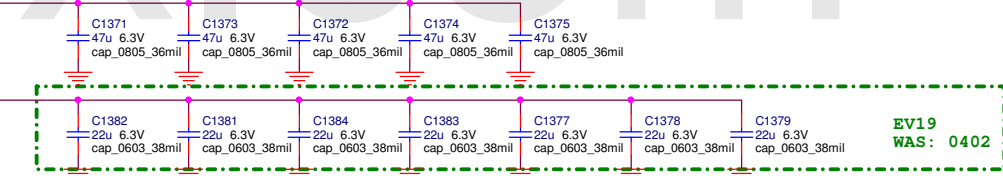
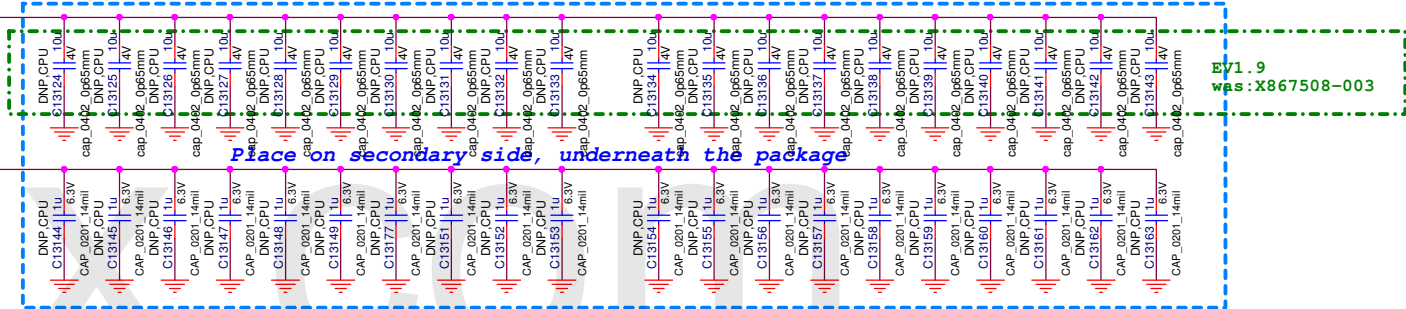
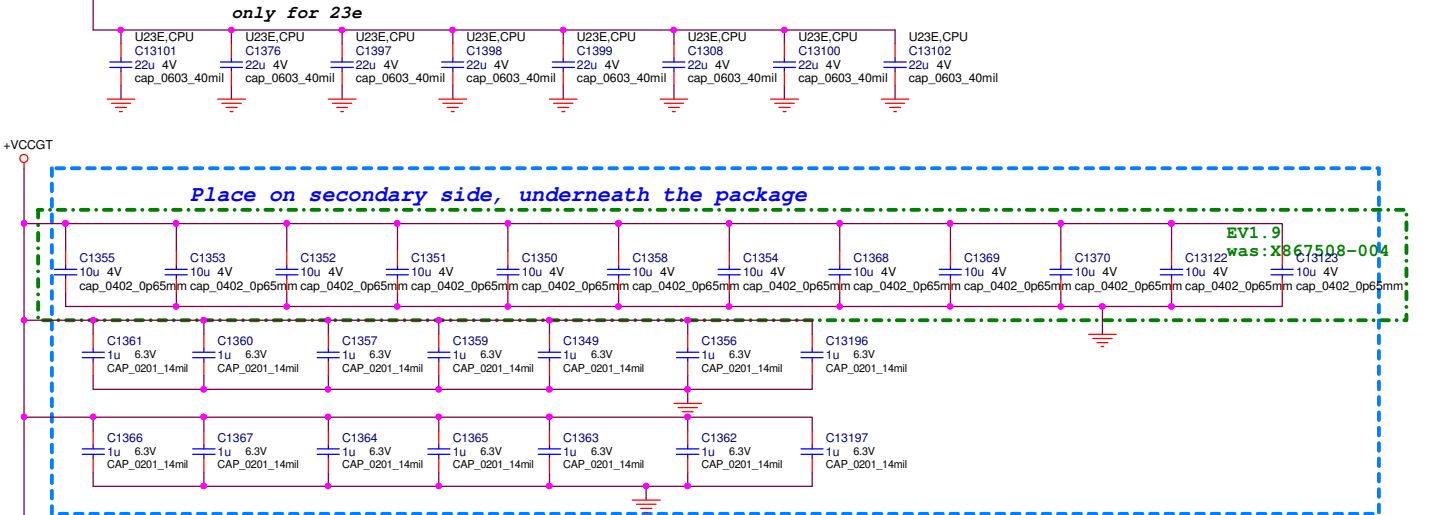
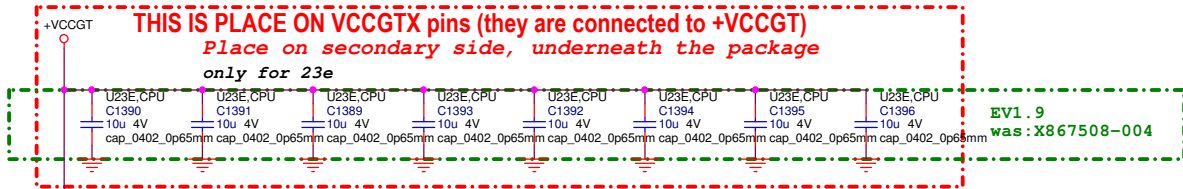
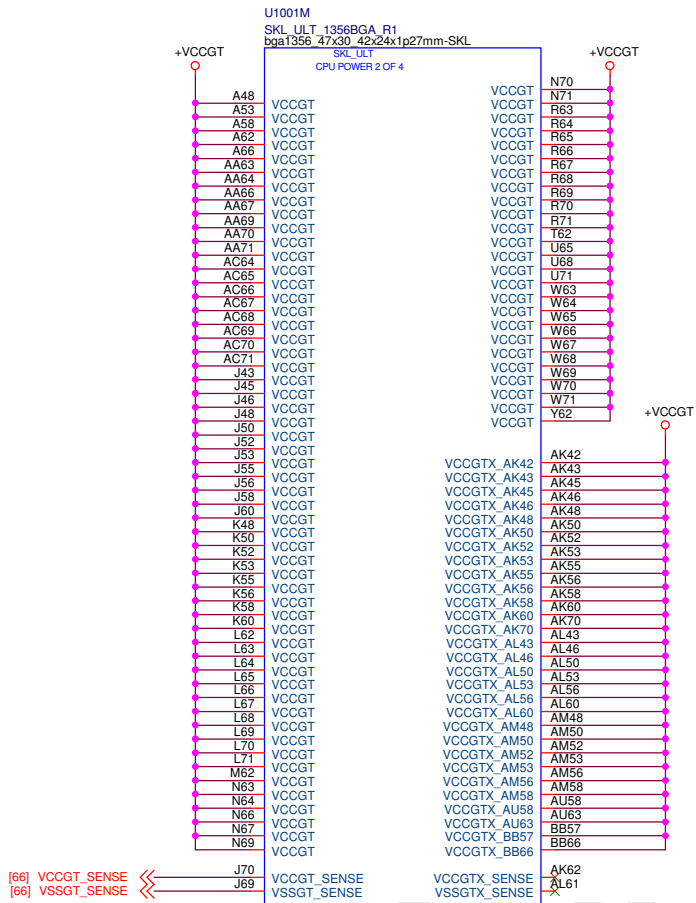
Magnetometer
U3203 0x30

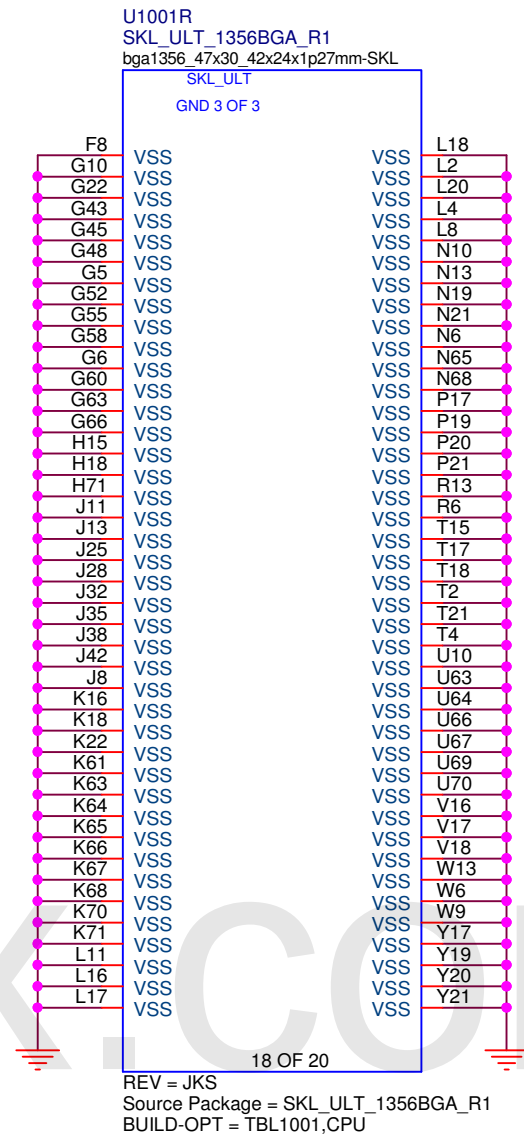
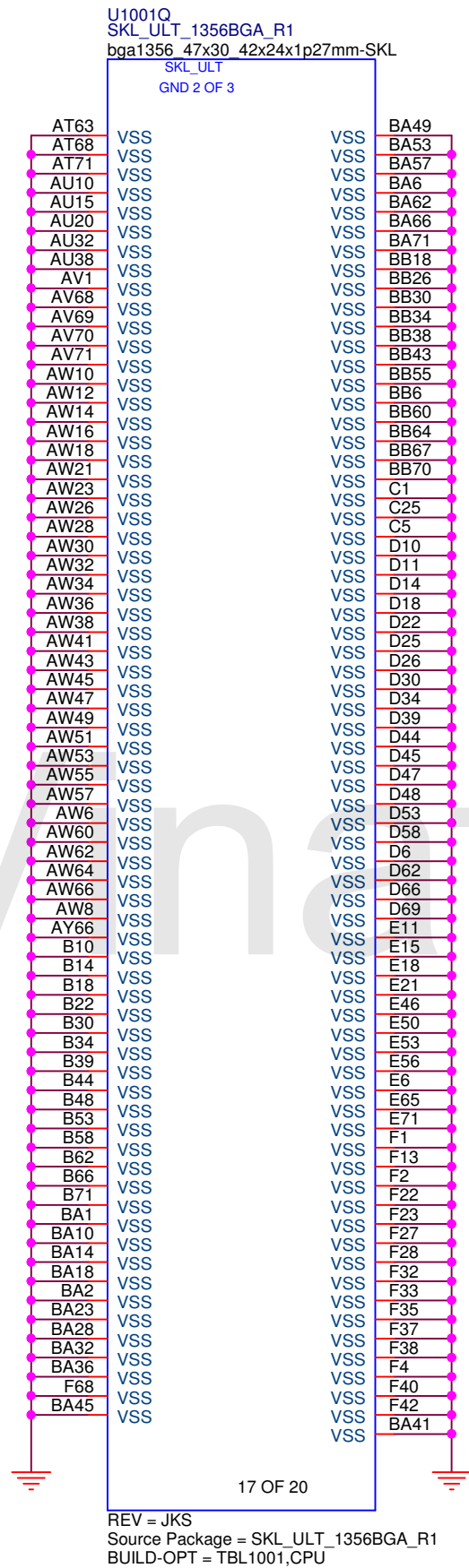
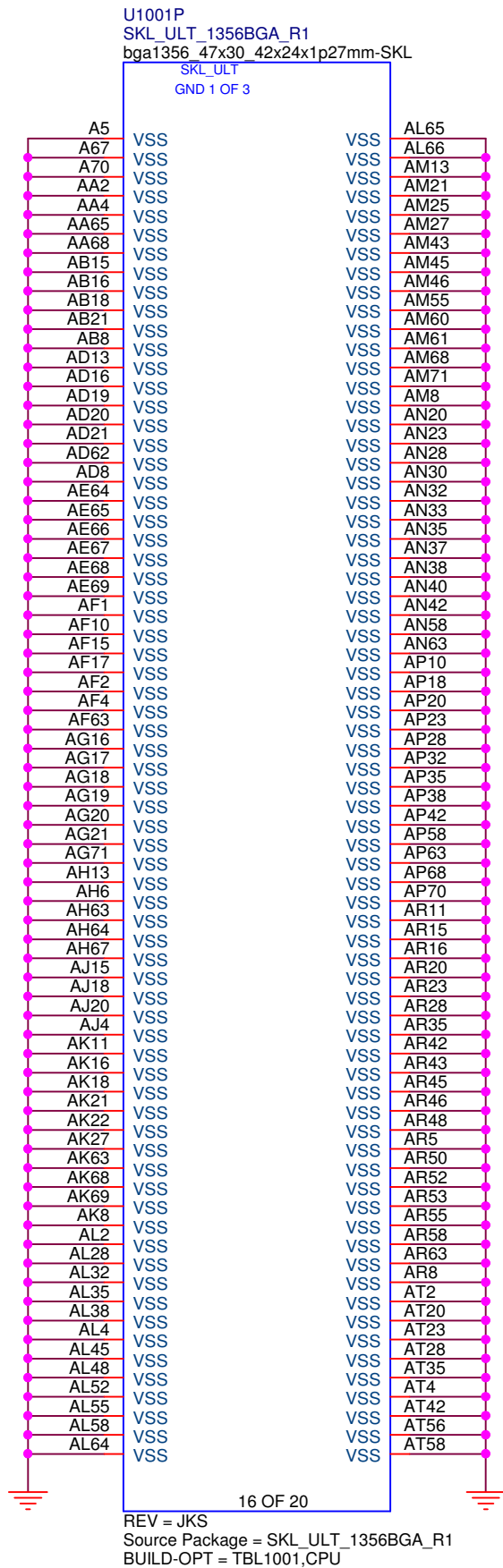
R3229
R3230

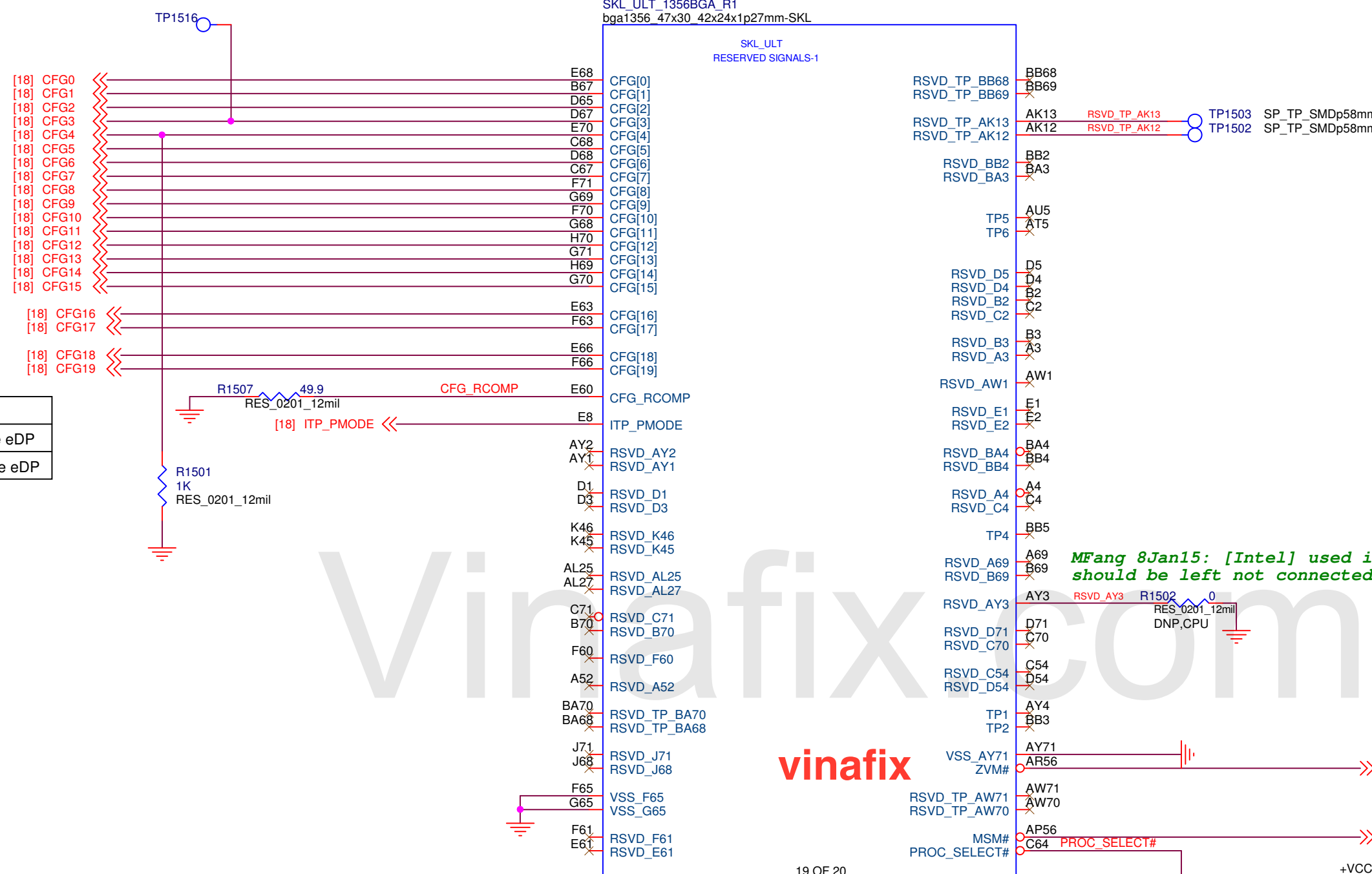
R3266
R3267

R3210
R3211







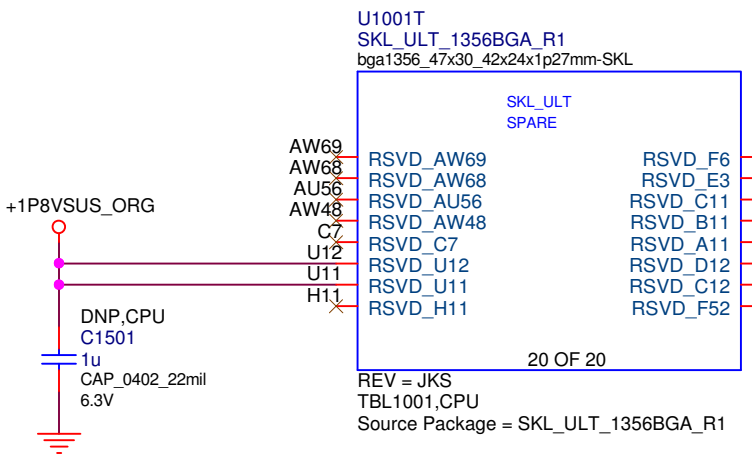


CFG4	
0 Default	enable eDP
1	Disable eDP

MFang 8Jan15: [Intel] used in the HVM testing should be left not connected.

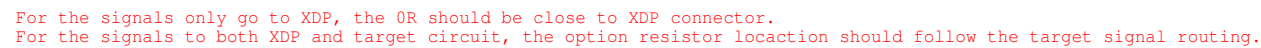
ZVM# and MSM# may need to control the VCCOCP and VCCEOP10

100k ohm resistor only needed for Cannonlake



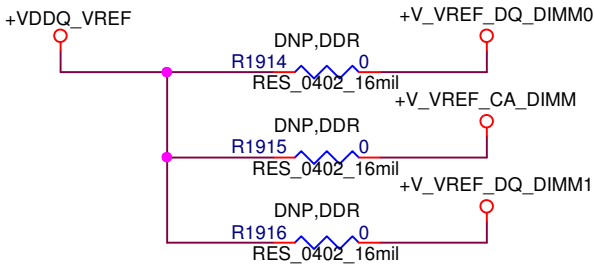
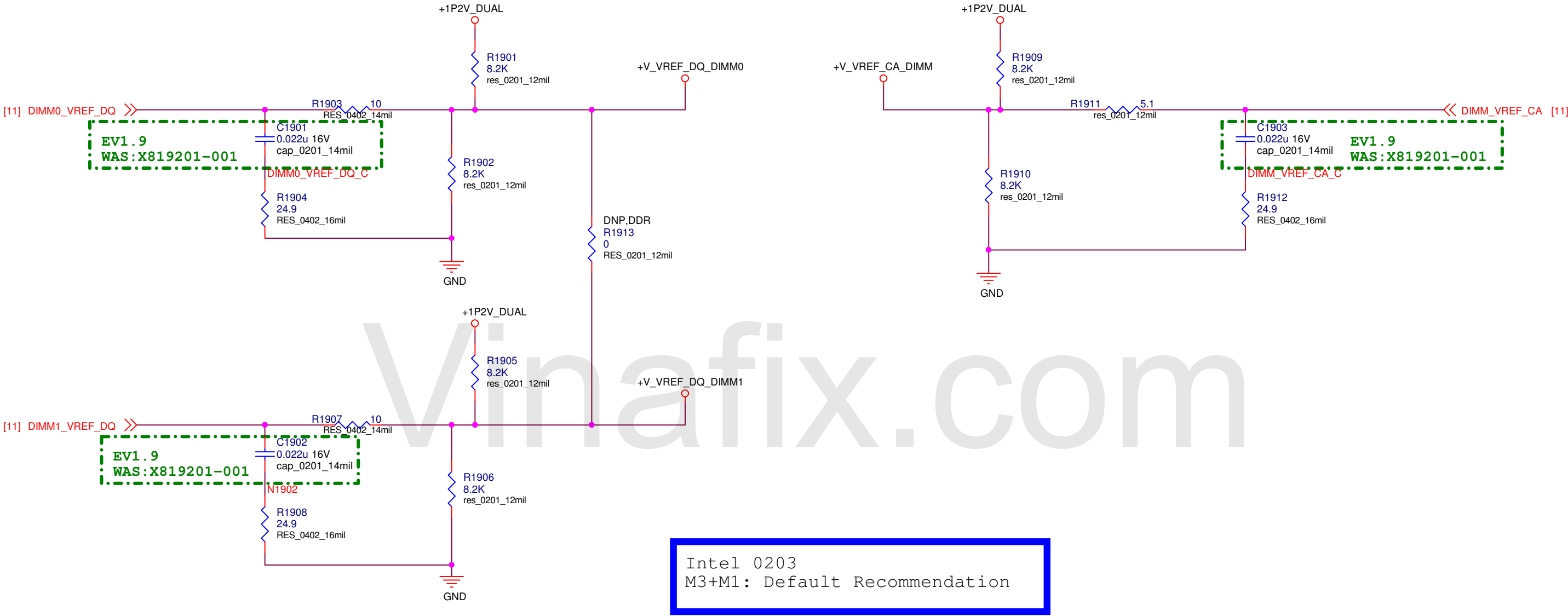
Microsoft		Title: CPU(6)_CFG_RESERVED	
Size B		Engineer: Surface	
Date: Monday, May 11, 2015		Rev 1.90.2	
Sheet 15		of 76	

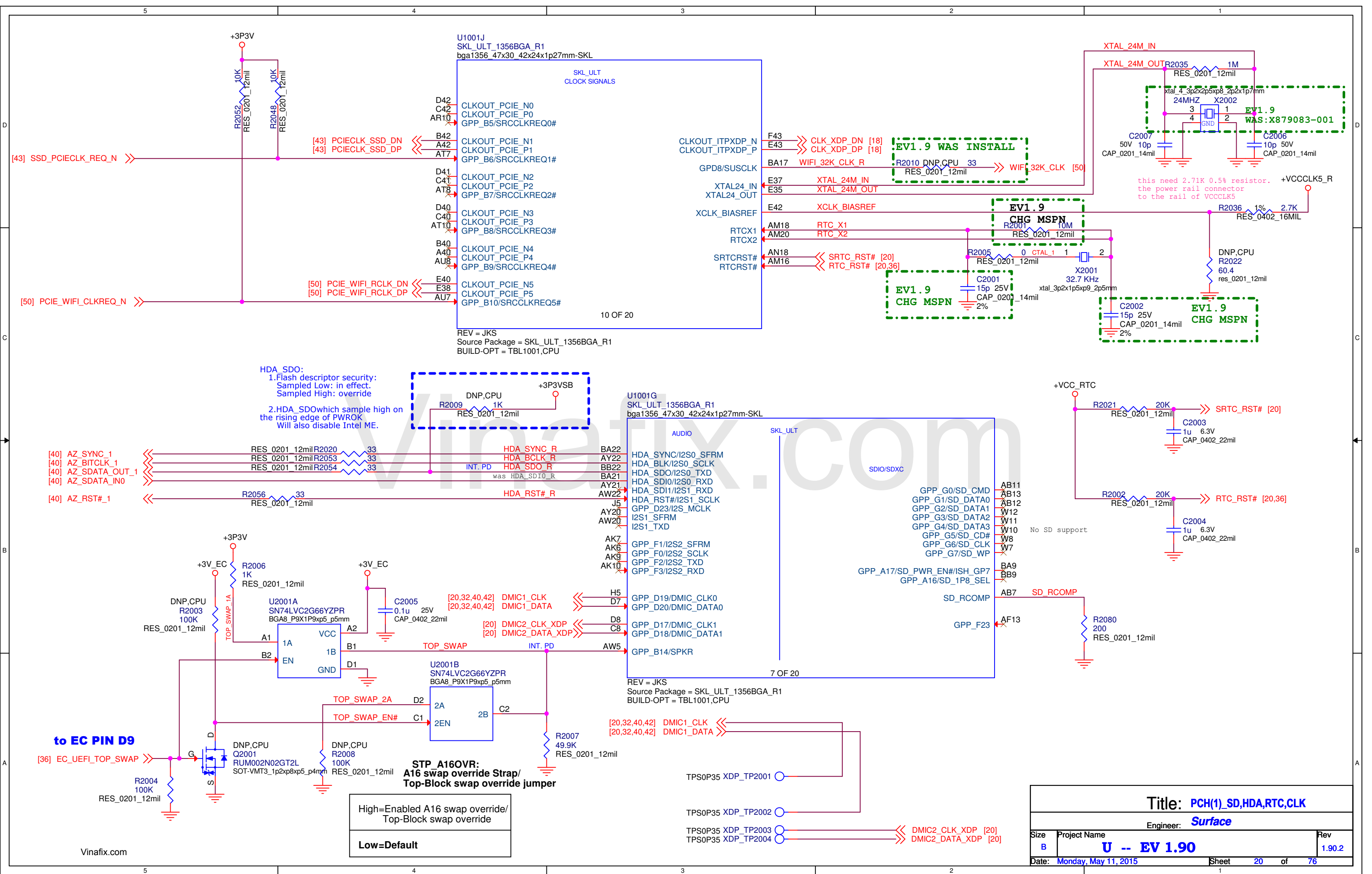
[15,18] CFG3 <<----- ROUTE WITH MINIMAL STUB WITH RESPECT TO CFG<3>



LPDDR3 Vref

M3: CPU driven VREF path is stuffed be default.
M1: VREF_DQ driven by a Voltage Divider Network during Processor power-off

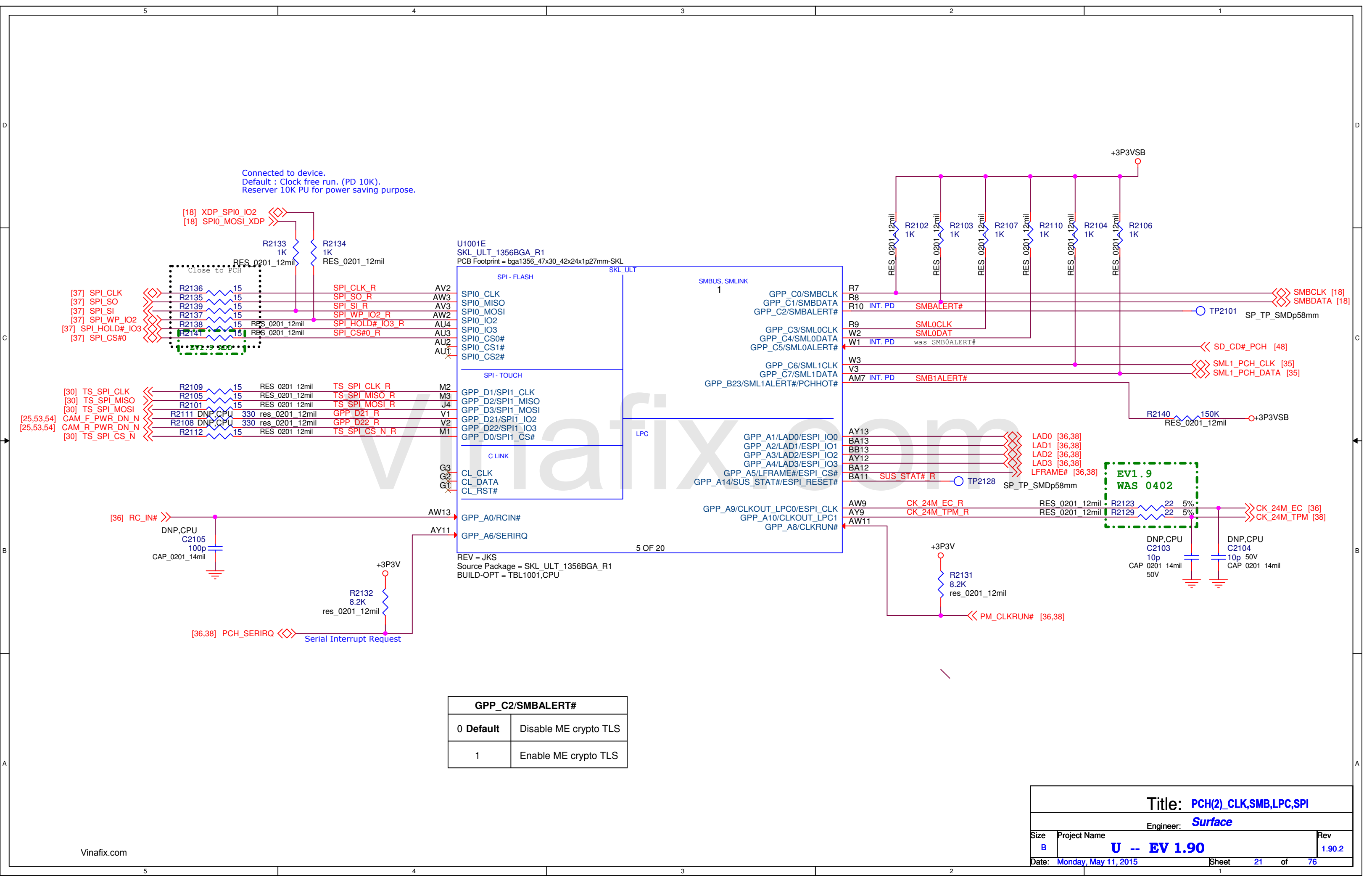




High=Enabled A16 swap override/
Top-Block swap override

Low=Default

Title: PCH(1)_SD,HDA,RTC,CLK		
Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 20 of 76	



Connected to device.
Default : Clock free run. (PD 10K).
Reserver 10K PU for power saving purpose.

[18] XDP_SPI0_IO2
[18] SPI0_MOSI_XDP

[37] SPI_CLK
[37] SPI_SO
[37] SPI_SI
[37] SPI_WP_IO2
[37] SPI_HOLD#_IO3
[37] SPI_CS#0

[25,53,54]
[25,53,54]

[30] TS_SPI_CLK
[30] TS_SPI_MISO
[30] TS_SPI_MOSI
CAM_F_PWR_DN_N
CAM_R_PWR_DN_N
[30] TS_SPI_CS_N

[36] RC_IN#
DNP,CPU
C2105
100p
CAP_0201_14mil

[36,38] PCH_SERIRQ
Serial Interrupt Request

U1001E
SKL_ULT_1356BGA_R1
PCB Footprint = bga1356_47x30_42x24x1p27mm-SKL

SPI - FLASH
SPI0_CLK
SPI0_MISO
SPI0_MOSI
SPI0_IO2
SPI0_IO3
SPI0_CS0#
SPI0_CS1#
SPI0_CS2#

SPI - TOUCH
GPP_D1/SPI1_CLK
GPP_D2/SPI1_MISO
GPP_D3/SPI1_MOSI
GPP_D21/SPI1_IO2
GPP_D22/SPI1_IO3
GPP_D0/SPI1_CS#

C LINK
CL_CLK
CL_DATA
CL_RST#

GPP_A0/RCIN#
GPP_A6/SERIRQ

REV = JKS
Source Package = SKL_ULT_1356BGA_R1
BUILD-OPT = TBL1001,CPU

SMBUS, SMLINK
1

GPP_C0/SMBCLK
GPP_C1/SMBDATA
GPP_C2/SMBALERT#

GPP_C3/SML0CLK
GPP_C4/SML0DATA
GPP_C5/SML0ALERT#

GPP_C6/SML1CLK
GPP_C7/SML1DATA
GPP_B23/SML1ALERT#/PCHHOT#

GPP_A1/LAD0/ESPI_IO0
GPP_A2/LAD1/ESPI_IO1
GPP_A3/LAD2/ESPI_IO2
GPP_A4/LAD3/ESPI_IO3
GPP_A5/LFRAME#/ESPI_CS#
GPP_A14/SUS_STAT#/ESPI_RESET#

GPP_A9/CLKOUT_LPC0/ESPI_CLK
GPP_A10/CLKOUT_LPC1
GPP_A8/CLKRUN#

+3P3VSB

R2102 1K
R2103 1K
R2107 1K
R2110 1K
R2104 1K
R2106 1K

R7
R8
R10 INT. PD
R9
W2
W1 INT. PD
W3
V3
AM7 INT. PD

SMBCLK [18]
SMBDATA [18]
TP2101 SP_TP_SMDp58mm
SMBALERT#
SML0CLK
SML0DAT
was SMB0ALERT#
SD_CD#_PCH [48]
SML1_PCH_CLK [35]
SML1_PCH_DATA [35]
SMB1ALERT#

R2140 150K
RES_0201_12mil
+3P3VSB

AY13
BA13
BB13
AY12
BA12
BA11
TP2128 SP_TP_SMDp58mm
SUS_STAT#_R

LAD0 [36,38]
LAD1 [36,38]
LAD2 [36,38]
LAD3 [36,38]
LFRAME# [36,38]

EV1.9
WAS 0402

CK_24M_EC_R
CK_24M_TPM_R
RES_0201_12mil
RES_0201_12mil
R2123 22 5%
R2129 22 5%
CK_24M_EC [36]
CK_24M_TPM [38]

DNP,CPU
C2103
10p
CAP_0201_14mil
50V

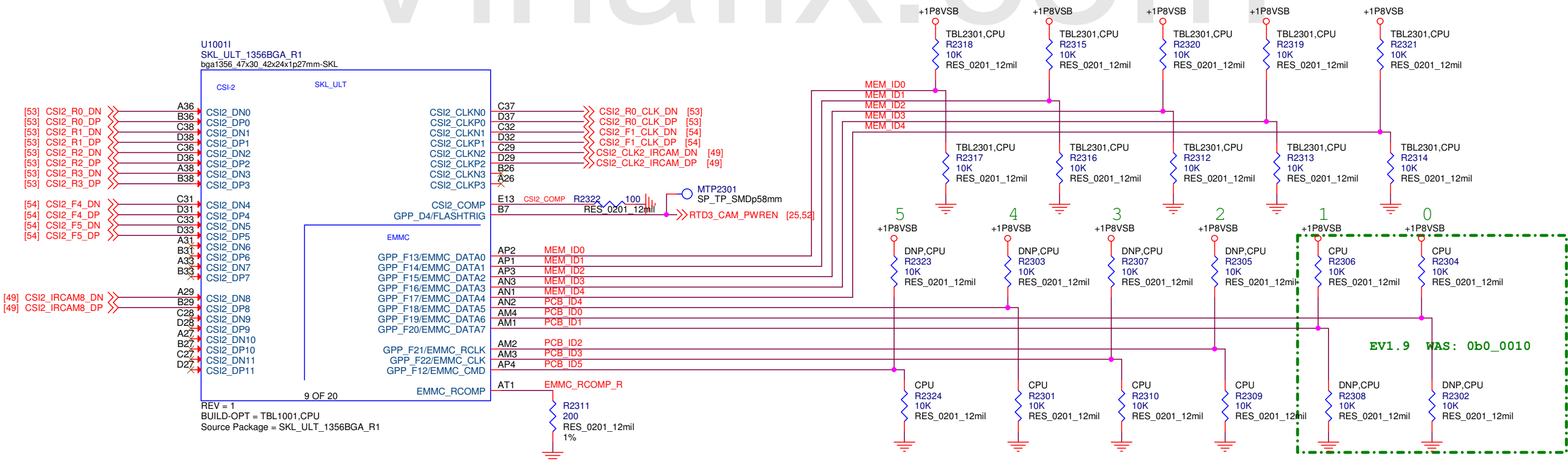
DNP,CPU
C2104
10p 50V
CAP_0201_14mil

+3P3V
R2131 8.2K
res_0201_12mil
PM_CLKRUN# [36,38]

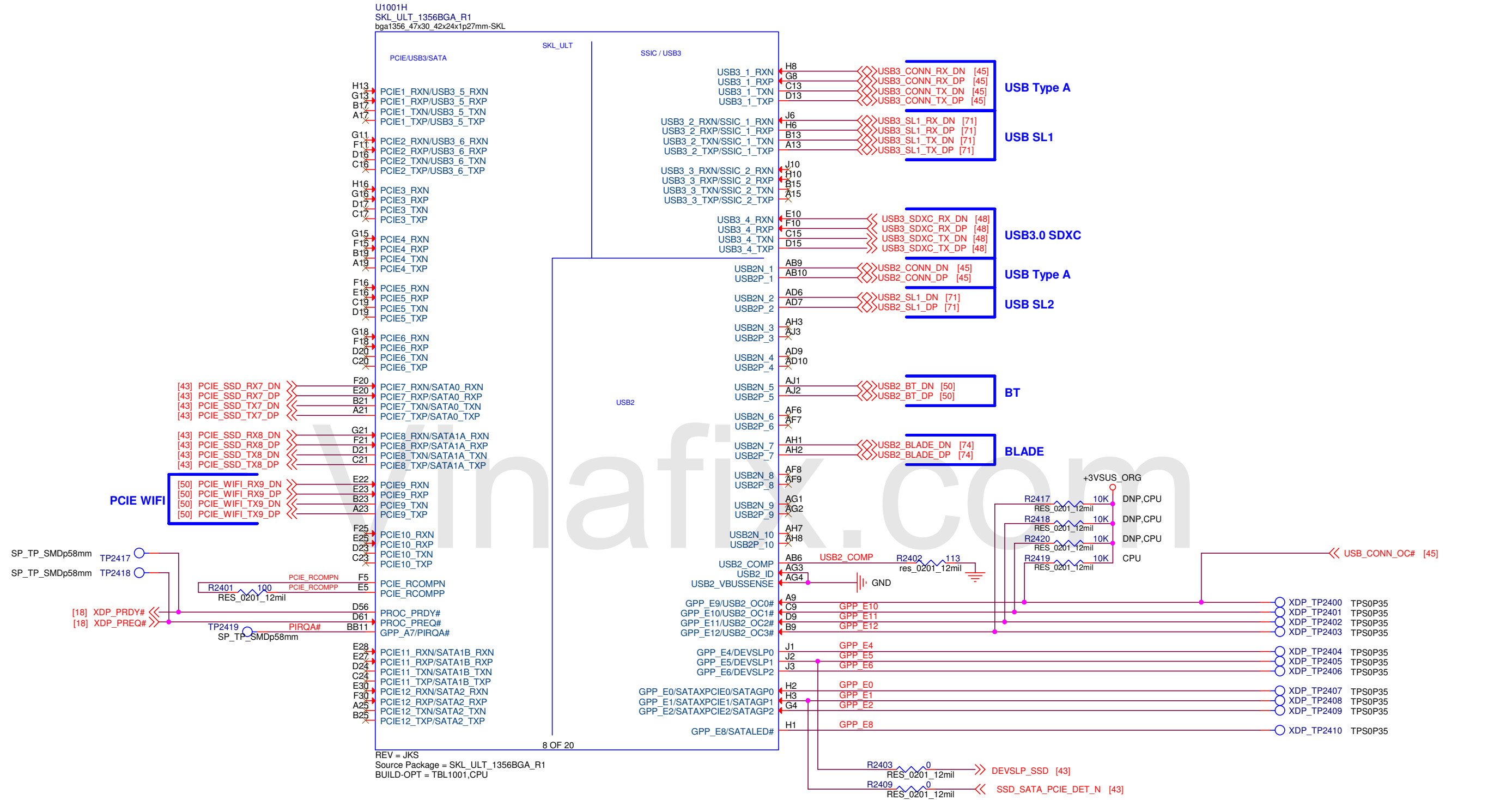
GPP_C2/SMBALERT#	
0 Default	Disable ME crypto TLS
1	Enable ME crypto TLS

Rev 4	EC Processor ID		PCH ID	TPM			EC Board Rev	PCH Board ID[3:0]				DRAM Manufacturer		RAM Speed	RAM Size & Calibration		
Signal	EC_ID1	ED_ID0	PCB_ID5	PCB_ID4			R3619	PCB_ID3	PCB_ID2	PCB_ID1	PCB_ID0	MEM_ID1	MEM_ID0	MEM_ID4	MEM_ID3	MEM_ID2	ZQ1
	1 = R3642 0 = R3643	1 = R3640 0 = R3641	1 = R2323 0 = R2324	1 = R2303 0 = R2301	R3813 R3815 R3816	R3814		1 = R2307 0 = R2310	1 = R2305 0 = R2309	1 = R2306 0 = R2308	1 = R2304 0 = R2302	1 = R2315 0 = R2316	1 = R2318 0 = R2317	1 = R2321 0 = R2314	1 = R2319 0 = R2313	1 = R2320 0 = R2312	R1602 R1604 R1702 R1704
	U22 = 0 U23E = 1 Y = 0 S = 1	U22 = 0 U23E = 0 Y = 1 S = 1	U = 0 Y = 1	Infineon = 0 Nation Z = 1	Infineon = DNP NationZ = POP	Infineon = POP NationZ = DNP						Hynix = 0 Samsung = 0	Hynix = 0 Samsung = 1	1600 LPDDR3 = 0 1866 LPDDR3 = 1	4GB = 0 8GB = 0 16GB = 1	4 GB = 0 8 GB = 1 16 GB = 0	4GB = DNP 8GB = POP 16GB = POP
EV 0.9							80.6 Ω	0	0	0	0						
EV 1.0							169 Ω	0	0	0	1						
EV 1.5							698 Ω	0	0	1	0						
EV 1.9							909 Ω	0	0	1	1						

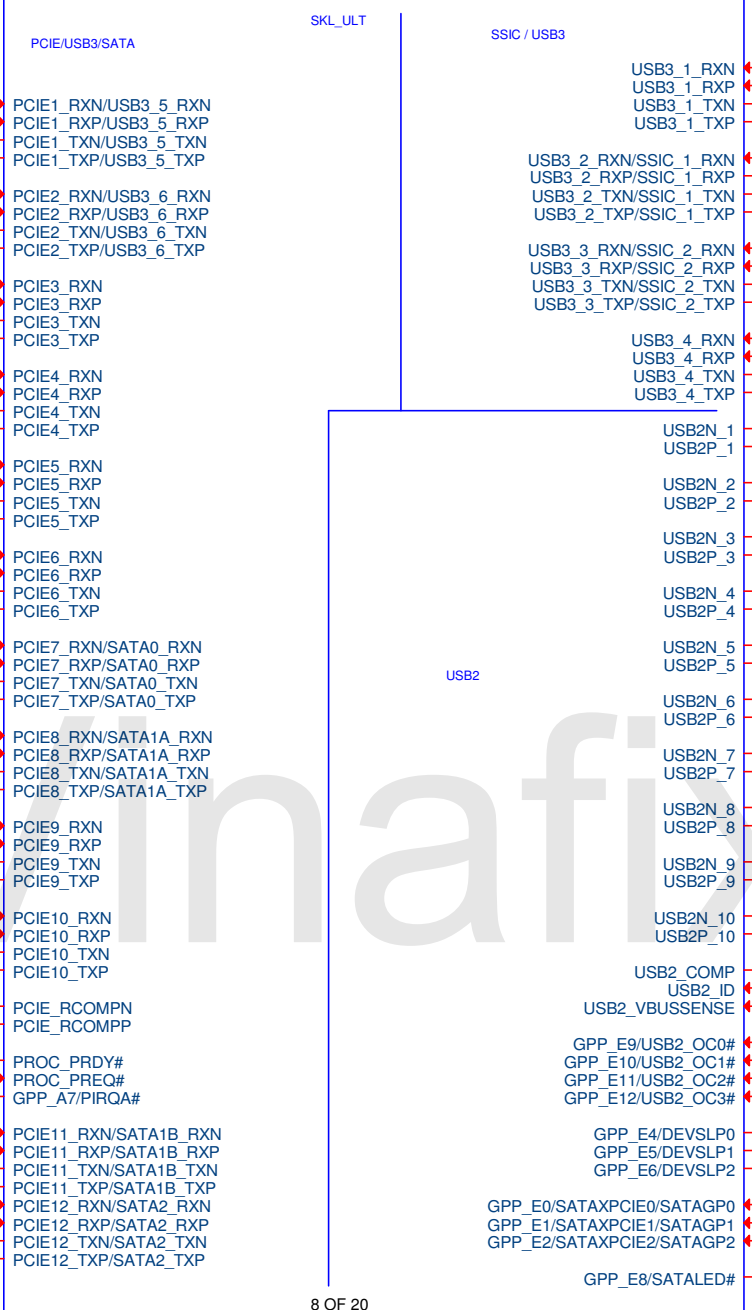
TBL2301



Title: PCH(4)_CCI, HWID		
Engineer: Surface		
Size A3	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 23 of 76	



U1001H
SKL_ULT_1356BGA_R1
bga1356_47x30_42x24x1p27mm-SKL



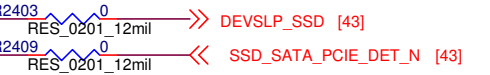
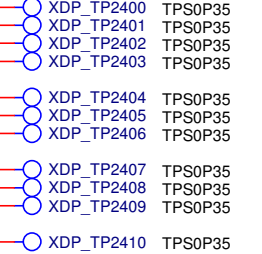
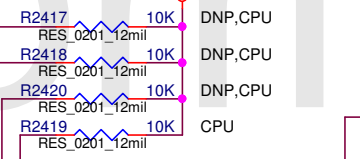
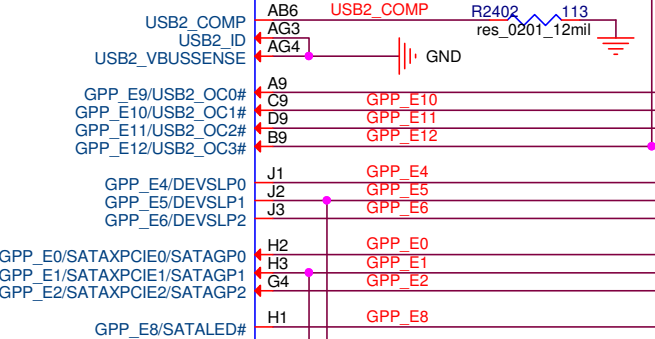
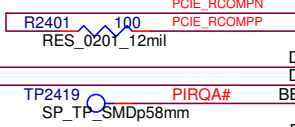
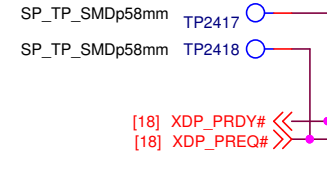
PCIE WIFI

[43] PCIE_SSD_RX7_DN
[43] PCIE_SSD_RX7_DP
[43] PCIE_SSD_TX7_DN
[43] PCIE_SSD_TX7_DP

[43] PCIE_SSD_RX8_DN
[43] PCIE_SSD_RX8_DP
[43] PCIE_SSD_TX8_DN
[43] PCIE_SSD_TX8_DP

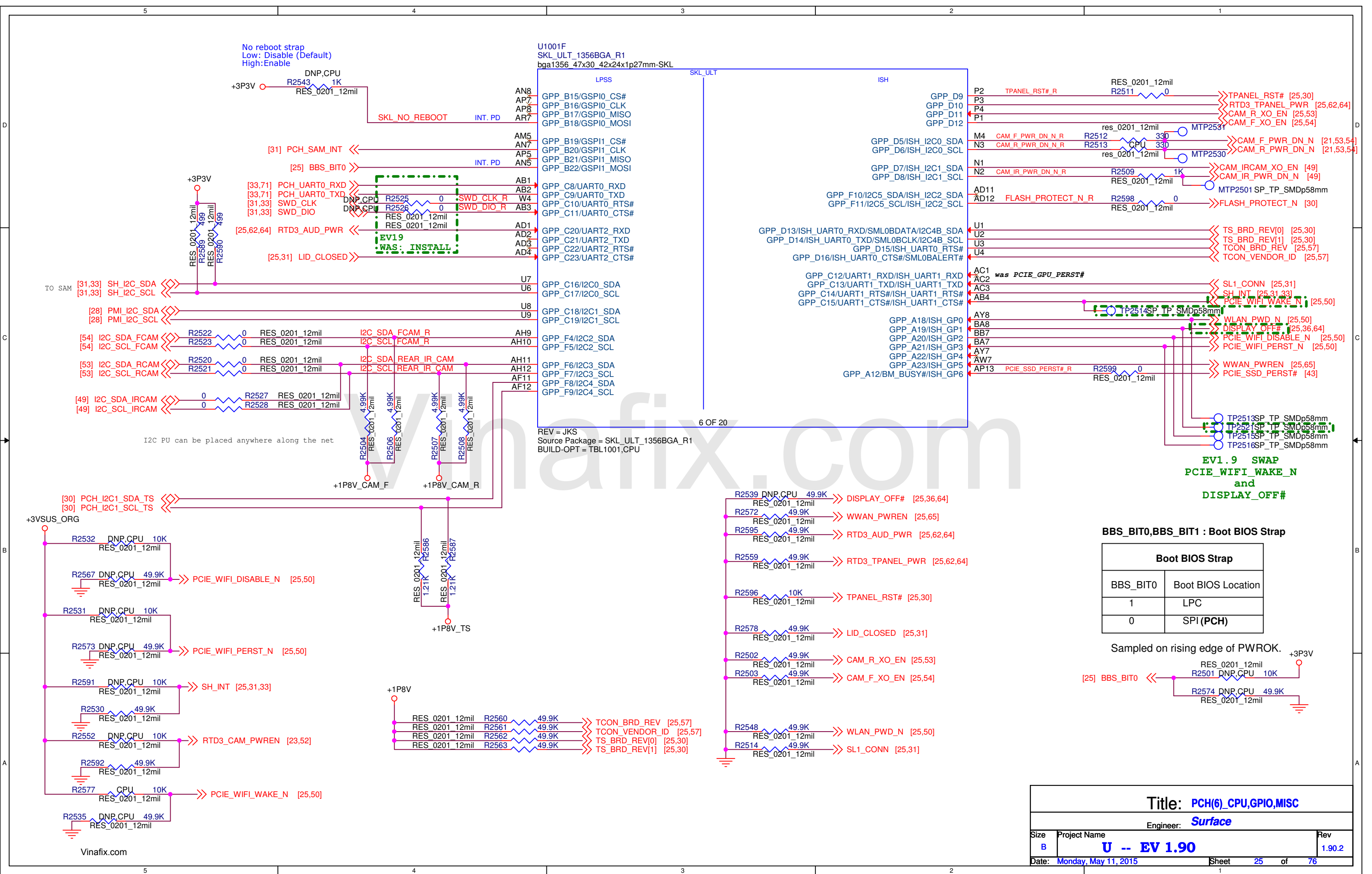
[50] PCIE_WIFI_RX9_DN
[50] PCIE_WIFI_RX9_DP
[50] PCIE_WIFI_TX9_DN
[50] PCIE_WIFI_TX9_DP

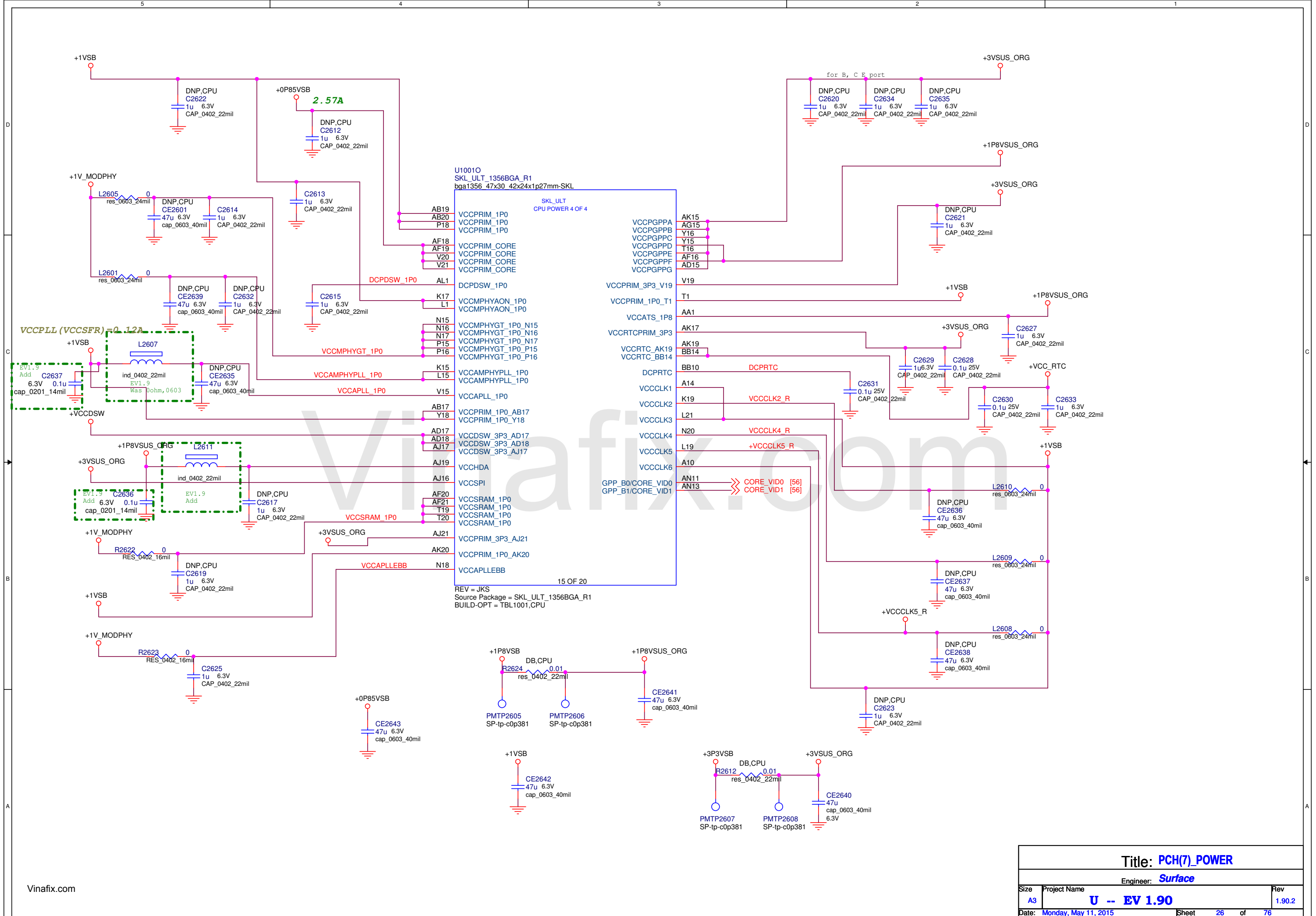
[18] XDP_PRDY#
[18] XDP_PREQ#



REV = JKS
Source Package = SKL_ULT_1356BGA_R1
BUILD-OPT = TBL1001,CPU

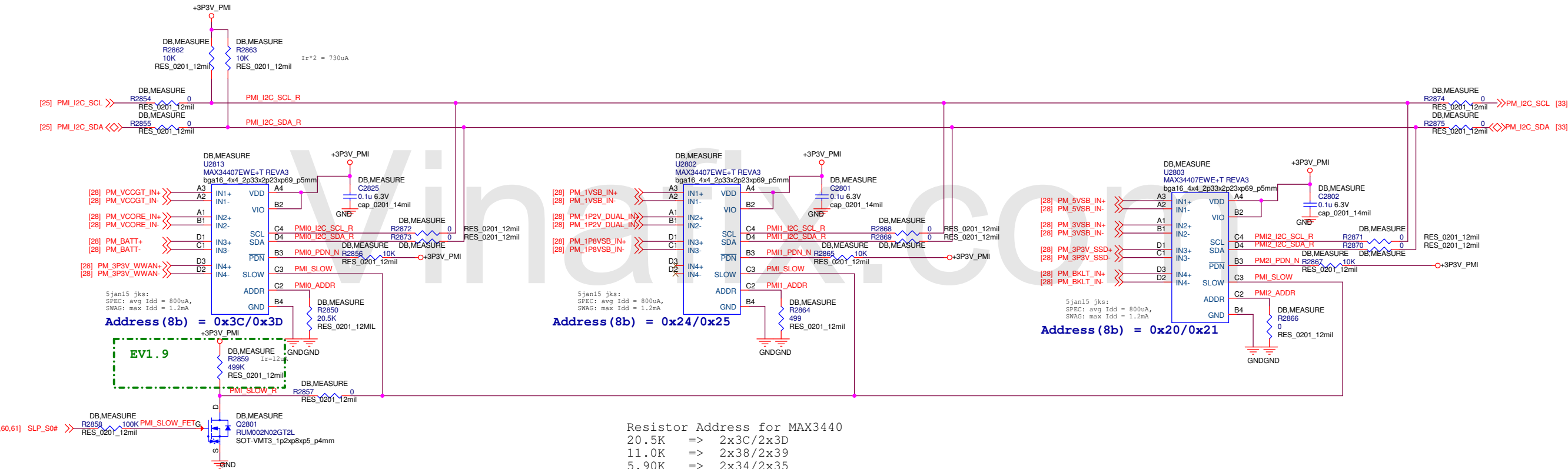
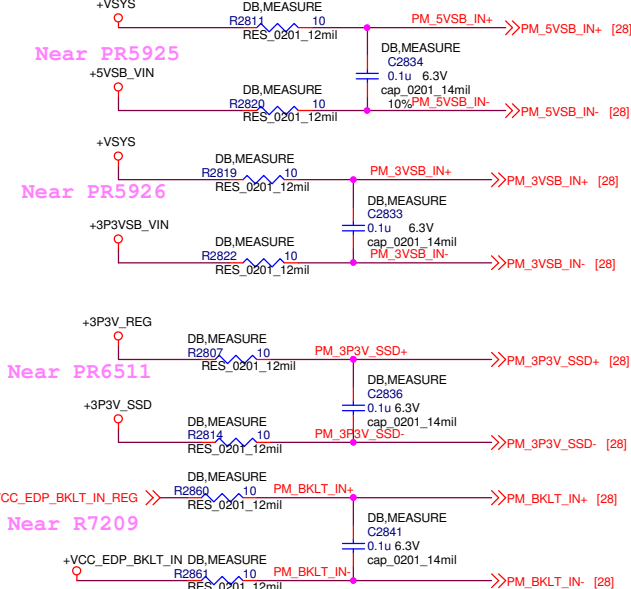
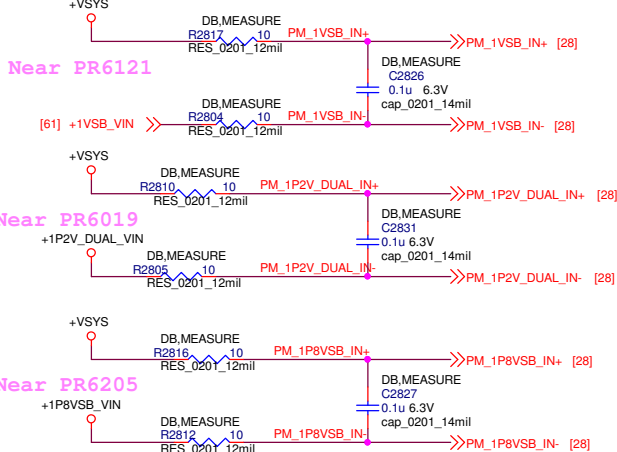
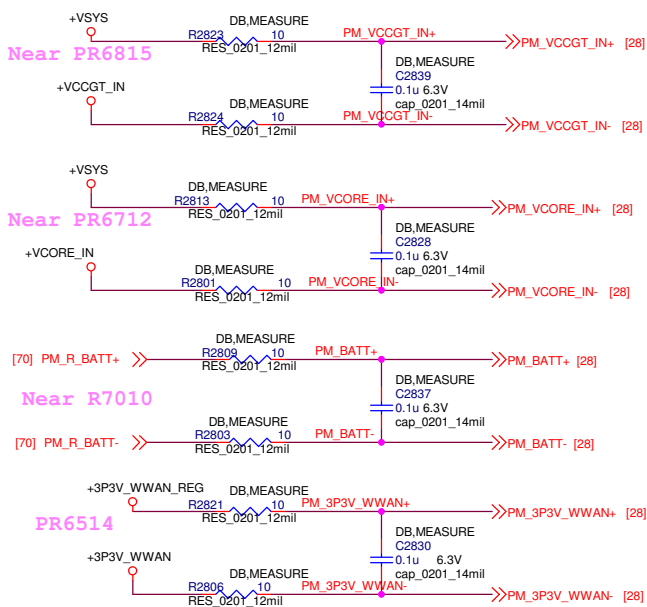
8 OF 20







Title: PCH(8)_empty		
Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 27	of 76

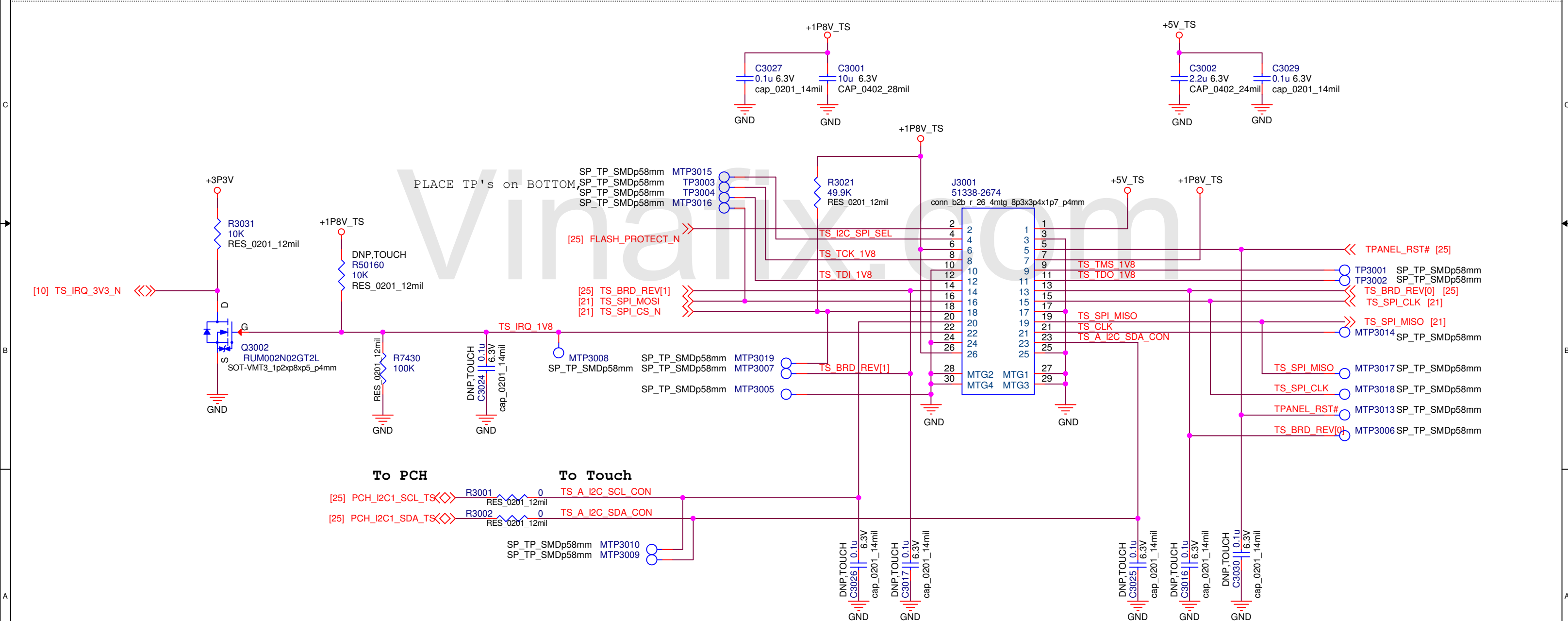
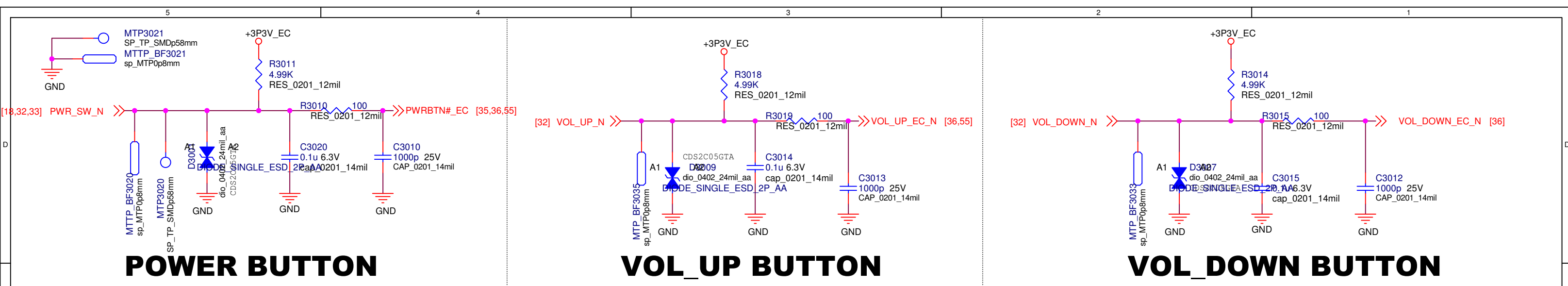


Resistor Address for MAX3440

20.5K	=>	2x3C/2x3D
11.0K	=>	2x38/2x39
5.90K	=>	2x34/2x35
3.16K	=>	2x30/2x31
1.74K	=>	2x2C/2x2D
931K	=>	2x28/2x29
499	=>	2x24/2x25
GND	=>	2x20/2x21



Title: EMPTY		
Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 29 of 76	

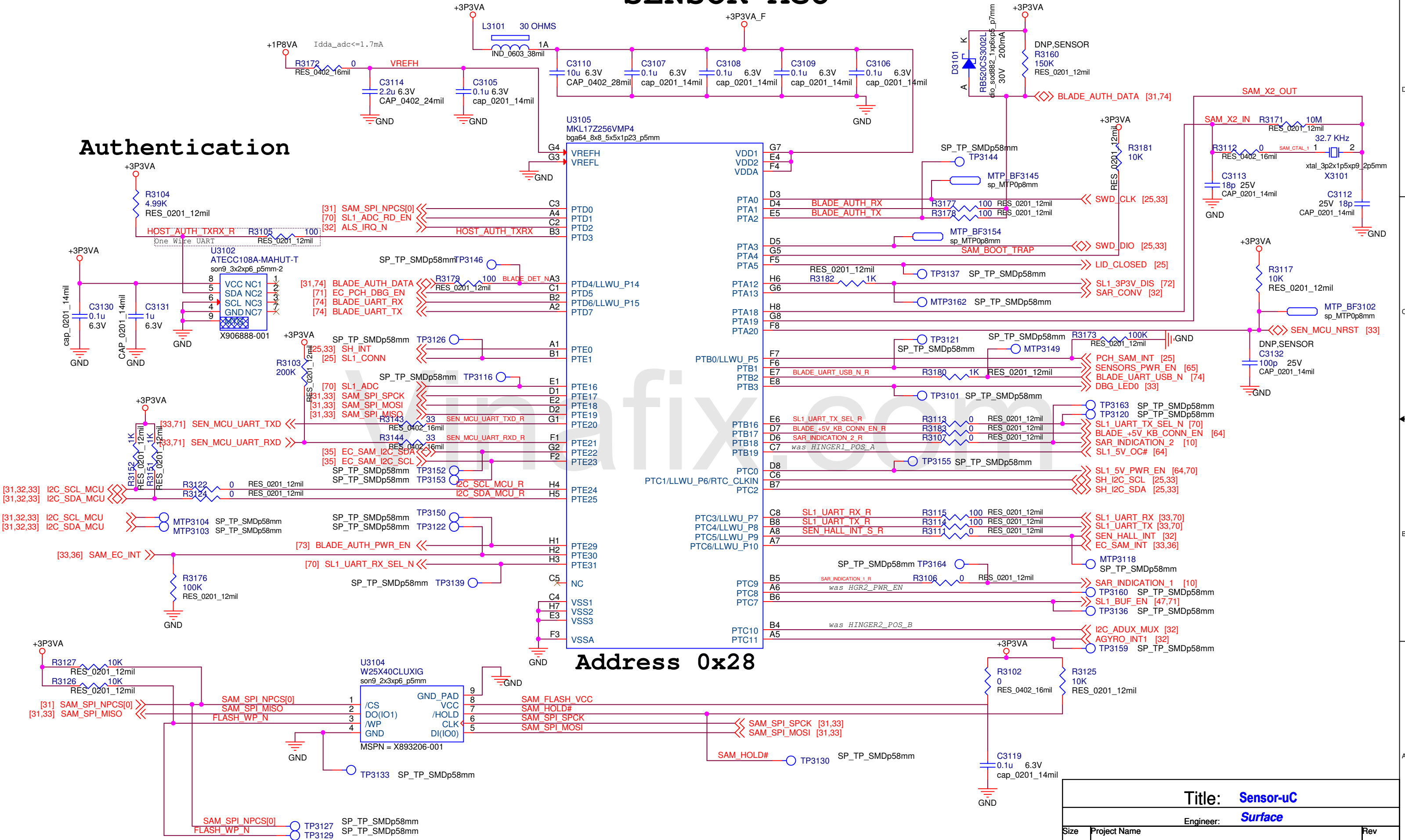


Title: Touch Con & Key		
Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 30	of 76

SENSOR MCU

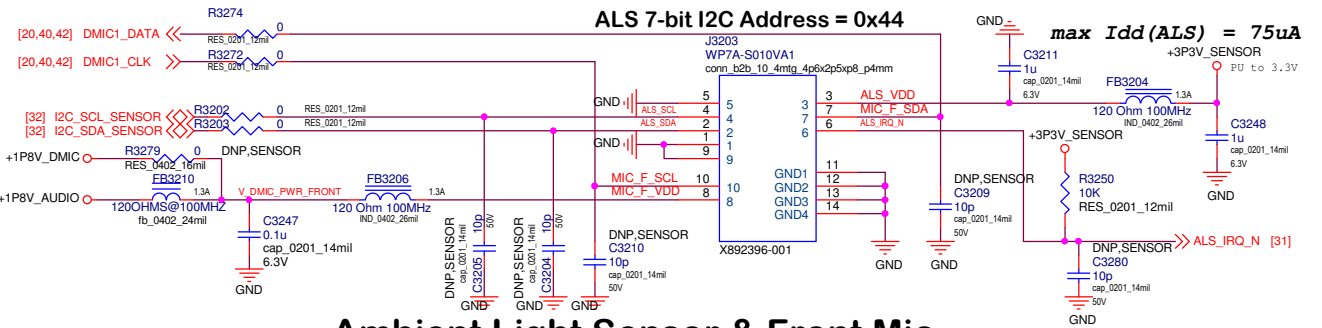
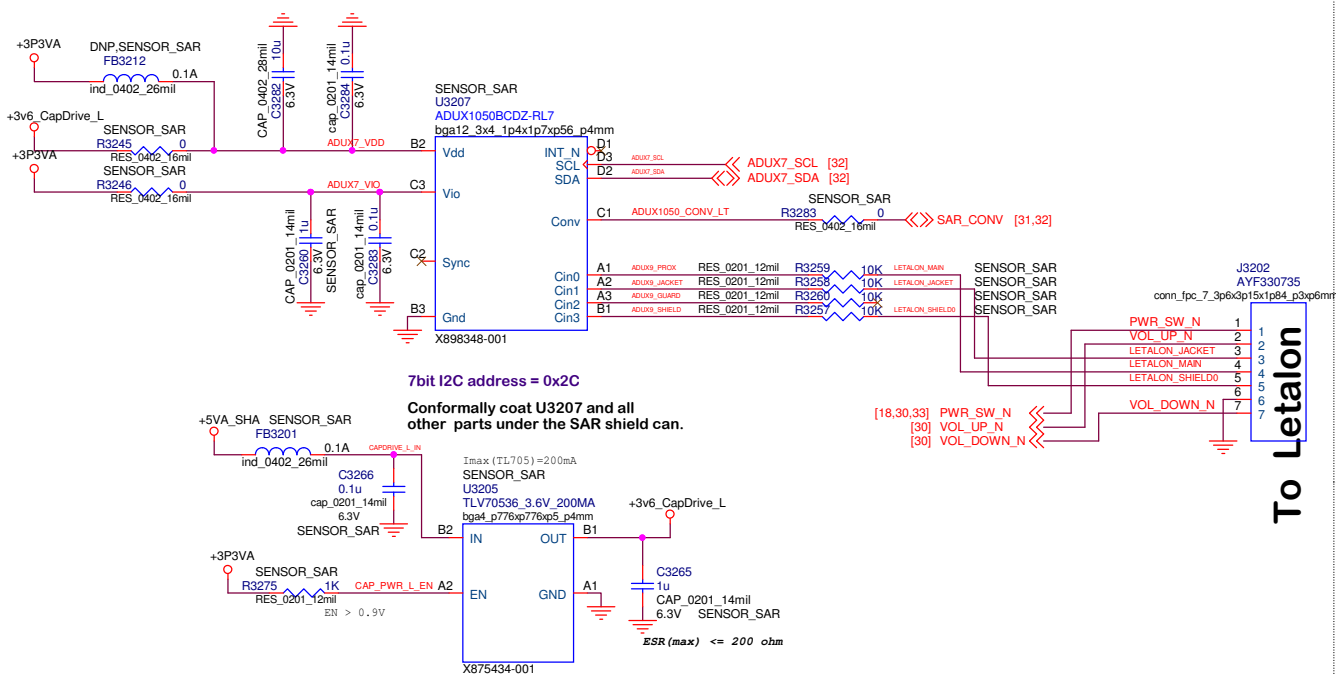
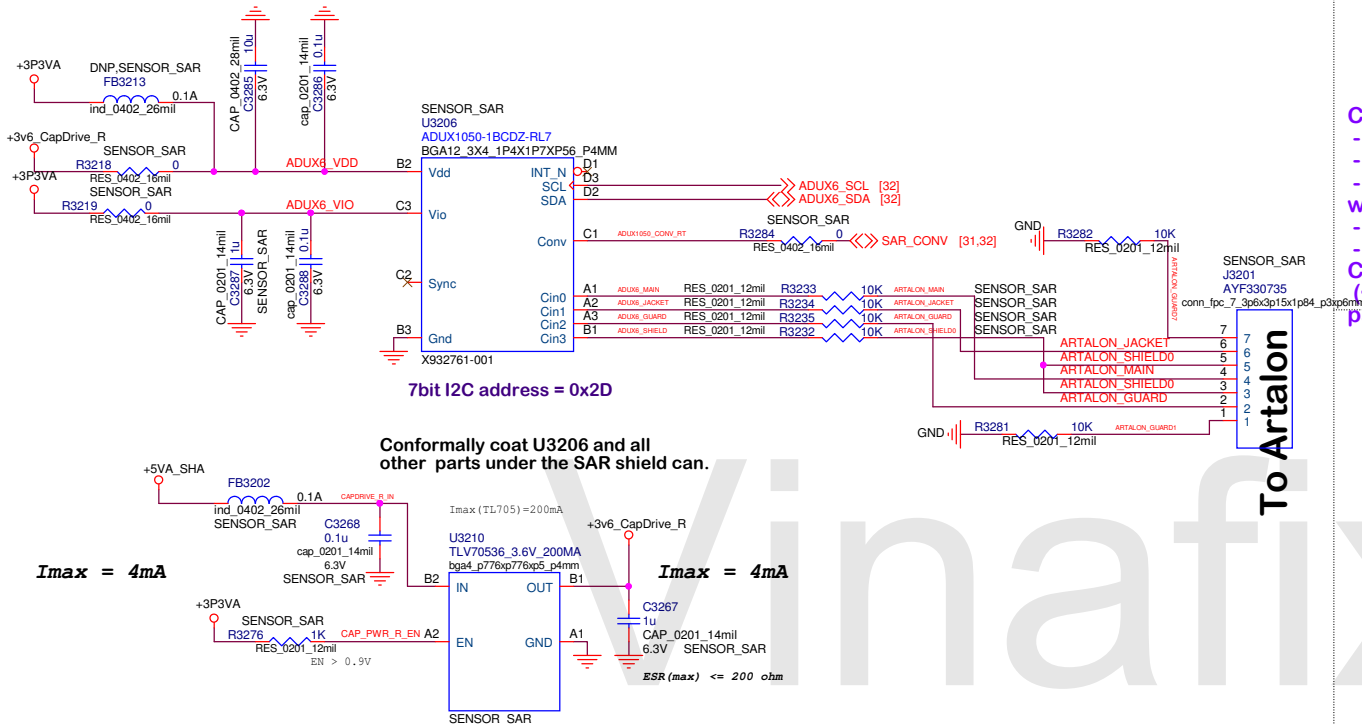
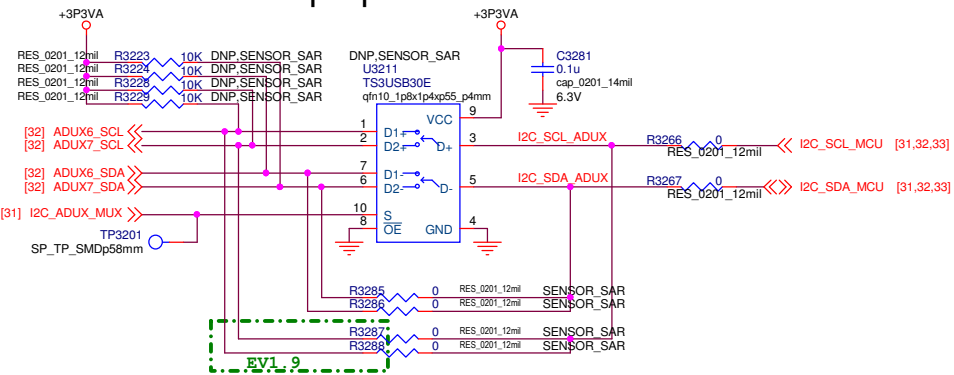
Authentication

Address 0x28

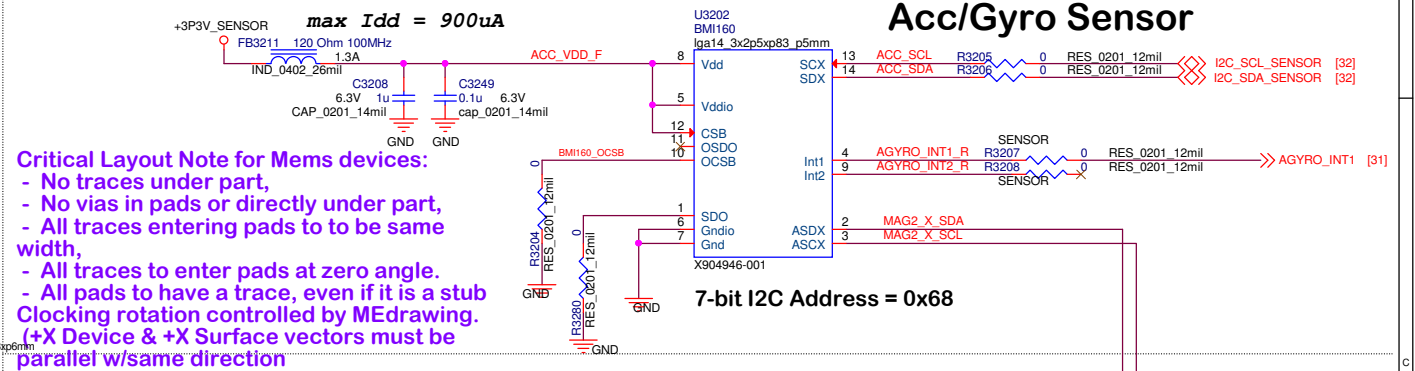


Title: Sensor-uC		
Engineer: Surface		
Size B	Project Name	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 31 of 76	

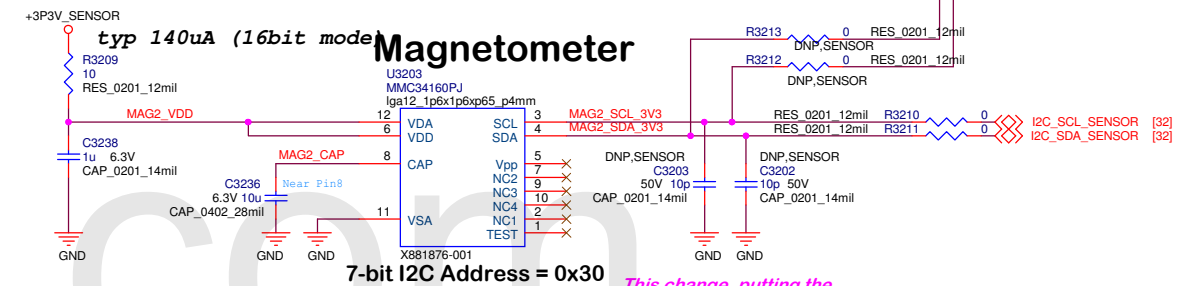
WiFi envelope protection drivers



Ambient Light Sensor & Front Mic



Acc/Gyro Sensor

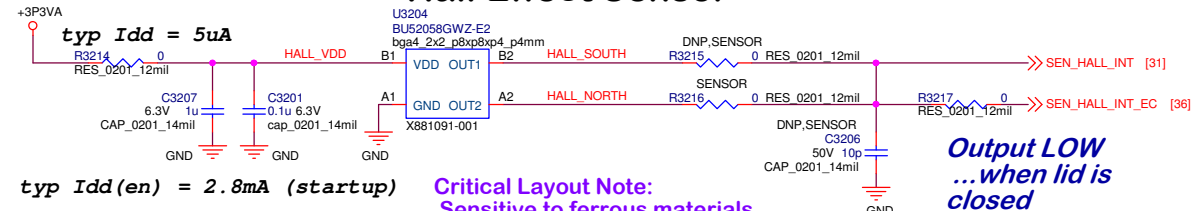


Magnetometer

Critical Layout Note:
Extremely sensitive to ferrous materials:
Local ferrite bead to be >8mm remote
No traces carrying >8mA within 10mm
... on any layer.
Clocking rotation controlled by
MEDrawing.

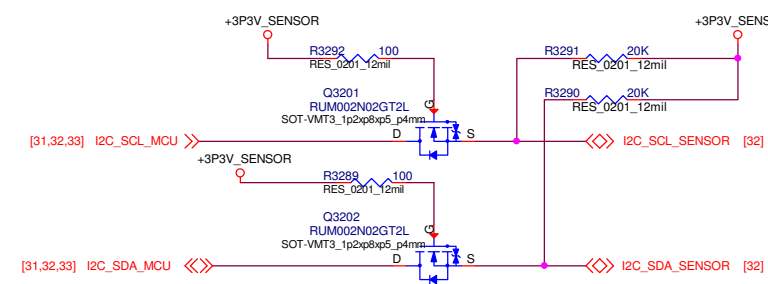
This change, putting the MAG behind the AGyro allows us to take advantage of the time-stamped FIFO in the AGyro to reduce power consumption and address load on the I2C bus -- in addition to improving jitter filtering in post processing. Eventually this will enable IR range camera frame syncing.

Hall Effect Sensor

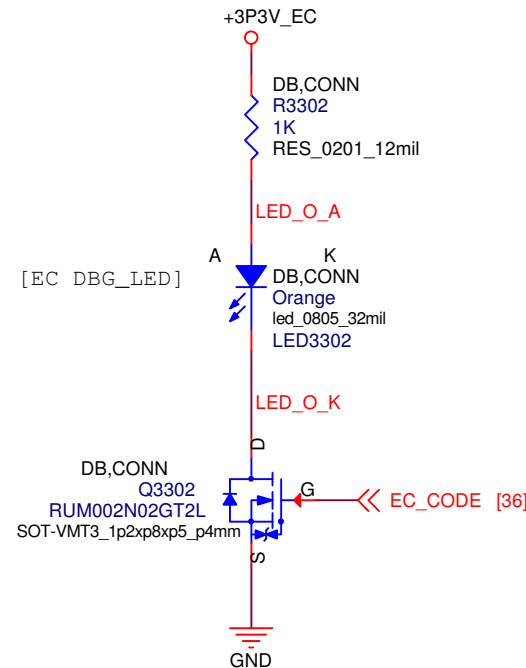
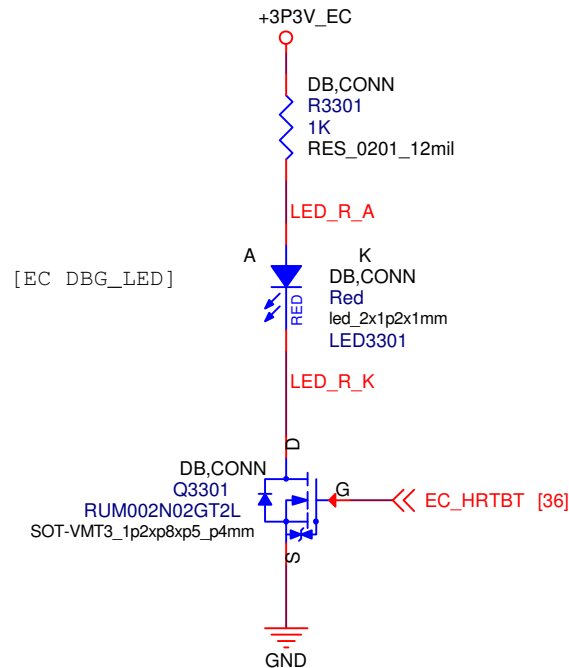
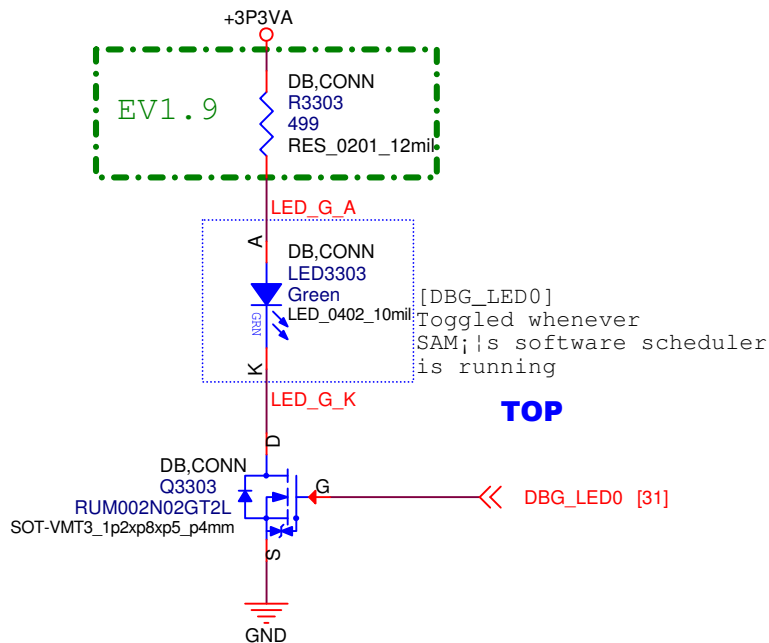
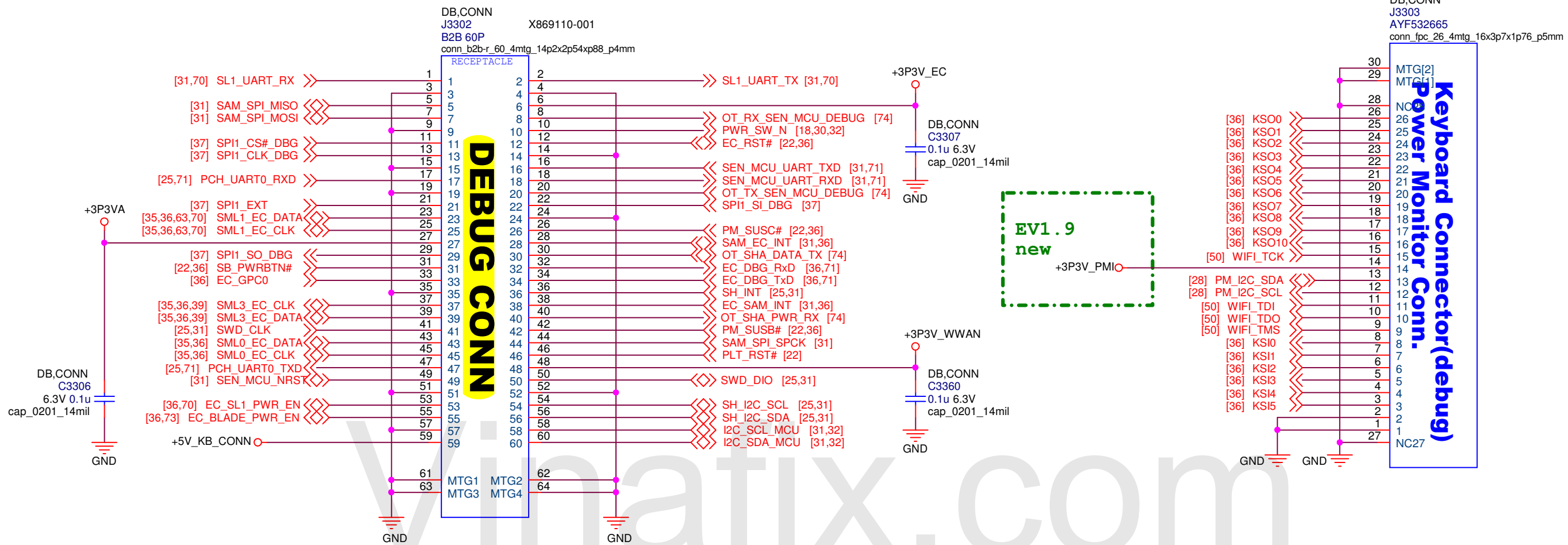


*Output LOW
...when lid is
closed*

Critical Layout Note:
Sensitive to ferrous materials
Do not mount under a steel shield can
If mounted on Glass side of board,
Trigger may occur
as early as 30Gauss North B-field
or as late as 50Gauss North B-field
Be careful not to mount within 15mm
of speaker autofocus camera or other
magnet.
X-Y location controlled by MEdrawing.



Title: On Board-Sensors			
Engineer: Surface			
Size C	Project Name U -- EV 1.90	Rev 1.90.2	
Date: Monday, May 11, 2015	Sheet 32	of	76



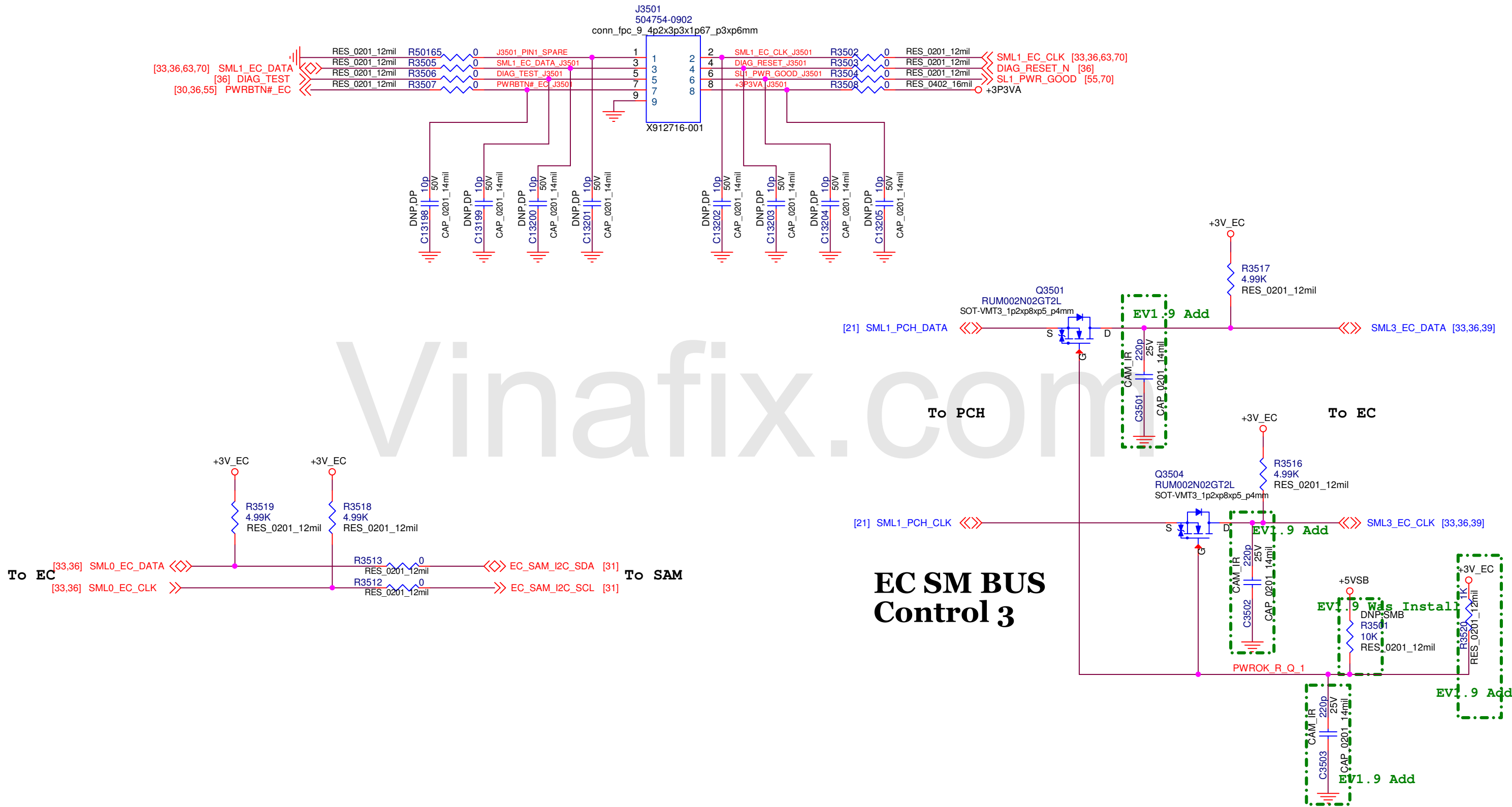
Vinafix.com

<Core Design>

Title: Debug Conn / LPC		
Microsoft		Engineer: Surface
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 33	of 76

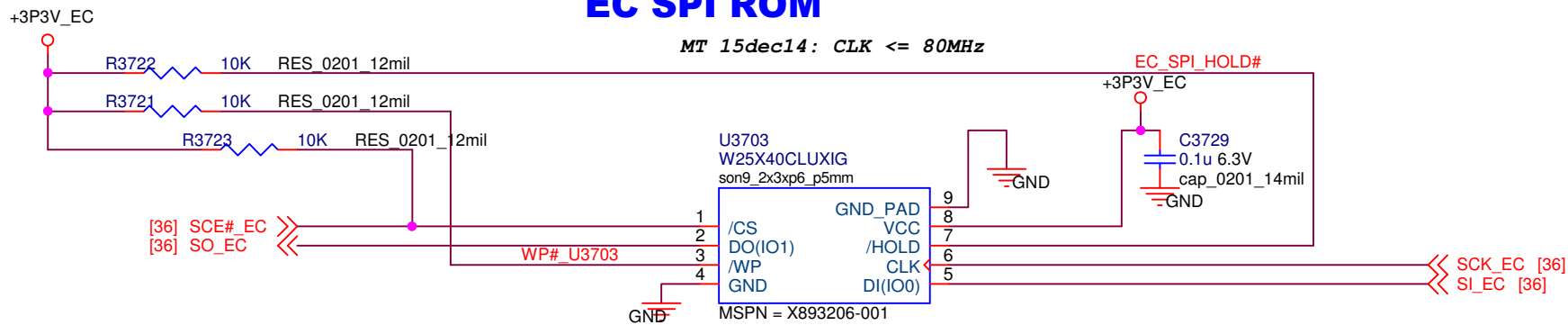
Title: Empty		
Microsoft		Engineer: Surface
Size	Project Name	Rev
A	U -- EV 1.90	1.90.2
Date: Monday, May 11, 2015	Sheet 34 of 76	

DIAGNOSTIC CONNECTOR



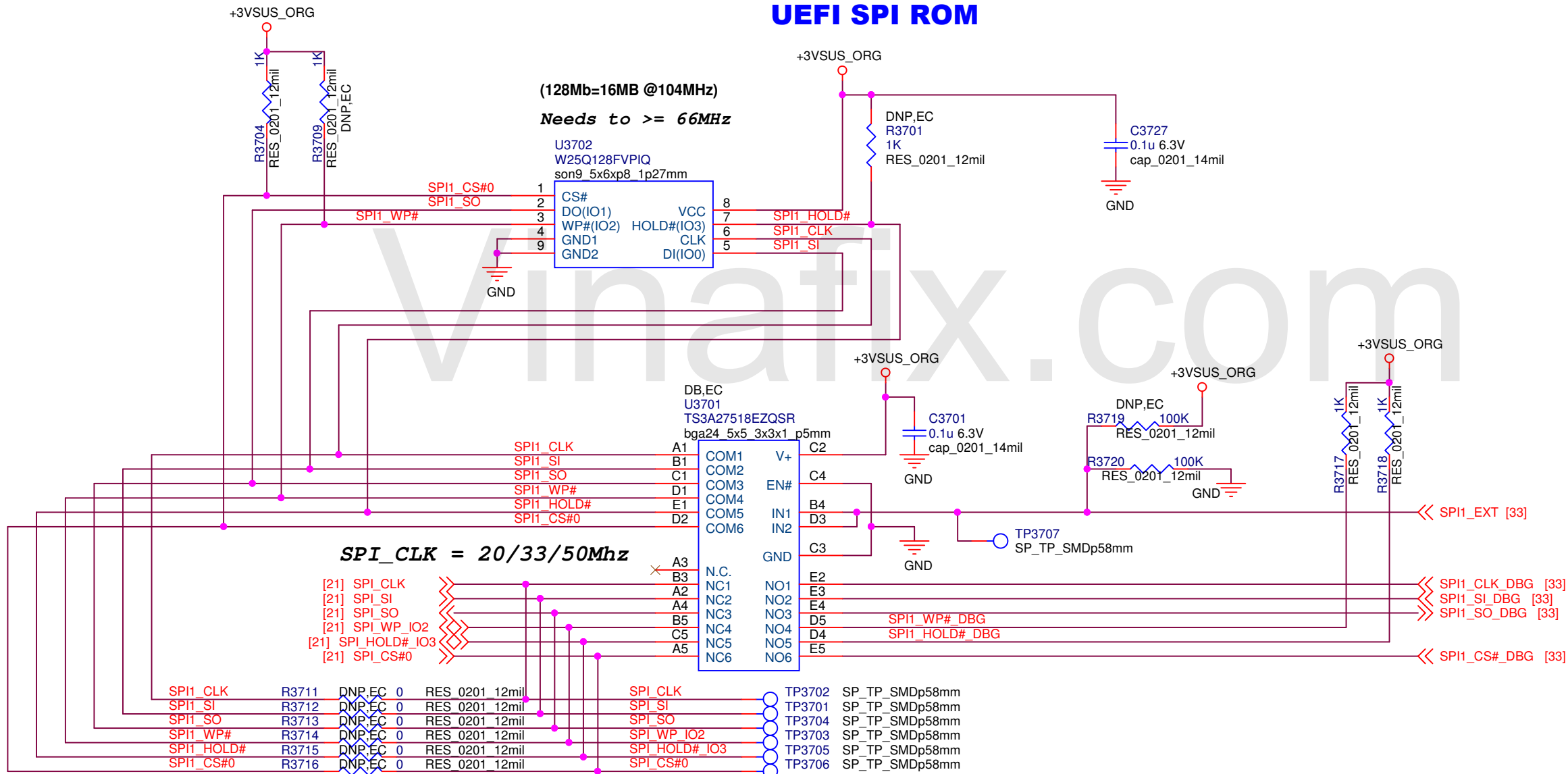
EC SPI ROM

MT 15dec14: CLK <= 80MHz



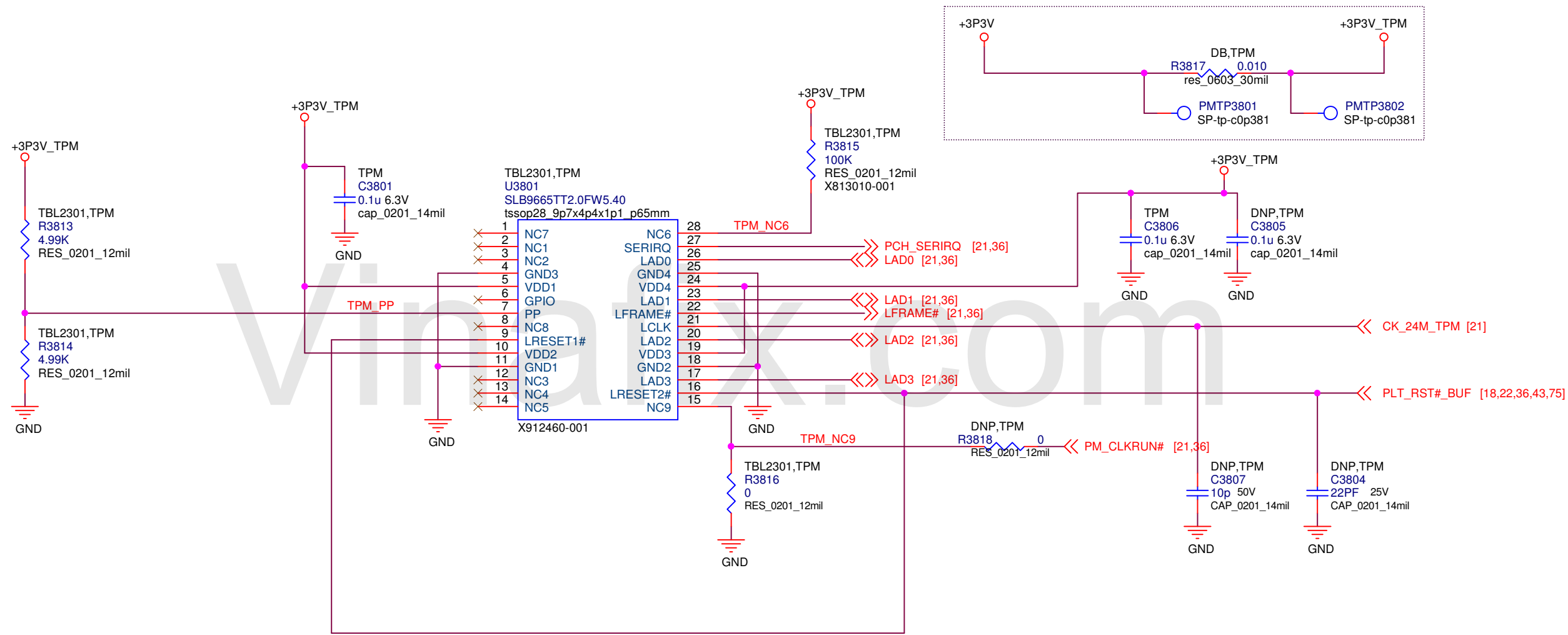
UEFI SPI ROM

(128Mb=16MB @104MHz)
Needs to >= 66MHz



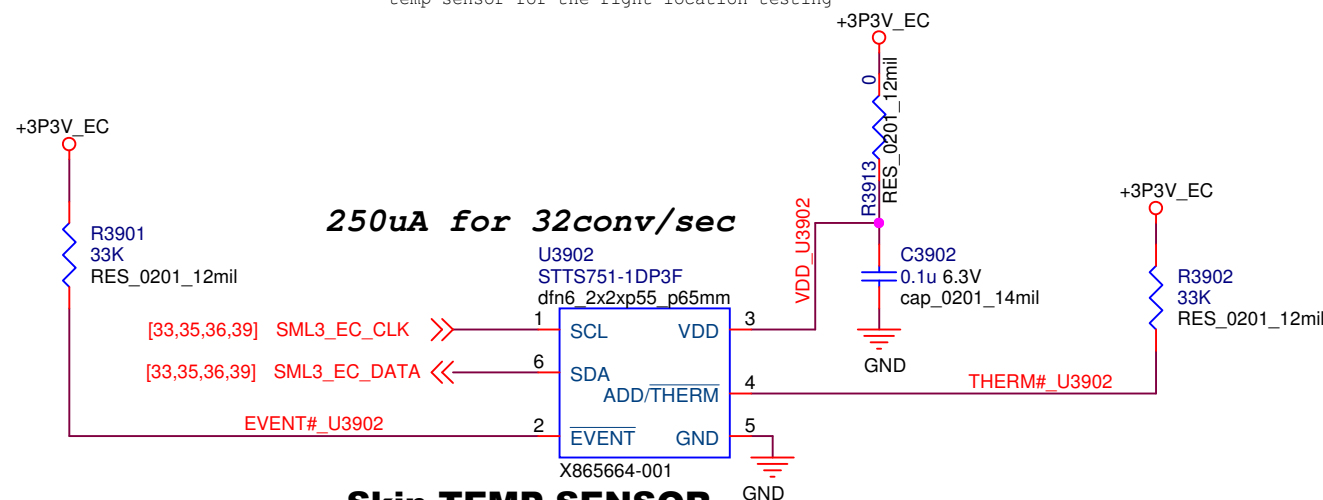
IN1/IN2 = L => COM to NC
IN1/IN2 = H => NC to COM

Trusted Platform Module



jks 6dec14: Only one sensor will be used for final product

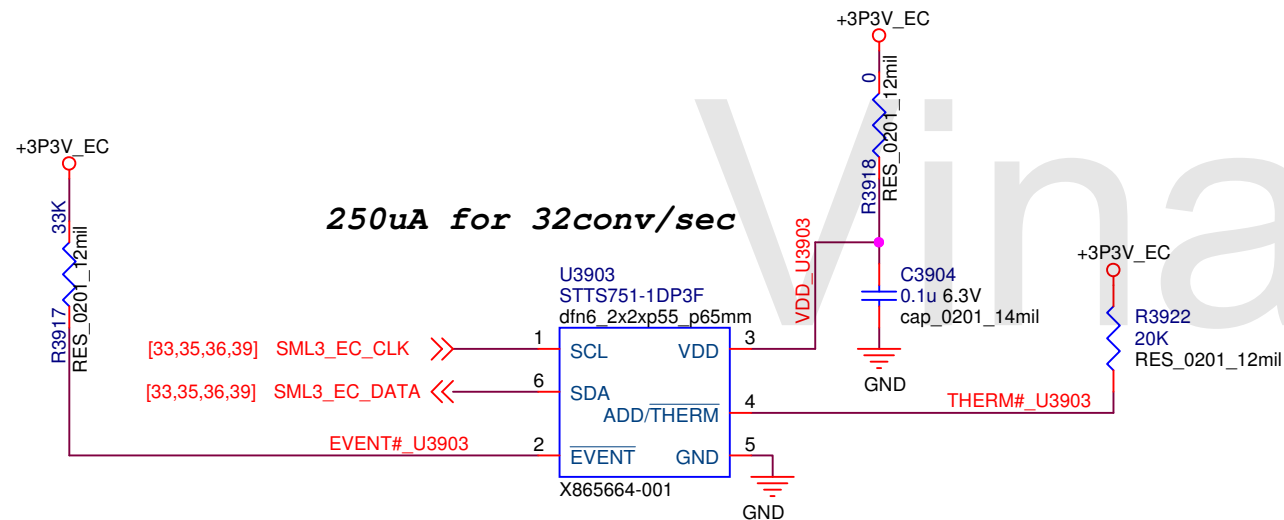
temp sensor for the right location testing



250uA for 32conv/sec

Skin TEMP SENSOR

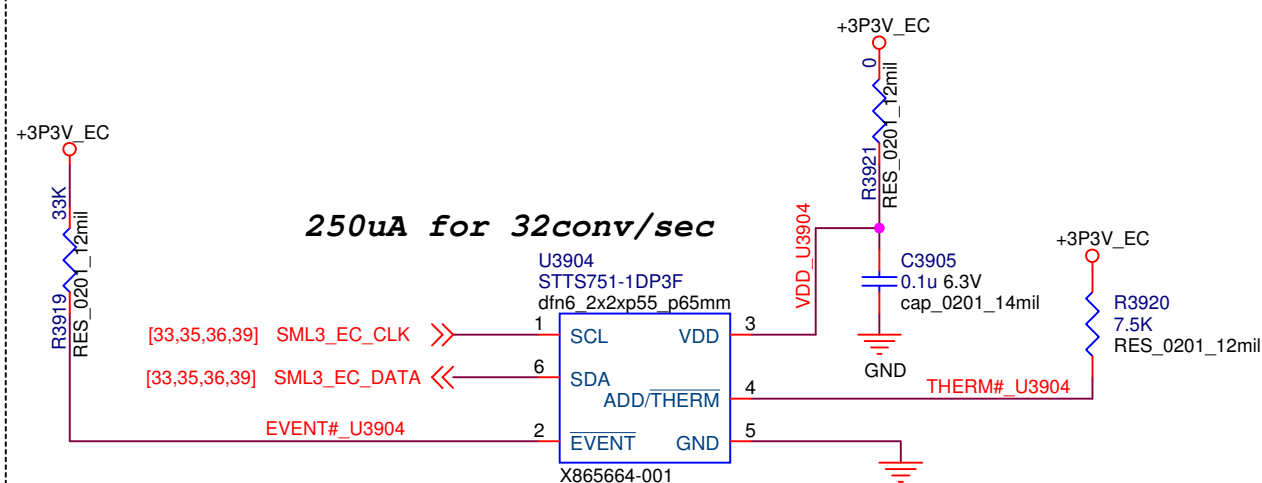
7-bit I2C Address = 0x3B



250uA for 32conv/sec

Skin TEMP SENSOR

7-bit I2C Address = 0x3A

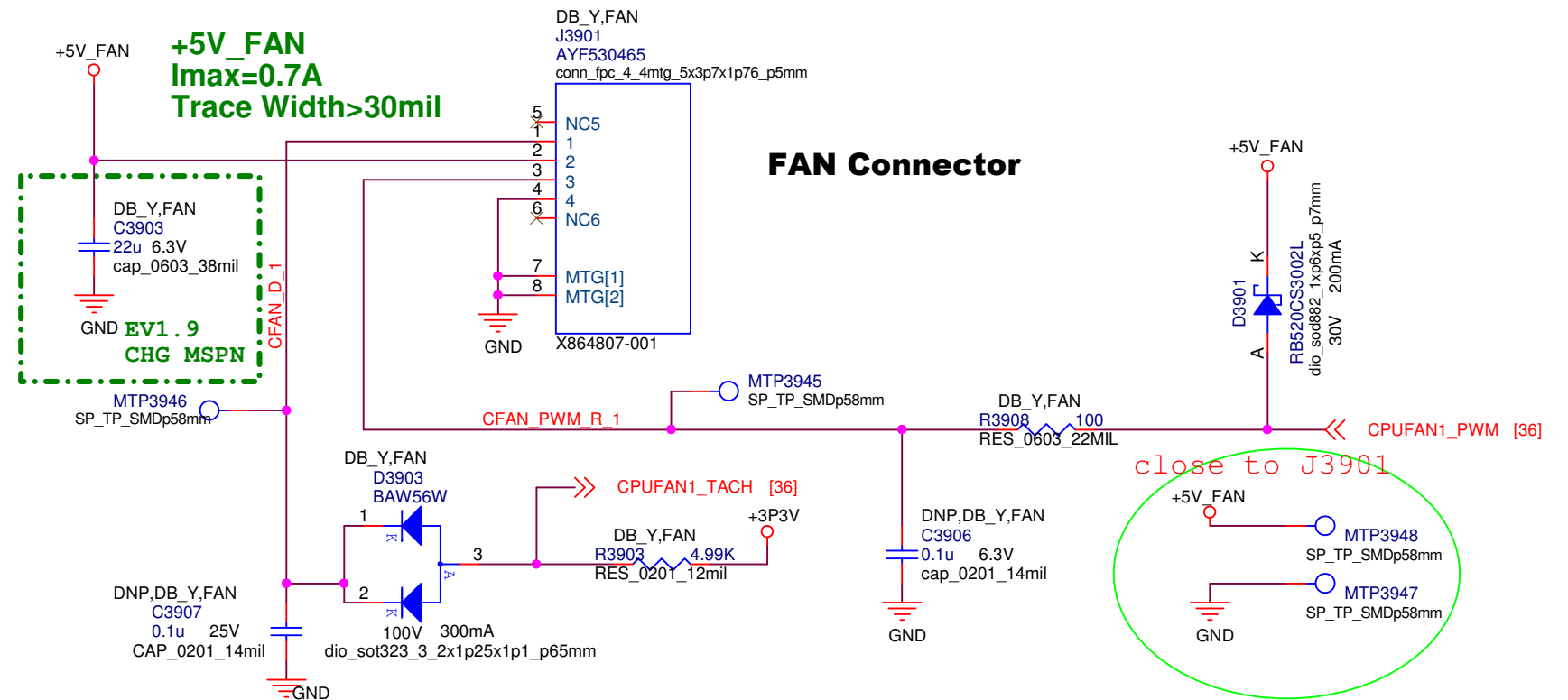


250uA for 32conv/sec

Skin TEMP SENSOR

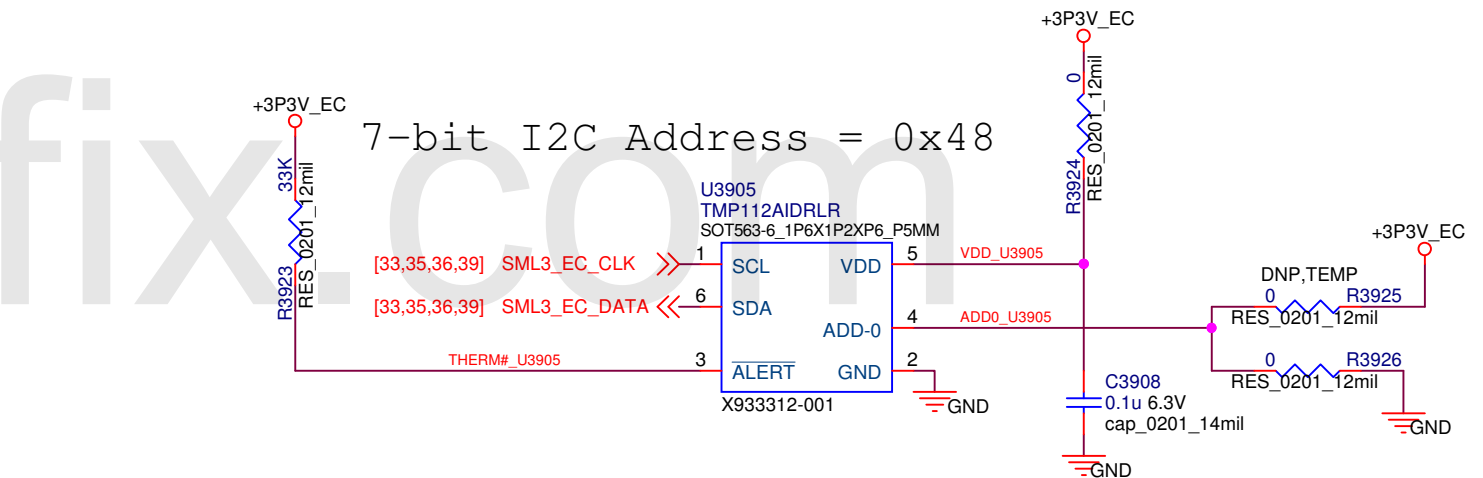
7-bit I2C Address = 0x 4A

Vinafix.com



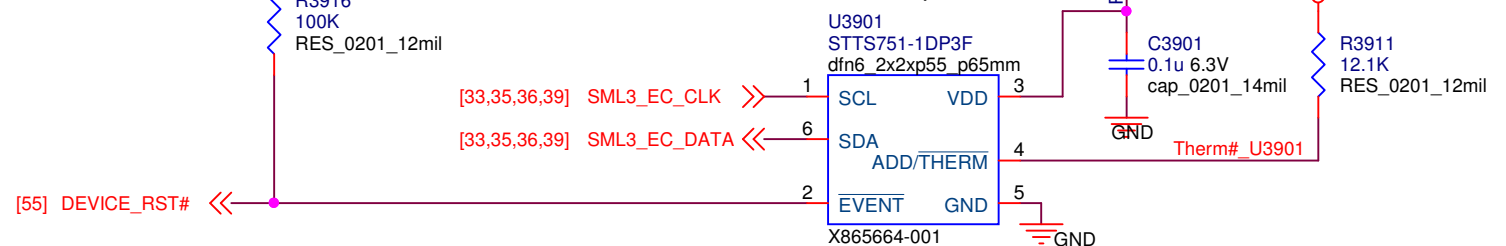
FAN Connector

7-bit I2C Address = 0x48



+3P3VAS

250uA for 32conv/sec



Surrnd TEMP SENSOR

7-bit I2C Address = 0x4B

Title: Temp Sensor/System Fan

Microsoft

Engineer: Surface

Size

Project Name

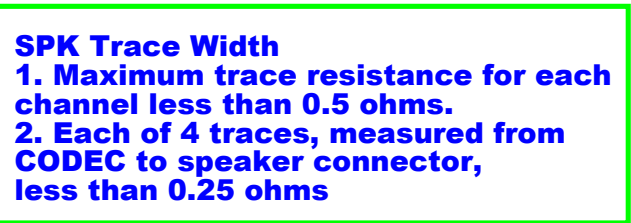
U -- EV 1.90

Rev

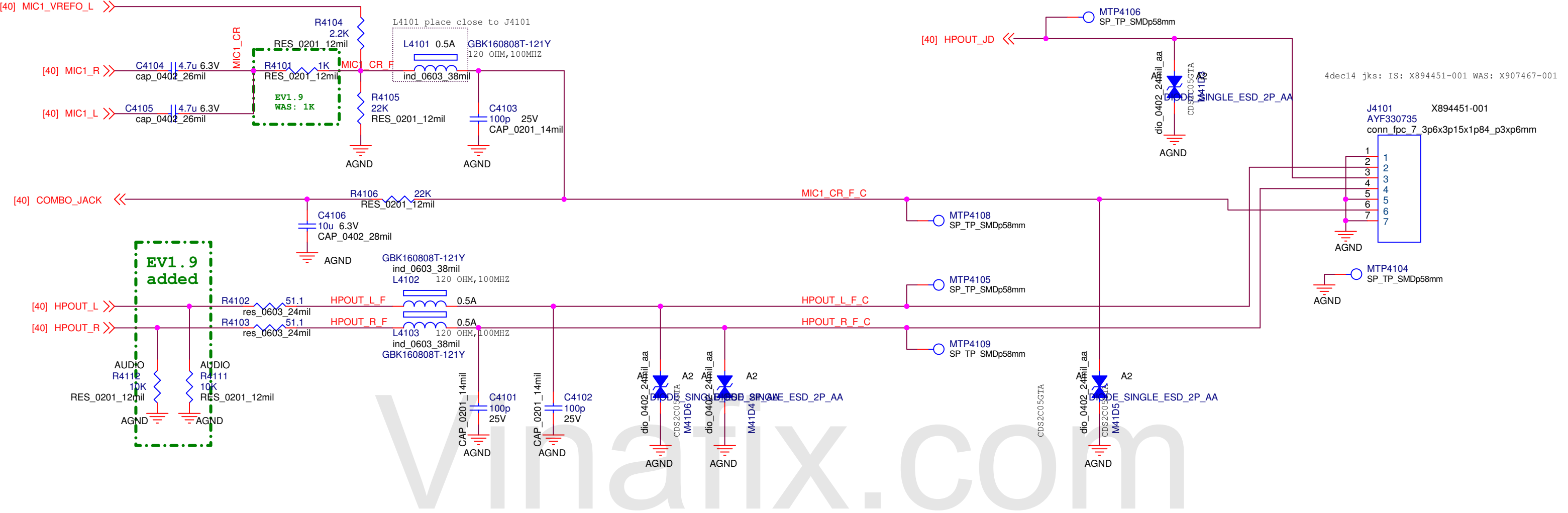
1.90.2

Date: Monday, May 11, 2015

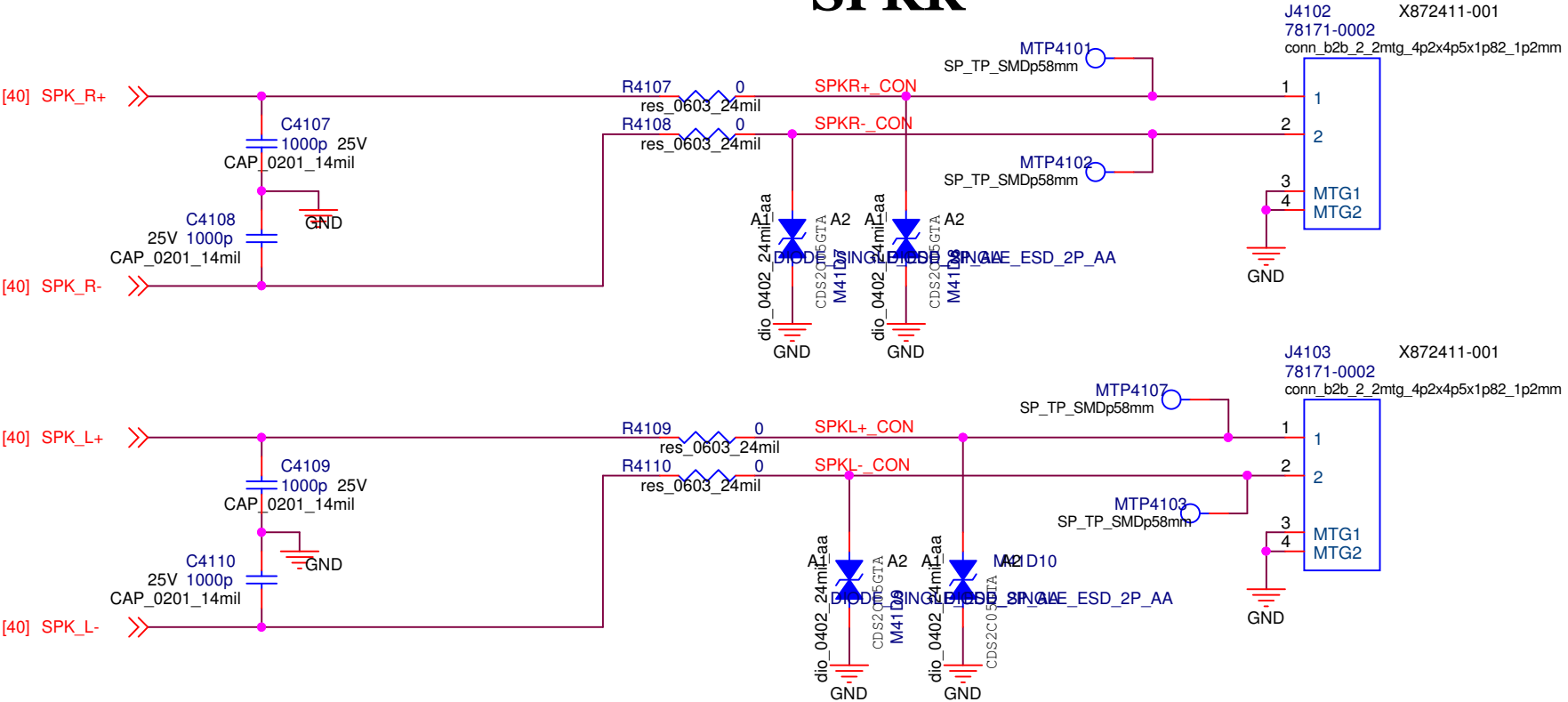
Sheet 39 of 76



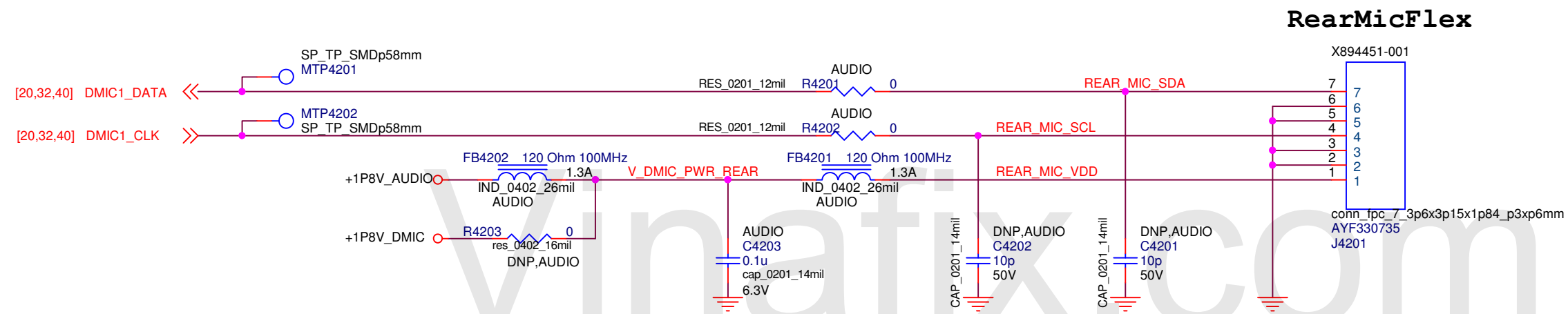
Audio Jack/MIC1 Combo Jack



SPKR



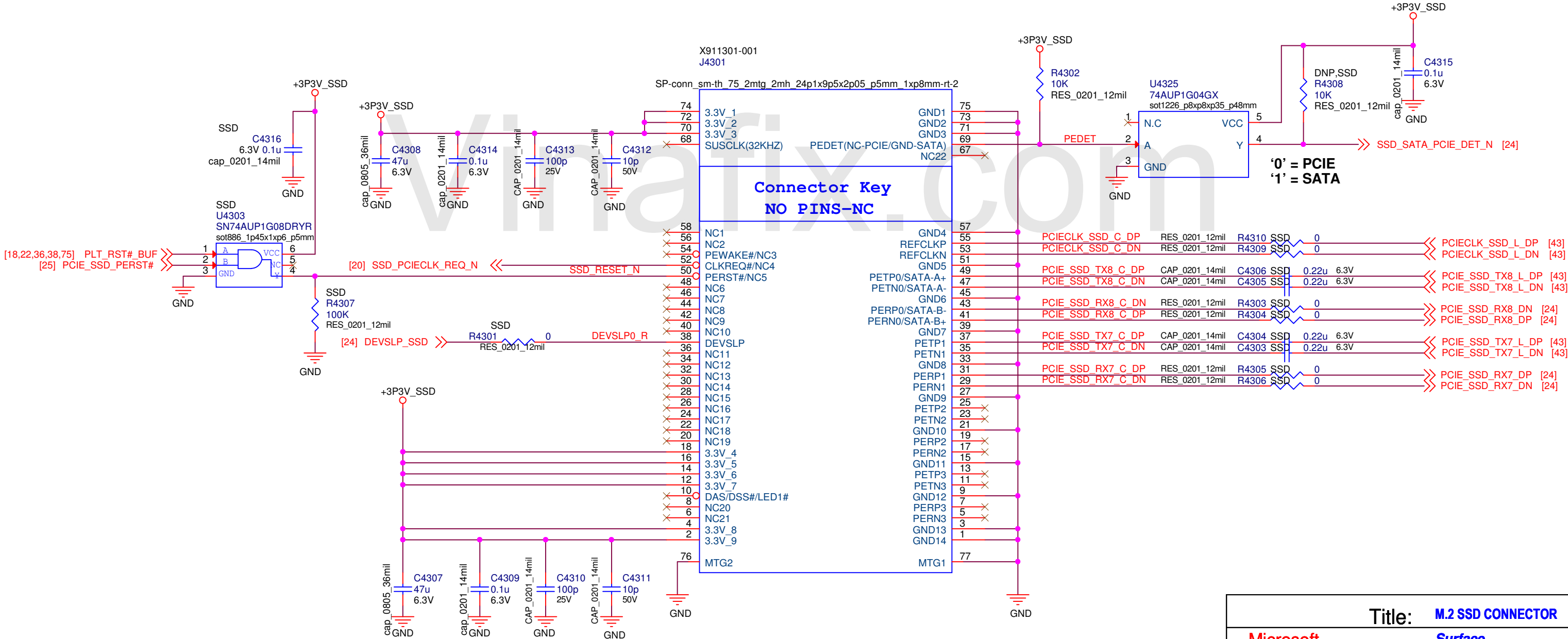
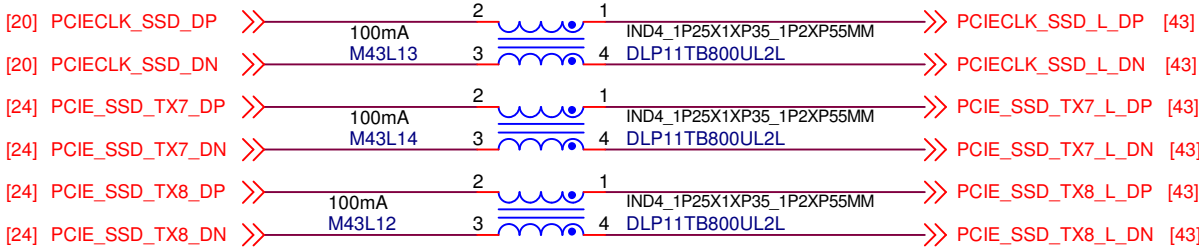
Title: Audio Jack/Speaker		
Microsoft Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 41	of 76



Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen2/SATA	PCI Express* Gen3/SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ²	None	None ³

2. Design Constraint: For SATA only application, both Tx and Rx channels need to have 10 nF capacitors on the motherboard. This option supports all SATA devices. However, the 10 nF capacitor on Rx can be removed if DC coupled ODDs / devices are NOT used.

3. Design Constraint: For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. This option DOES NOT support DC coupled ODDs / Devices.





Title: Empty		
Microsoft	Engineer: Surface	
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 44 of 76	1

[24] USB3_CONN_RX_DN <<
[24] USB3_CONN_RX_DP <<

[24] USB3_CONN_TX_DN >> C4513 0.1u 6.3V
[24] USB3_CONN_TX_DP >> C4512 0.1u 6.3V

[24] USB2_CONN_DP <<<
[24] USB2_CONN_DN <<<

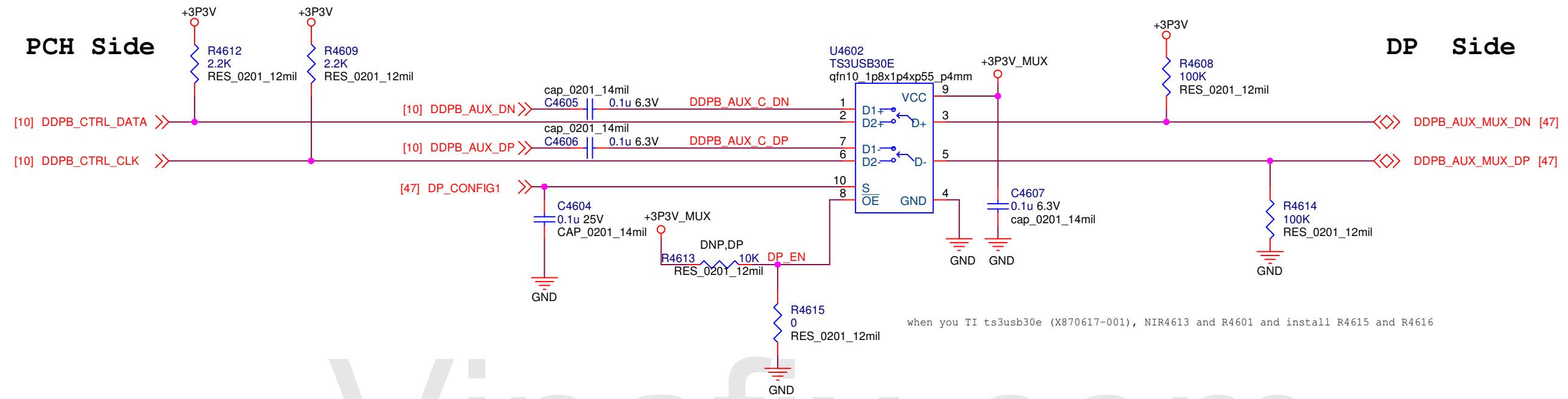
1.5 => ILIM(11.8K) => 2 A
I_{max} = 2.1 A

[24] USB_CONN_OC# <<<
[36,60,61,62] SUSC_EC# <<<

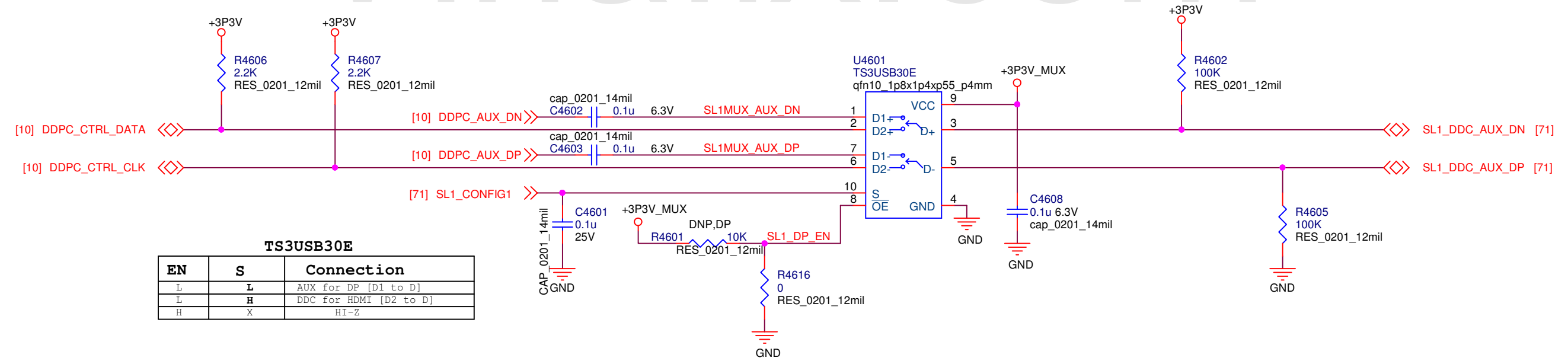
jks 6dec14: chg from ceramic
to tant for space saving

+5V_USB_PWR
I_{min} = 1.5A (ng 19dec14)
I_{max} = 1.9A

mDP mux to HDMI/DVI Dongle control



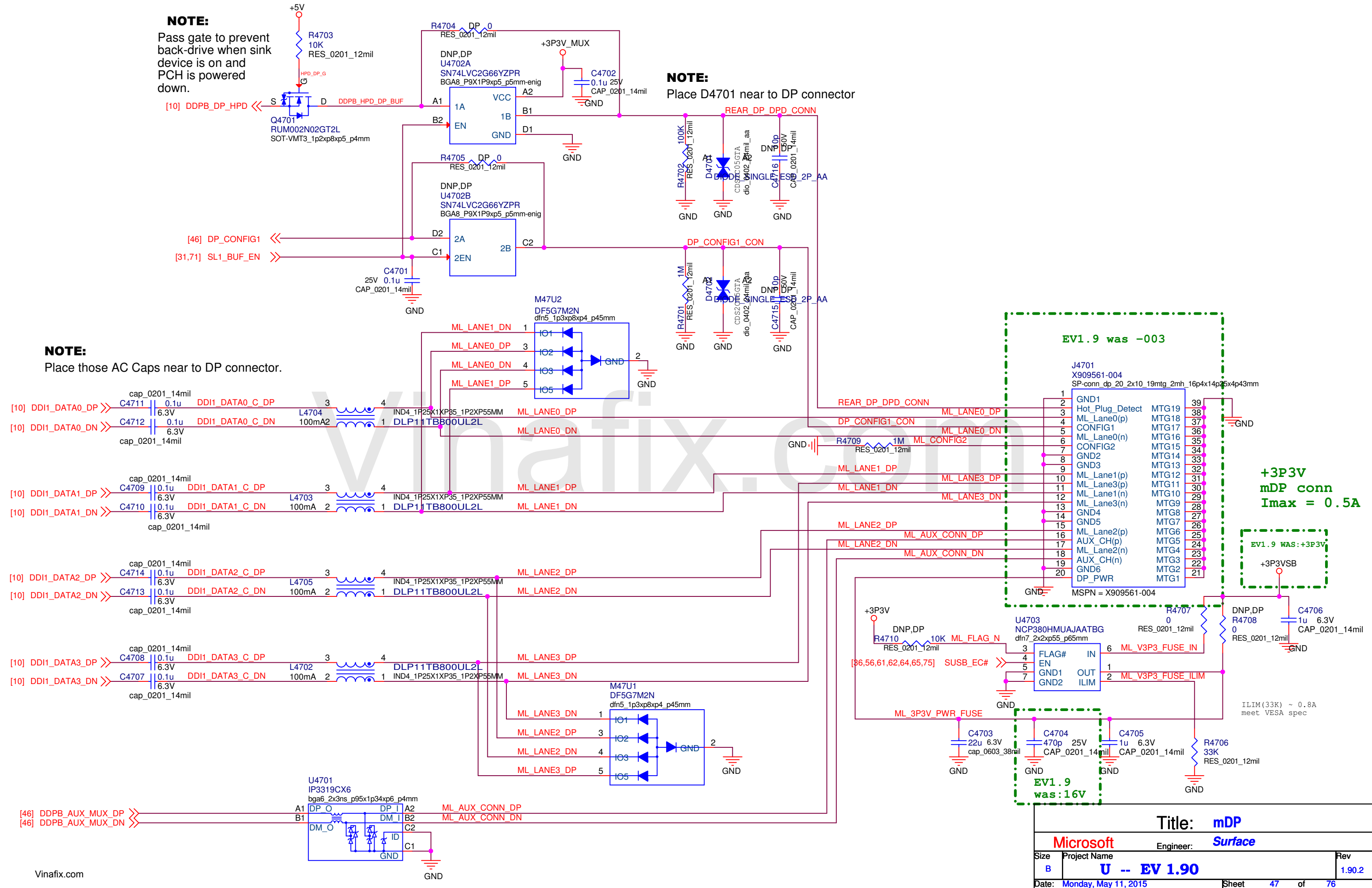
SL1 DP mux to HDMI/DVI Dongle control



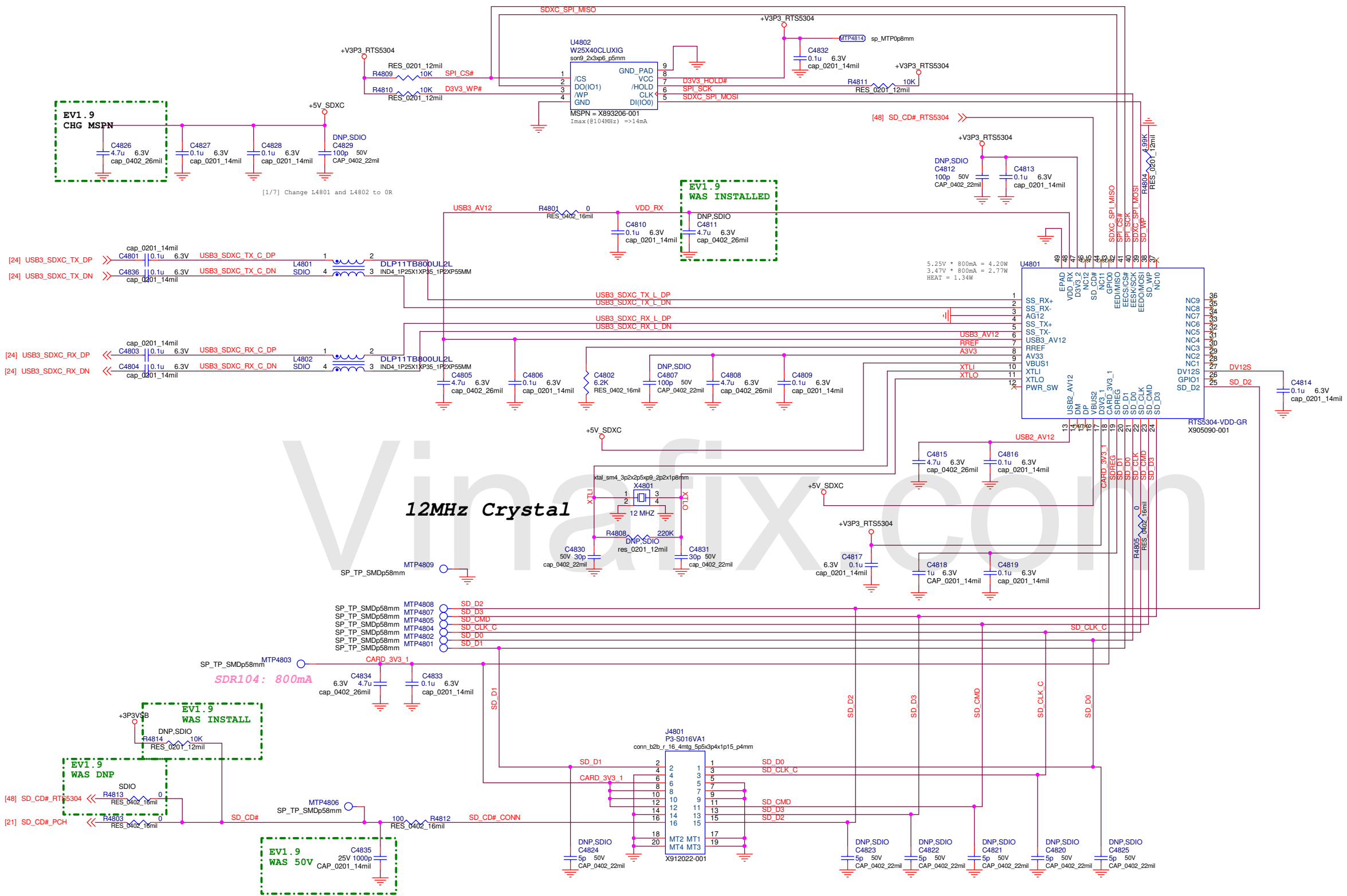
NOTE:
Pass gate to prevent back-drive when sink device is on and PCH is powered down.

NOTE:
Place D4701 near to DP connector

NOTE:
Place those AC Caps near to DP connector.



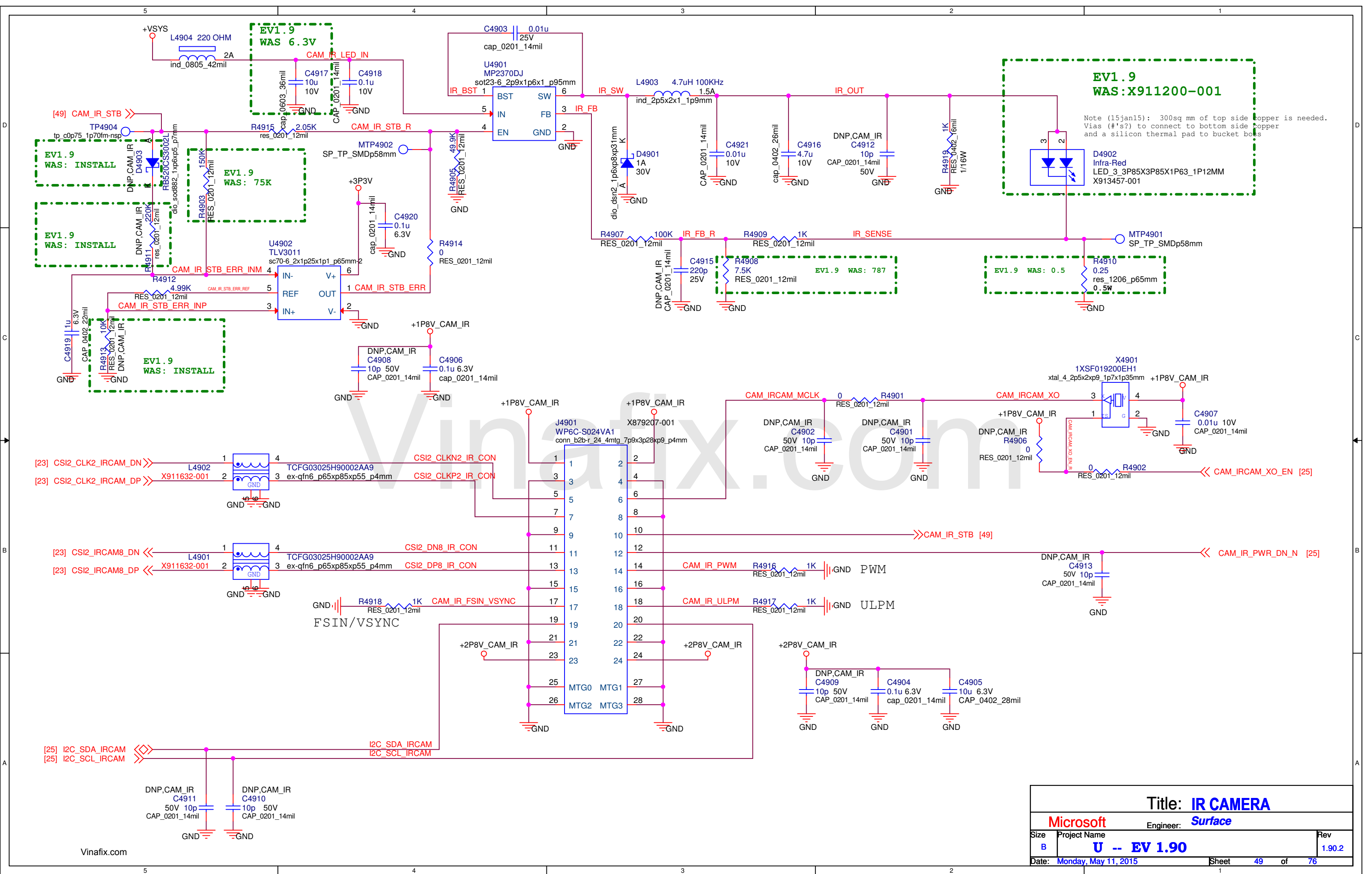
Title: mDP	
Microsoft	Engineer: Surface
Size B	Project Name U -- EV 1.90
Date: Monday, May 11, 2015	Rev 1.90.2
Sheet 47	of 76



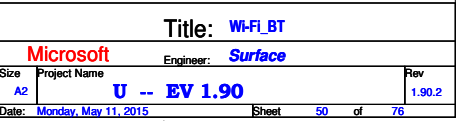
12MHz Crystal

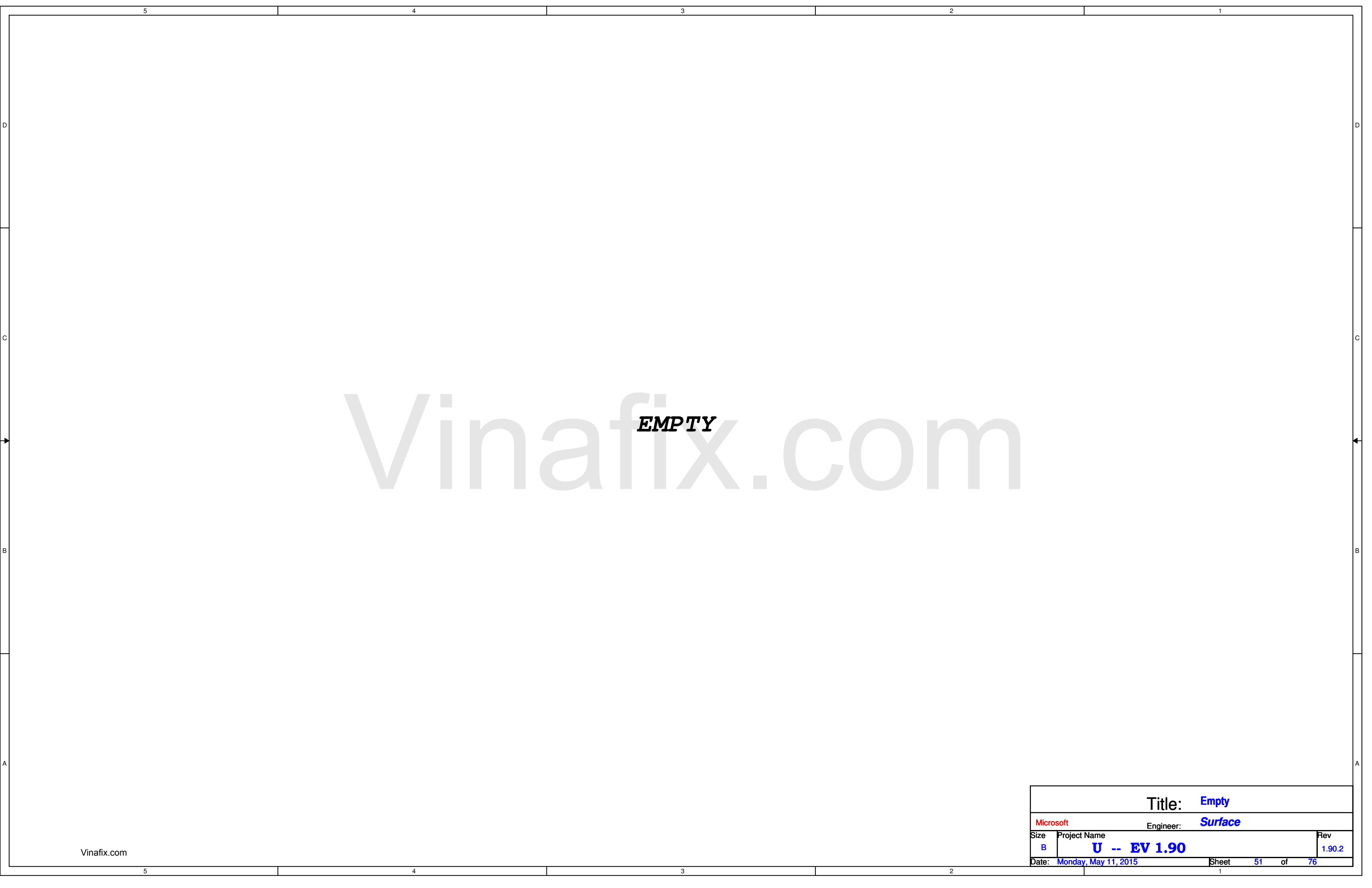
SDR104: 800mA

Title: SDXC			
Microsoft		Engineer: Surface	
Size	Project Name	Rev	
C	U -- EV 1.90	1.90.2	
Date:	Monday, May 11, 2015	Sheet	48 of 76

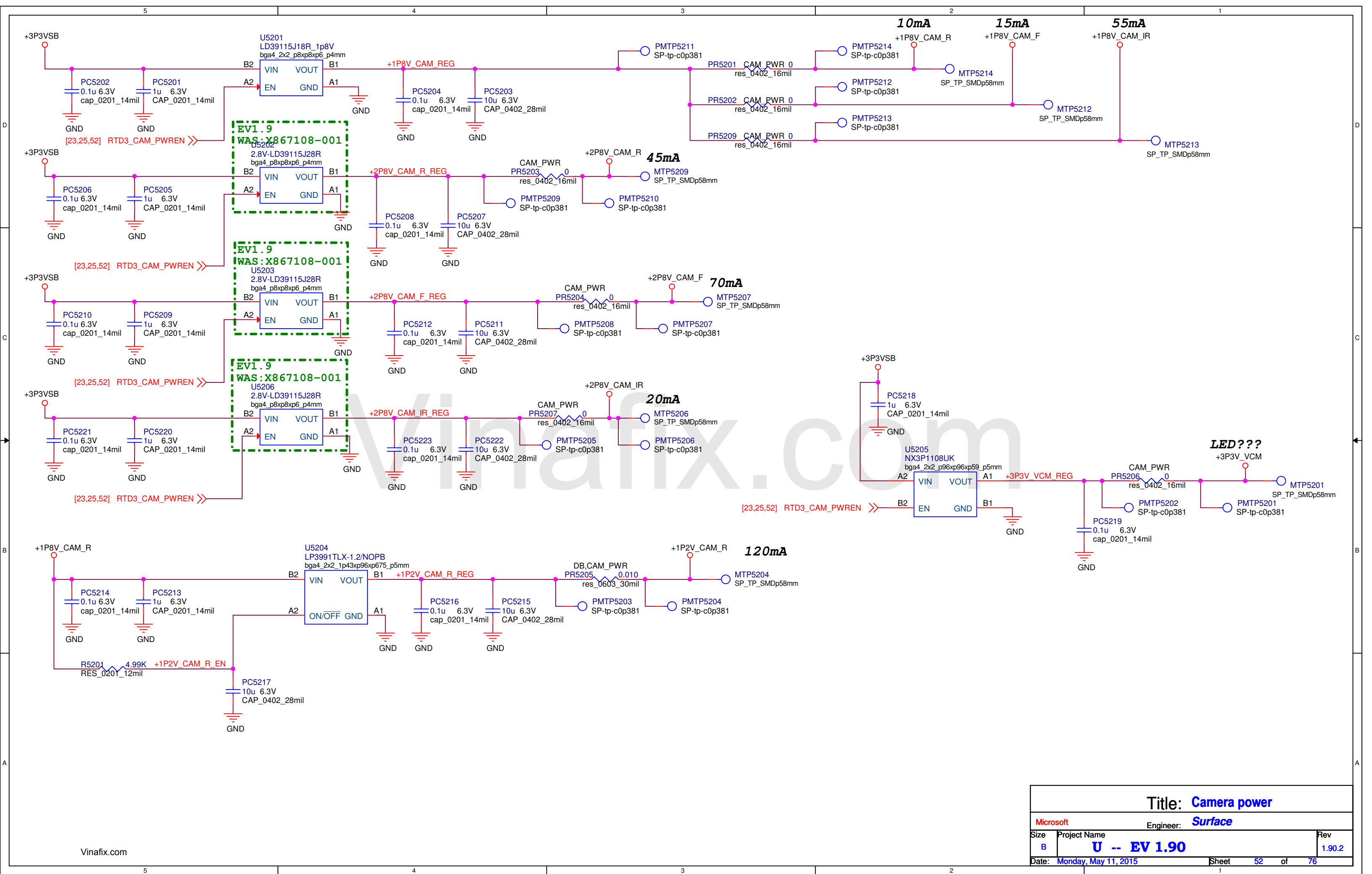


Title: IR CAMERA		
Microsoft Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 49	of 76

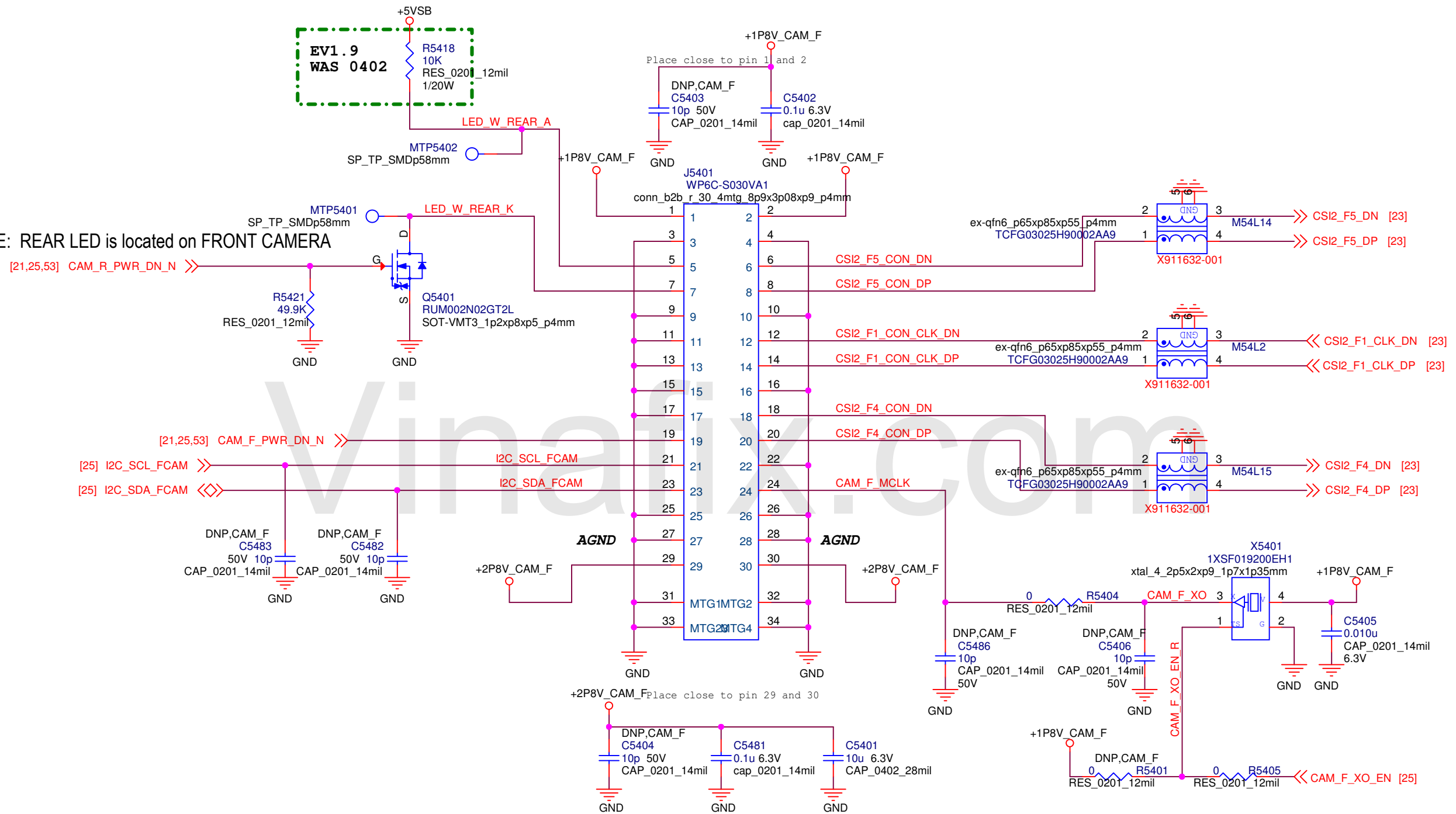


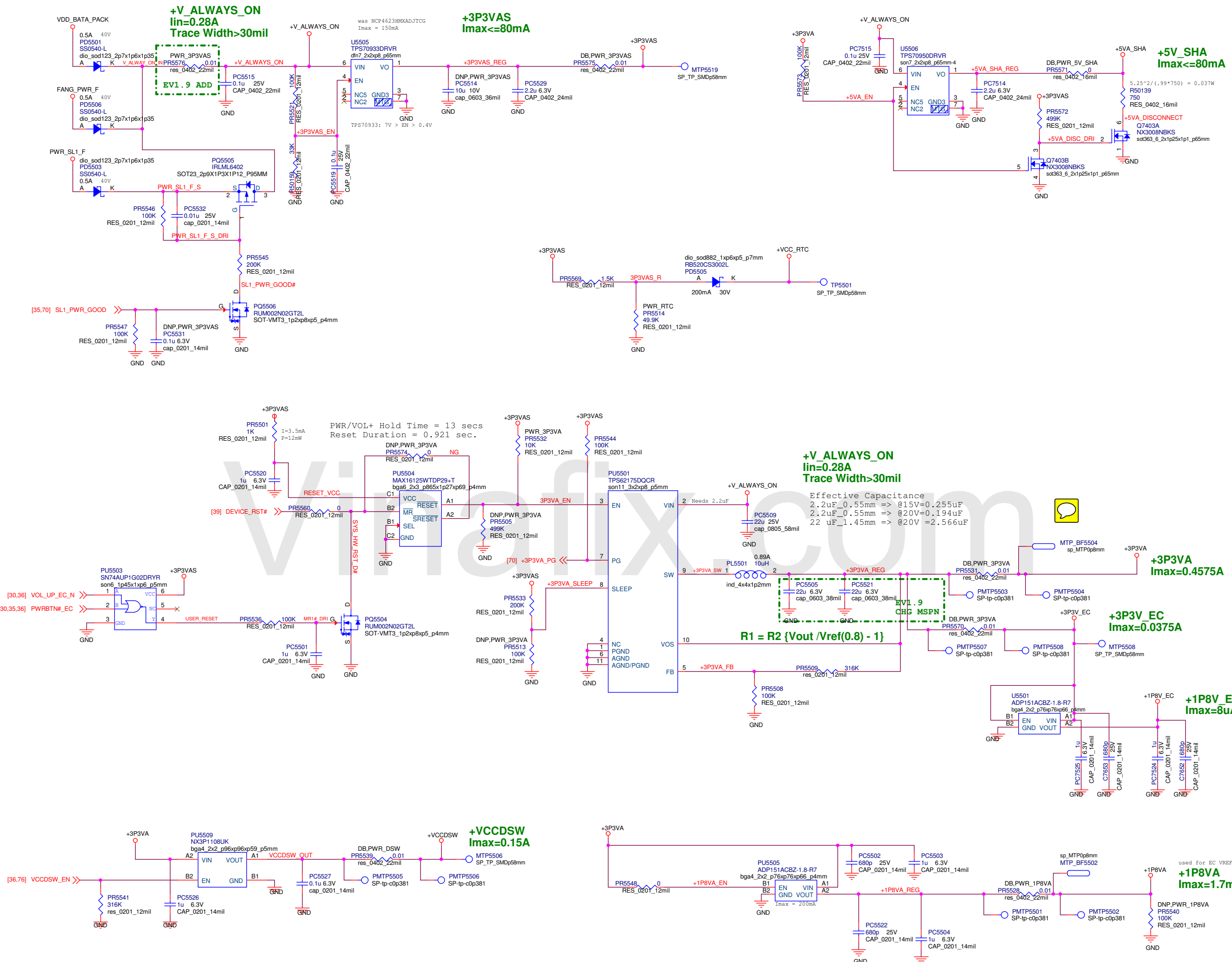


Title: Empty		
Microsoft Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 51	of 76

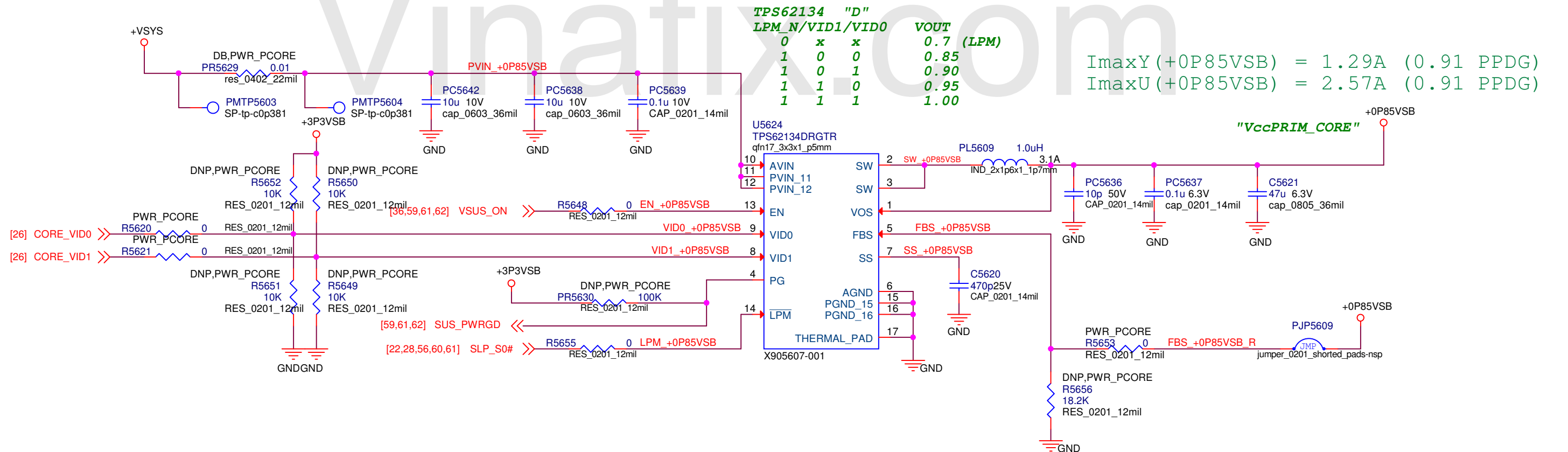
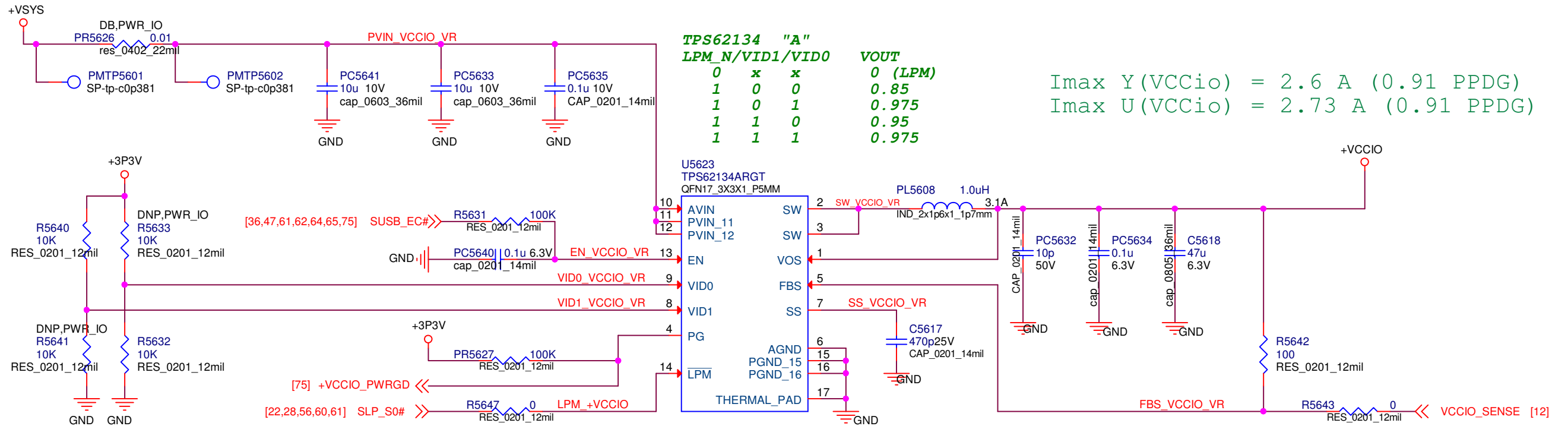


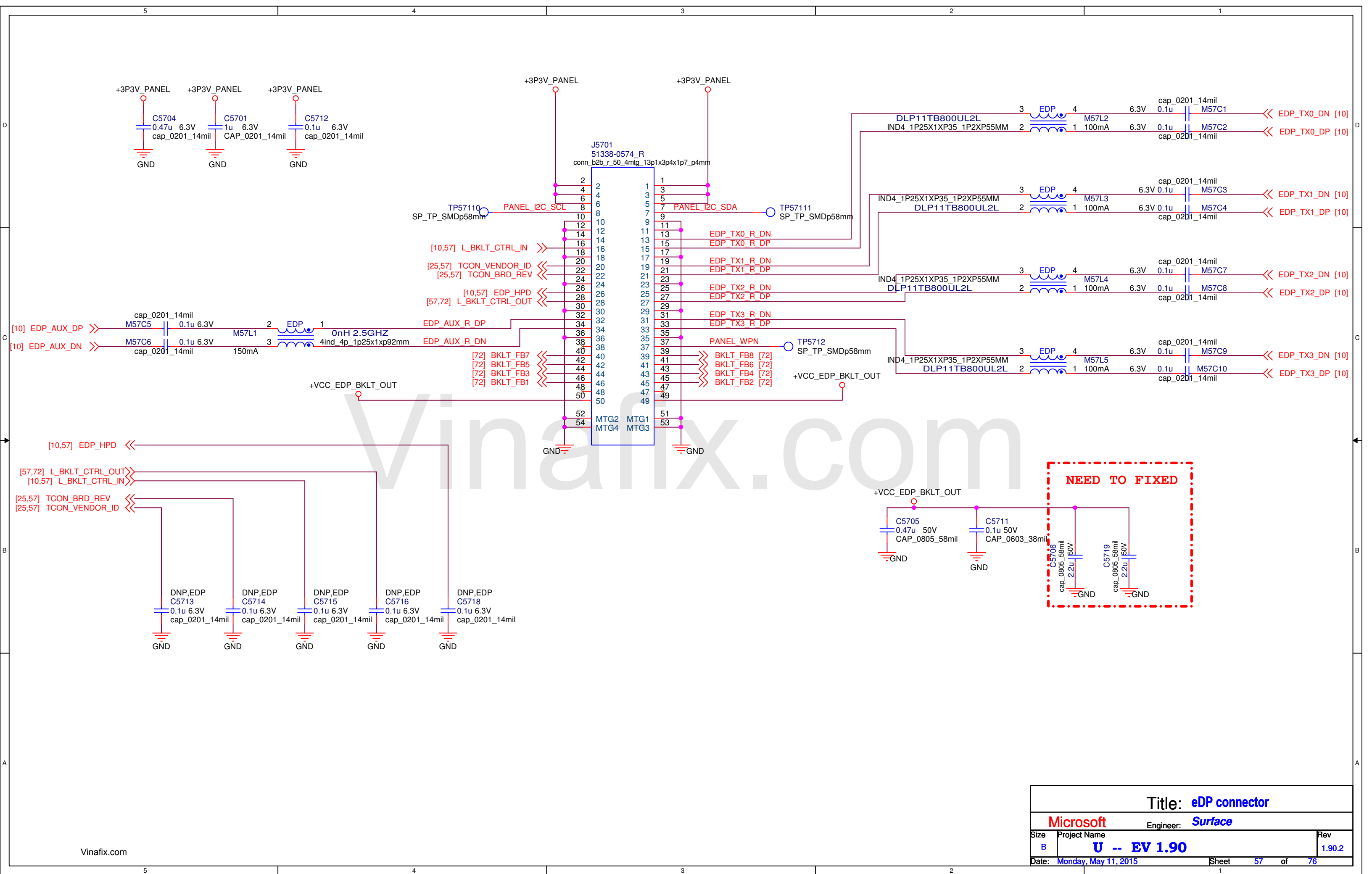
NOTE: REAR LED is located on FRONT CAMERA



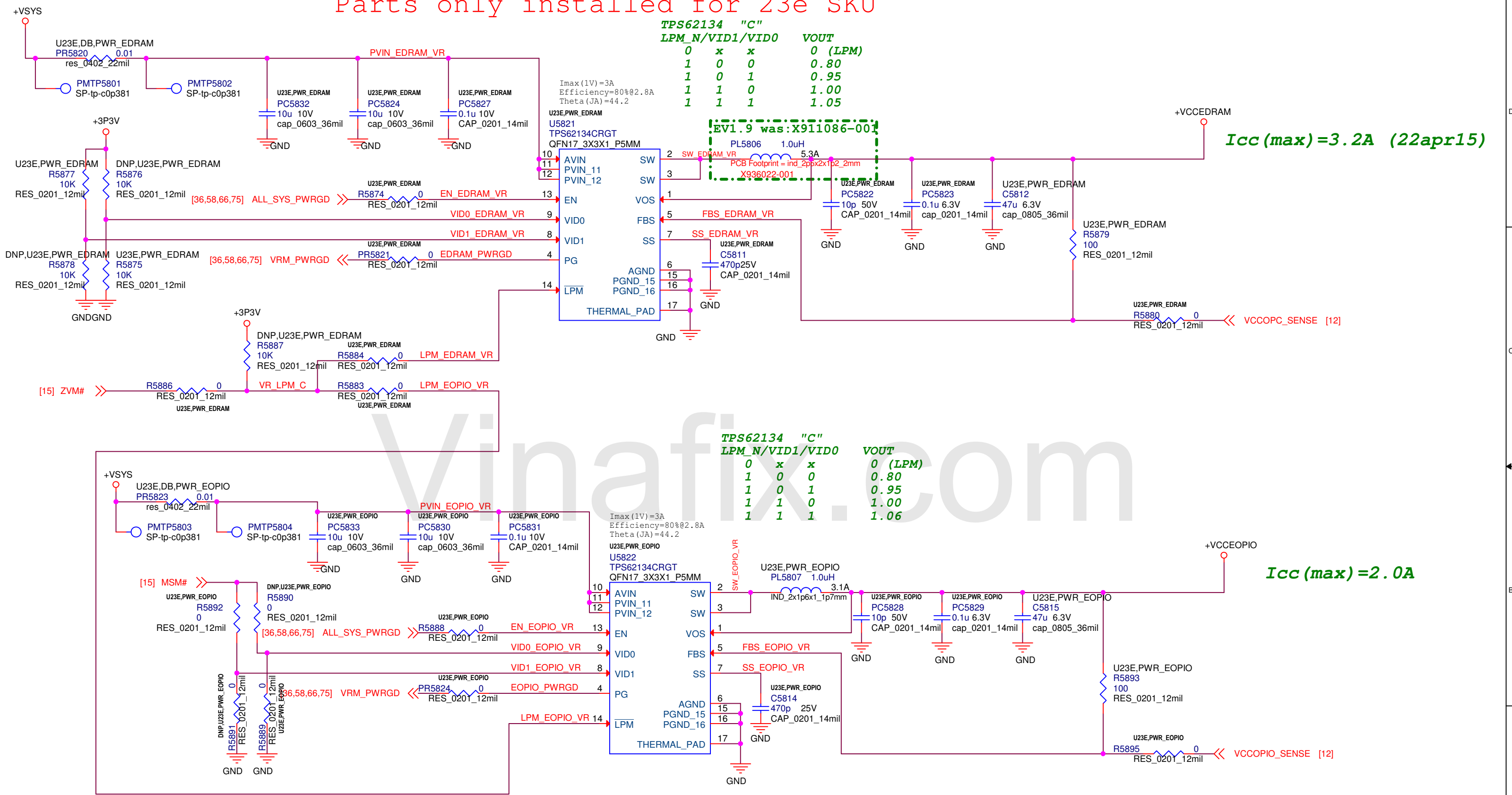


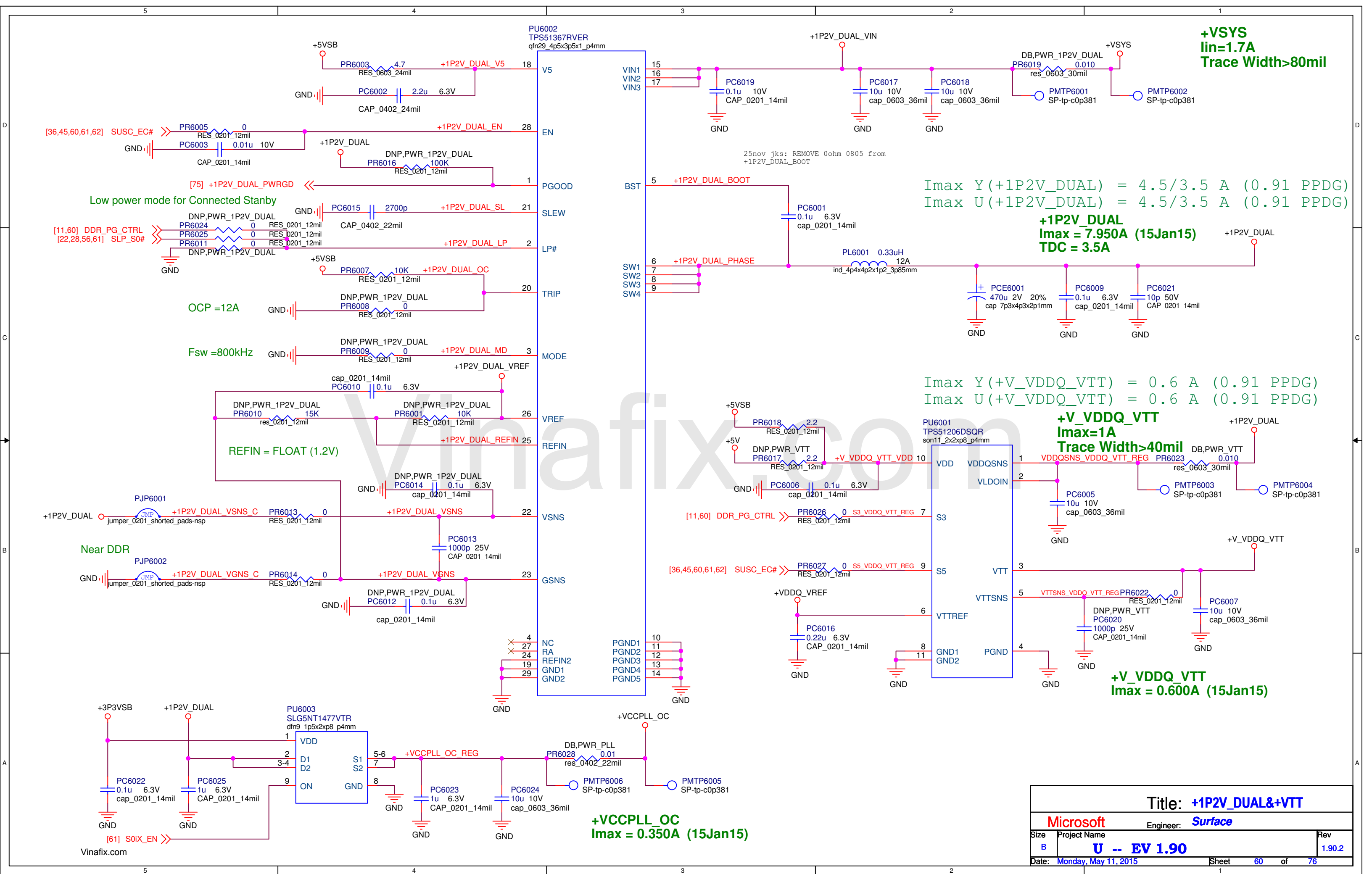
Title: +3P3VA & +5VA			
Microsoft	Engineer: Surface		
Size	Project Name		Rev
C	U -- EV 1.90		1.90.2
Date:	Monday, May 11, 2015	Sheet	55 of 76



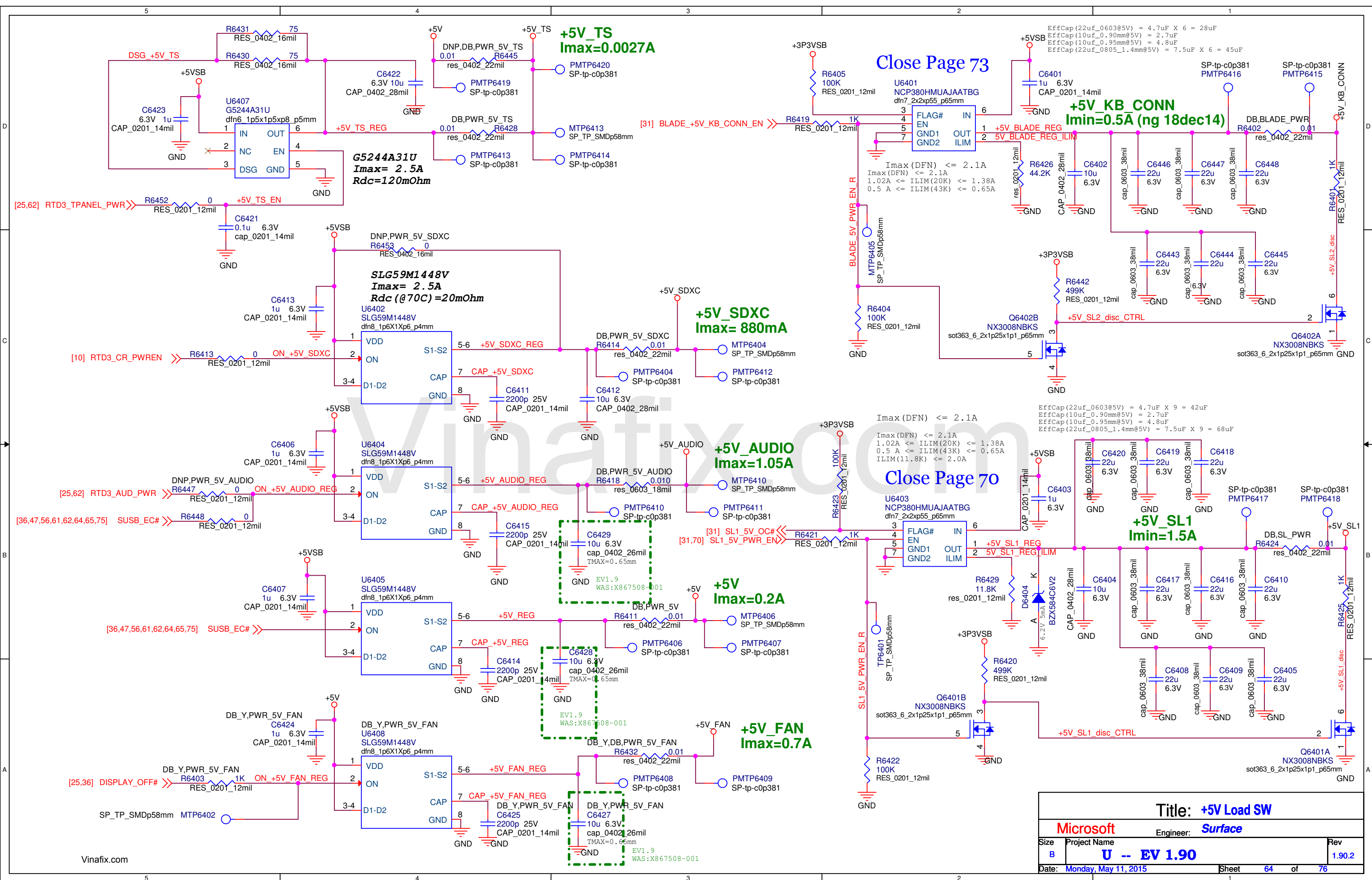


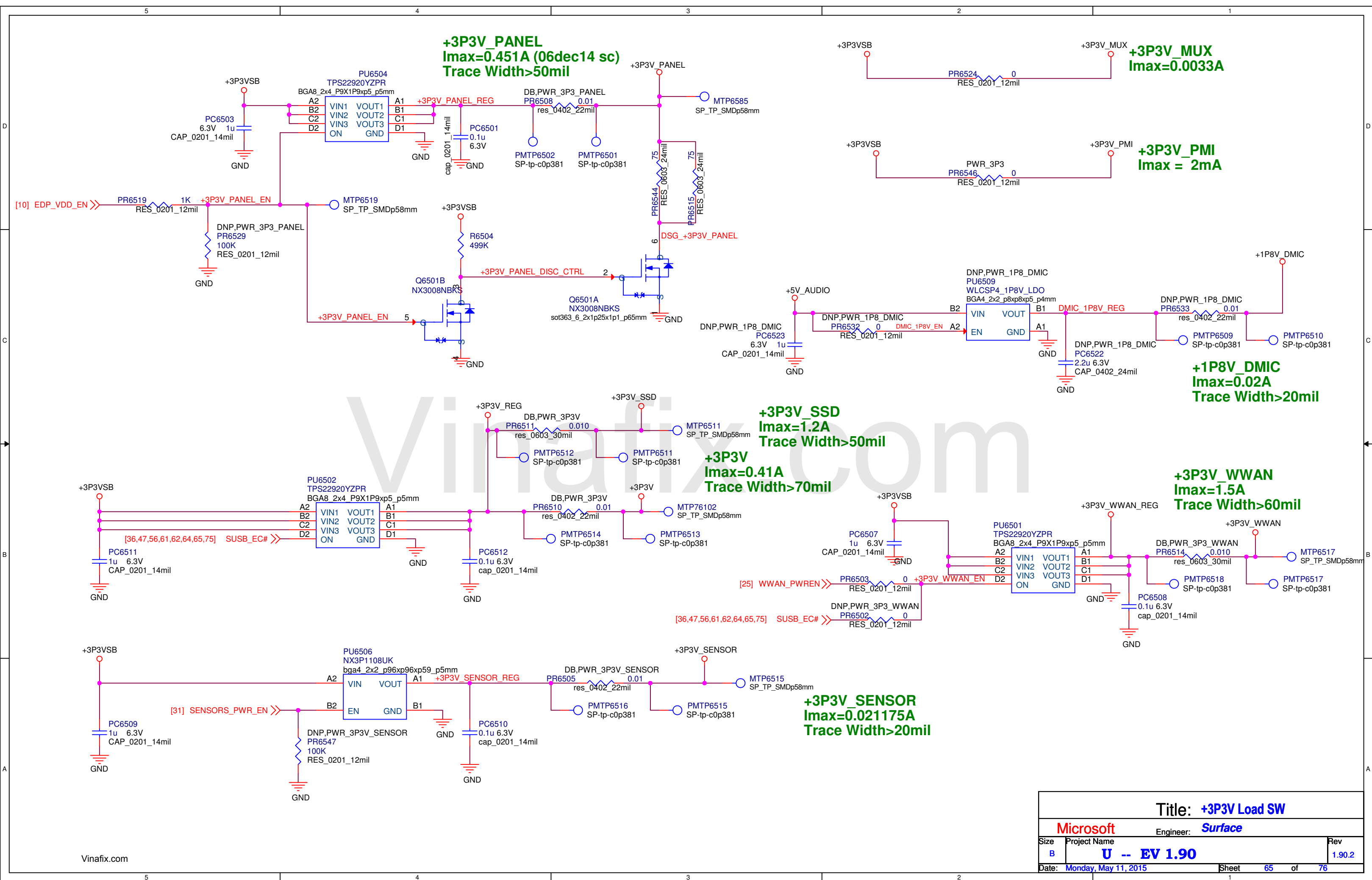
Parts only installed for 23e SKU

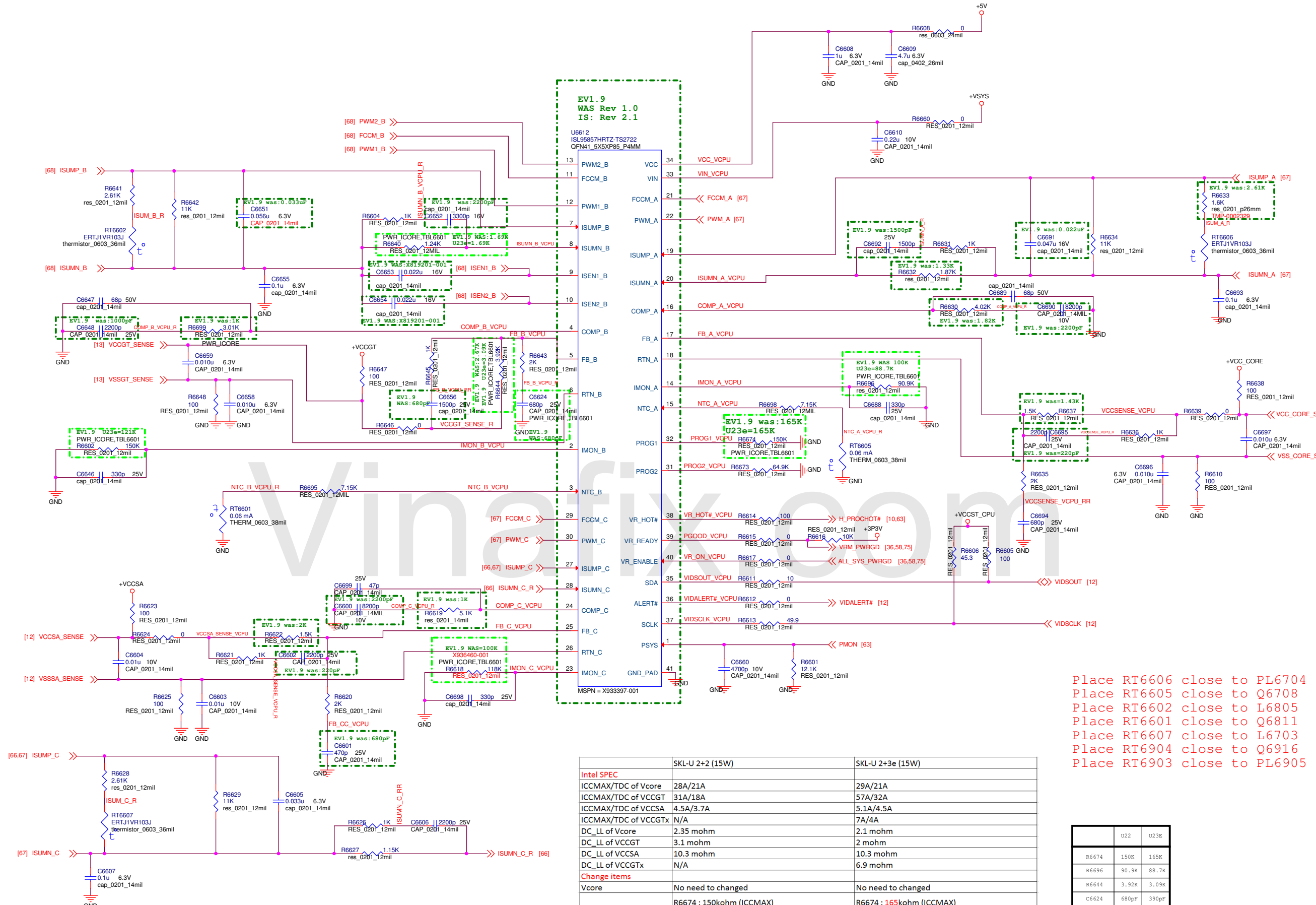




Title: +1P2V_DUAL&+VTT		
Microsoft		Engineer: Surface
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 60	of 76



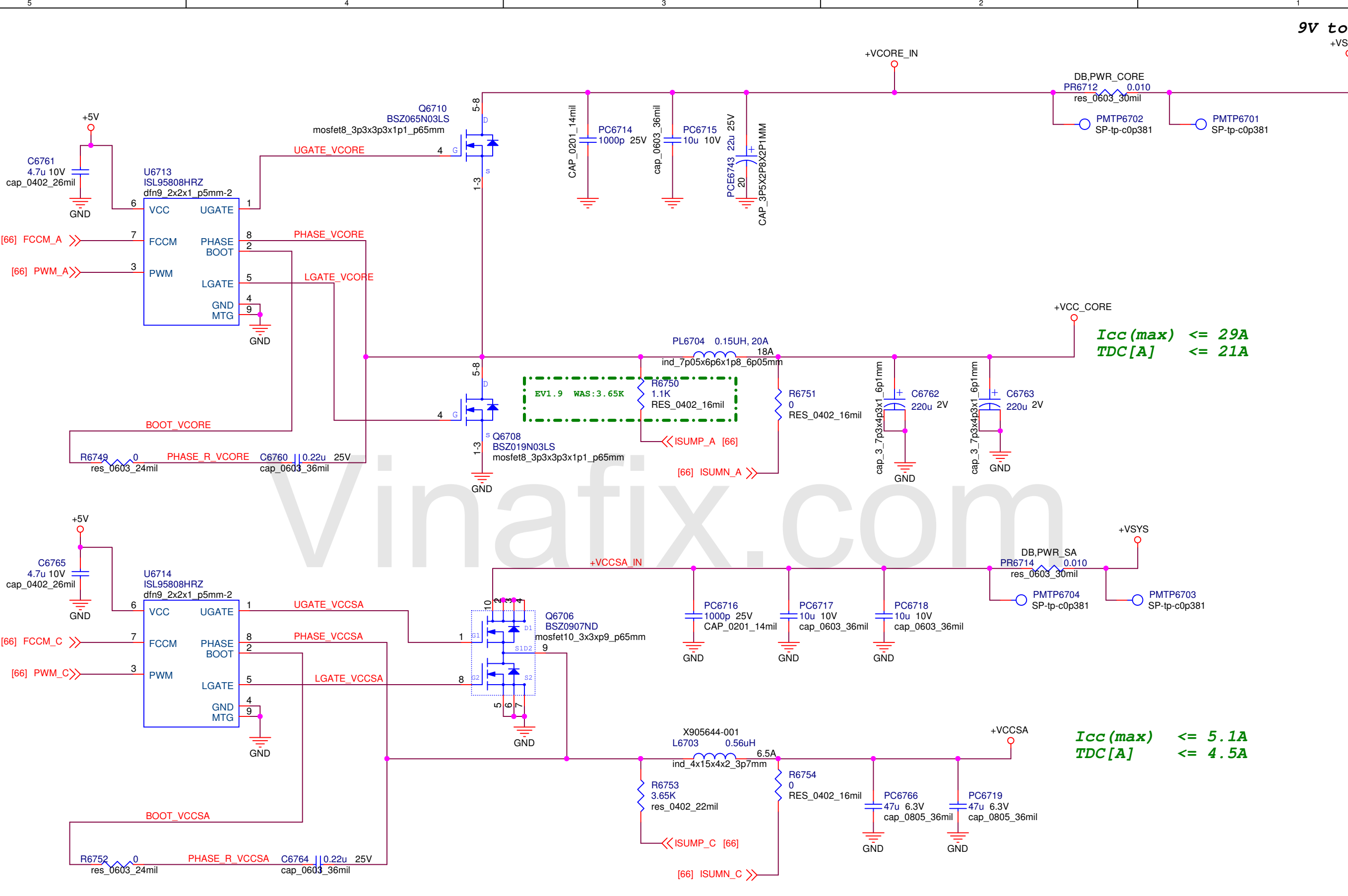




Place RT6606 close to PL6704
Place RT6605 close to Q6708
Place RT6602 close to L6805
Place RT6607 close to L6703
Place RT6904 close to Q6916
Place RT6903 close to PL6905

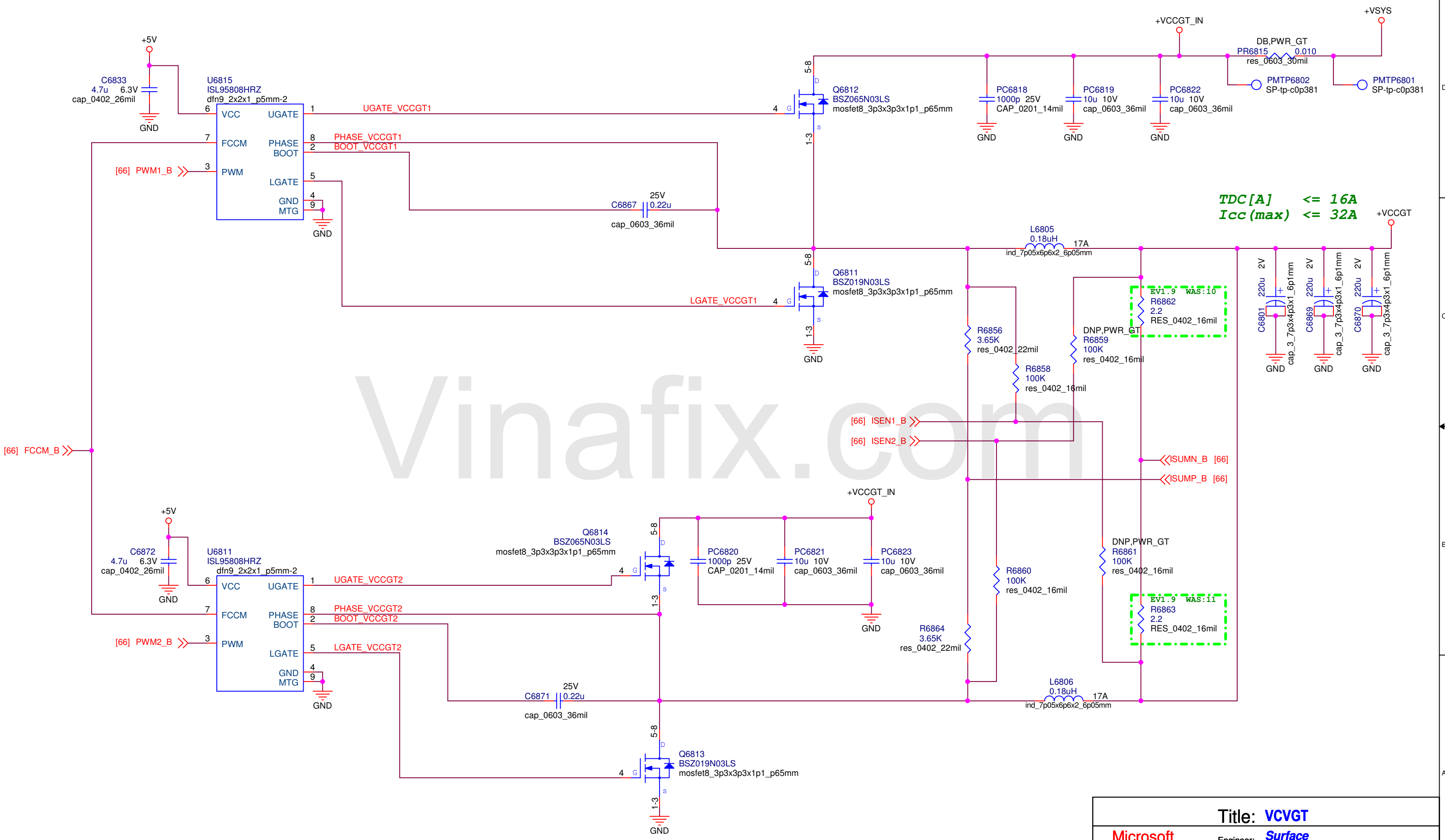
	SKL-U 2+2 (15W)	SKL-U 2+3e (15W)
Intel SPEC		
ICCMAX/TDC of Vcore	28A/21A	29A/21A
ICCMAX/TDC of VCCGT	31A/18A	57A/32A
ICCMAX/TDC of VCCSA	4.5A/3.7A	5.1A/4.5A
ICCMAX/TDC of VCCGTx	N/A	7A/4A
DC_LL of Vcore	2.35 mohm	2.1 mohm
DC_LL of VCCGT	3.1 mohm	2 mohm
DC_LL of VCCSA	10.3 mohm	10.3 mohm
DC_LL of VCCGTx	N/A	6.9 mohm
Change items		
Vcore	No need to changed	No need to changed
VCCGT	R6674 : 150kohm (ICCMAX) R6640 : 1.24kohm (60A OCP) R6644 : 3.09kohm (LL 3.1mohm)	R6674 : 165kohm (ICCMAX) R6640 : 1.69kohm (80A OCP) R6644 : 2.68kohm (LL 2mohm)
VCCSA	No need to changed	No need to changed
VCCGTx	Disable U6916	Enable U6916

	U22	U23E
R6674	150K	165K
R6696	90.9K	88.7K
R6644	3.92K	3.09K
C6624	680pF	390pF
R6640	1.24K	1.69K
R6602	150K	121K
R6618	118K	100K

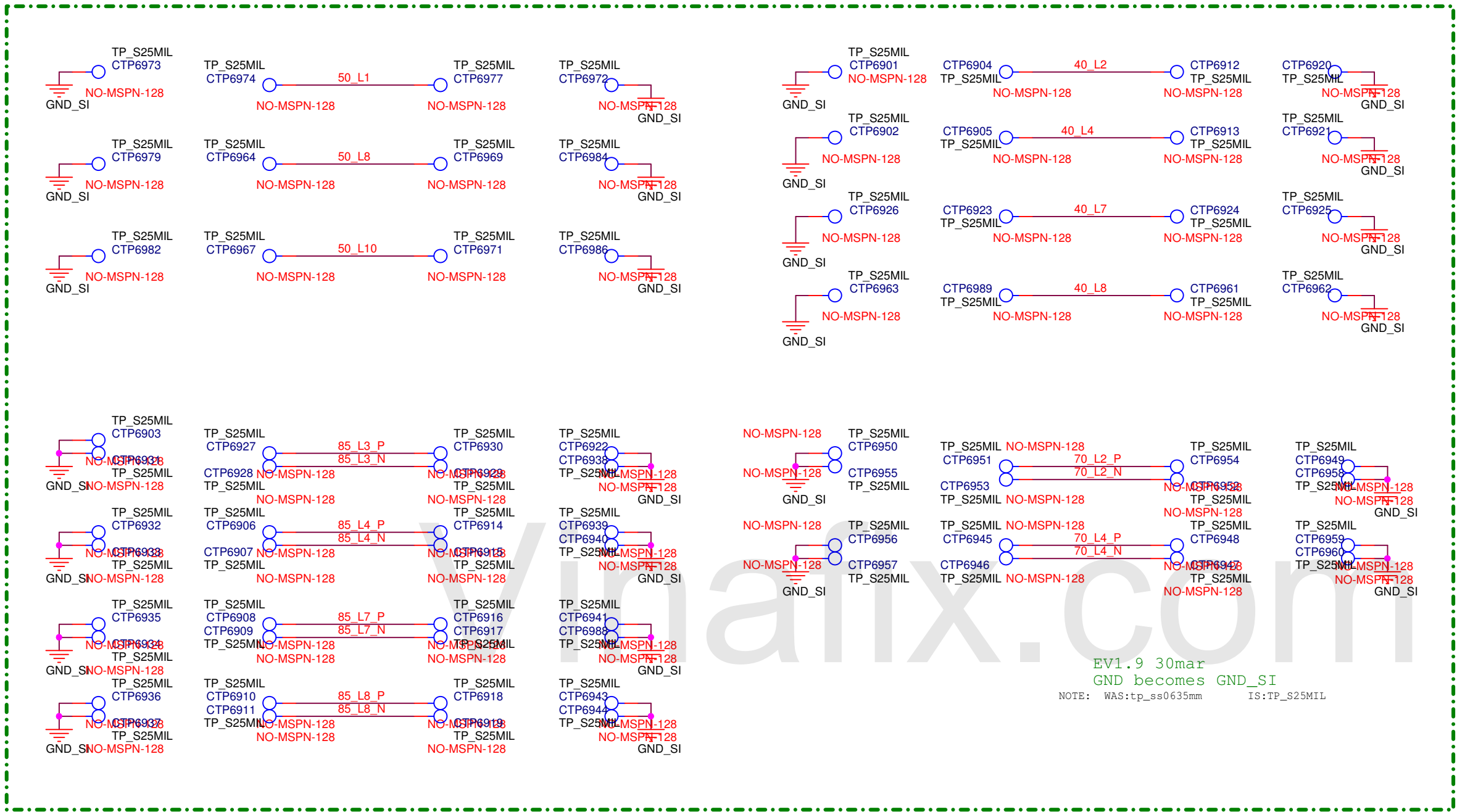


$I_{cc(max)} \leq 29A$
 $TDC[A] \leq 21A$

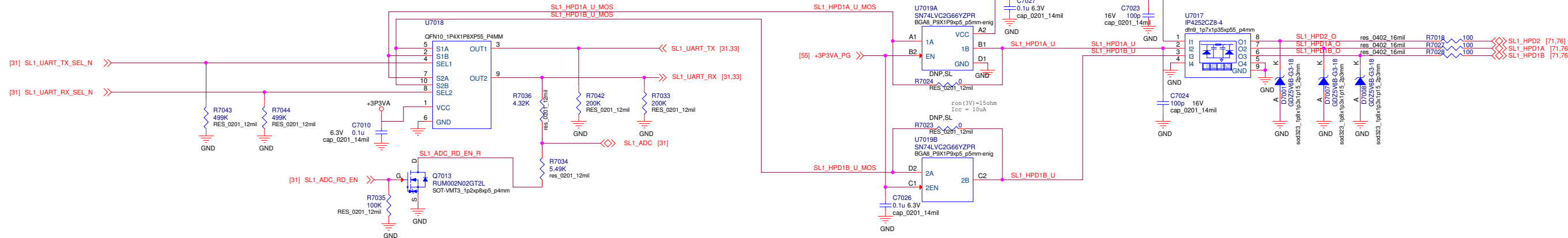
$I_{cc(max)} \leq 5.1A$
 $TDC[A] \leq 4.5A$



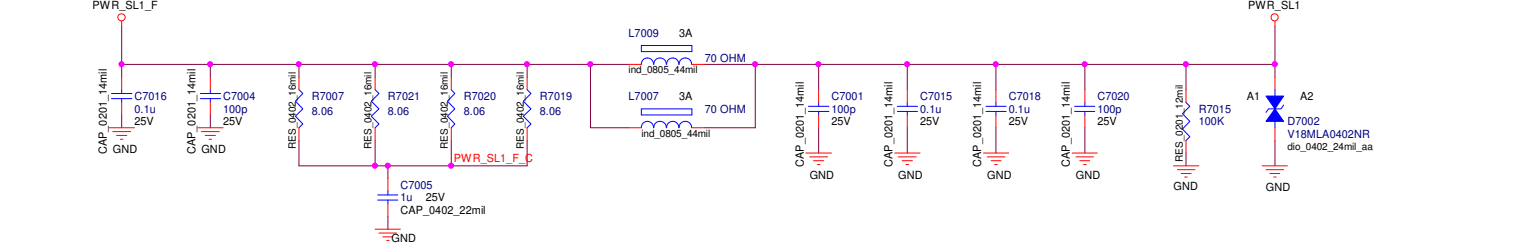
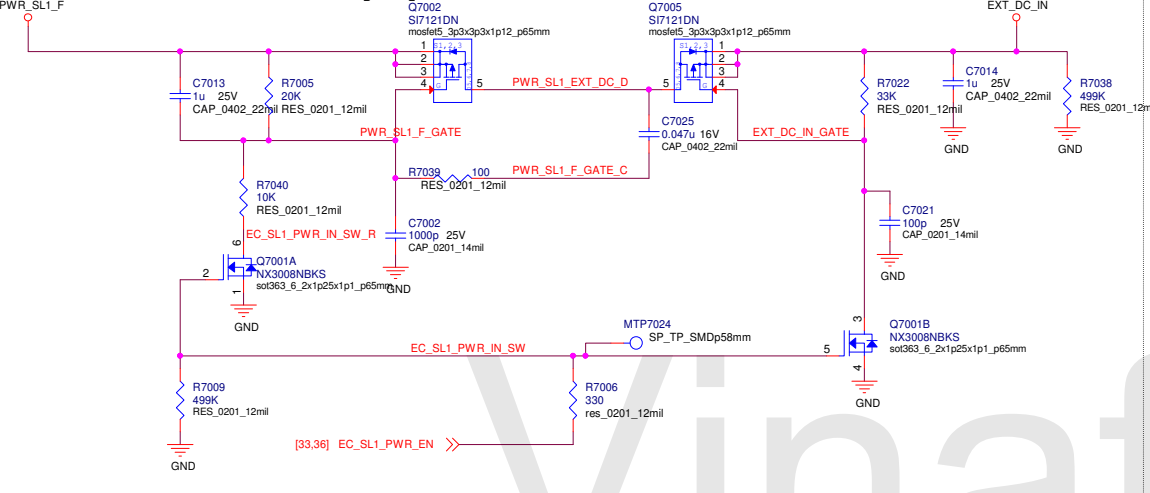
TDC[A] <= 16A
Icc (max) <= 32A



HPD FOR SL1 (ONE/TWO WIRE UART)



[In] SL1 6-12V PWR to EXT DC IN



Present State			Trigger	Output		
SL1_UART_TX	SL1_UART_RX	1W/2W Detect	Initial A/D read	SL1_UART_TX_SEL_N	SL1_UART_RX_SEL_N	SL Polarity
Low	Low	Detach	n/a	Low	Low	Detach
Low	High	1W	n/a	High	Low	Straight up
High	Low	1W	n/a	Low	High	Reversed
High	High	2W	Valid	Low	Low	Straight up
High	High	2W	Invalid	High	High	Reversed

TPS3700 (Voltage Comparator)

INA+	<400mV	OUTA=Low
INB+	>400mV	OUTB=Low

CHG_ACDET

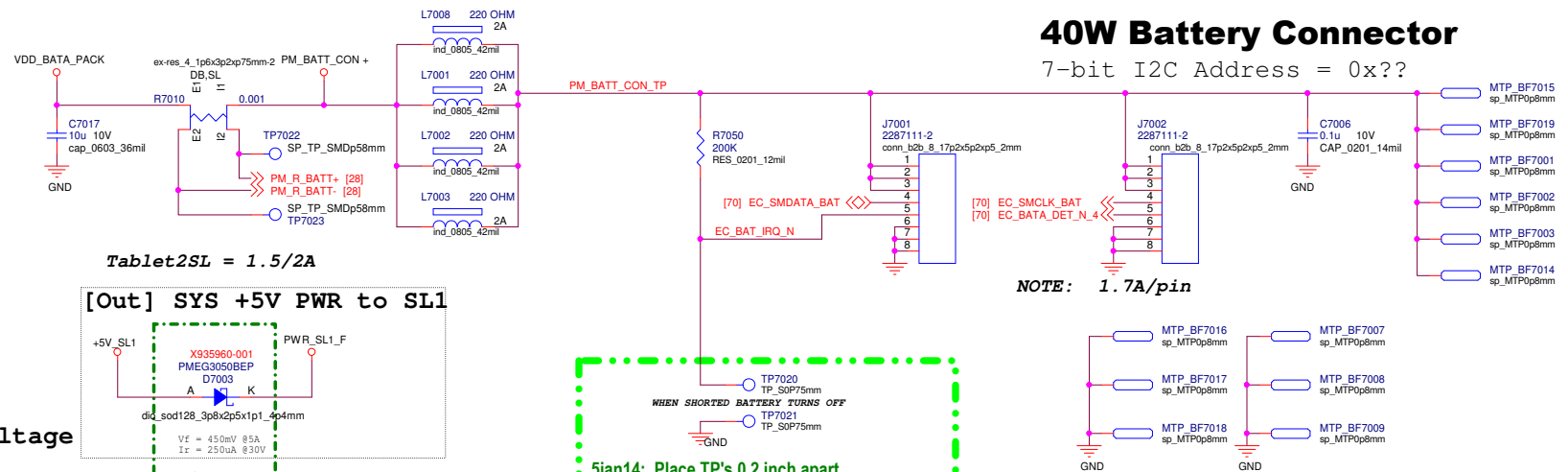
Charger in RESET	0	X
Charger OFF/ SMBUS EN	1	No
Charger ON/ SMBUS EN	1	YES

EC_EXT_DCIN_EN

EXT_DC_IN >9V	0	X
EXT_DC_IN >9V	1	No
EXT_DC_IN >9V	1	YES

40W Battery Connector

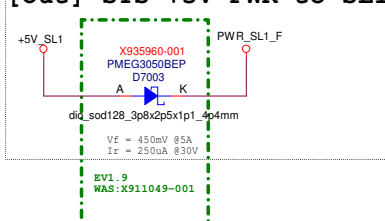
7-bit I2C Address = 0x??



NOTE: 1.7A/pin

Tablet2SL = 1.5/2A

[Out] SYS +5V PWR to SL1



5jan14: Place TP's 0.2 inch apart, Place on component side, near battery. Must be accessible when battery is installed

Title: SL1 PWR/ BATT CONN	
Microsoft	Engineer: Surface
Size A2	Project Name: U -- EV 1.90
Date: Monday, May 11, 2015	Sheet 70 of 76

[31] SL1_3P3V_DIS

isolated ground on layer 2 to tie Cin GND, Cout GND, and controller PGND together. Then tie this isolated ground plane to main GND under the exposed pads.

+VCC_EDP_BKLT_IN
I_{max}=??A
TDC=??A

jks 15dec14:
EffCap (10u@8.7V) = 1.5uF
EffCap (22u@8.7V) = 3.6uF
Novatek: Cin = 4.7uF

EV1.9
WAS NNT50273QG/A

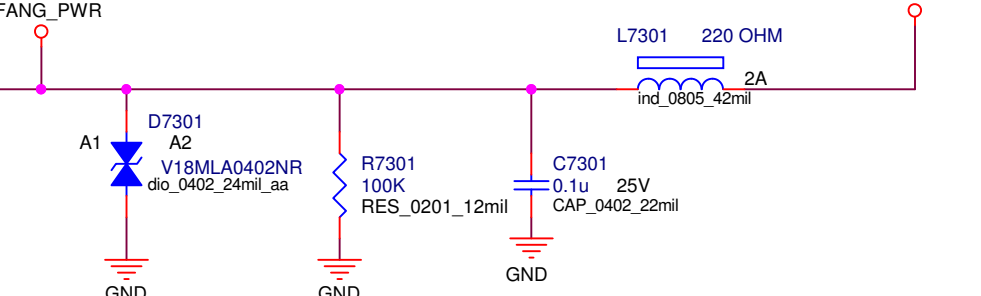
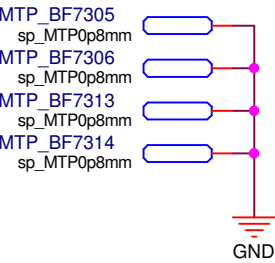
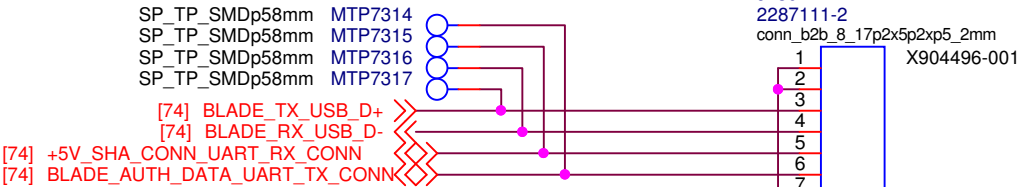
EV1.9
was: INSTALL

EV1.9 install

- MTP7202 SP_TP_SMDp58mm << BKLT_FB1 [57,72]
- MTP7203 SP_TP_SMDp58mm << BKLT_FB2 [57,72]
- MTP7206 SP_TP_SMDp58mm << BKLT_FB3 [57,72]
- MTP7210 SP_TP_SMDp58mm << BKLT_FB4 [57,72]
- MTP7204 SP_TP_SMDp58mm << BKLT_FB5 [57,72]
- MTP7205 SP_TP_SMDp58mm << BKLT_FB6 [57,72]
- MTP7207 SP_TP_SMDp58mm << BKLT_FB7 [57,72]
- MTP7208 SP_TP_SMDp58mm << BKLT_FB8 [57,72]

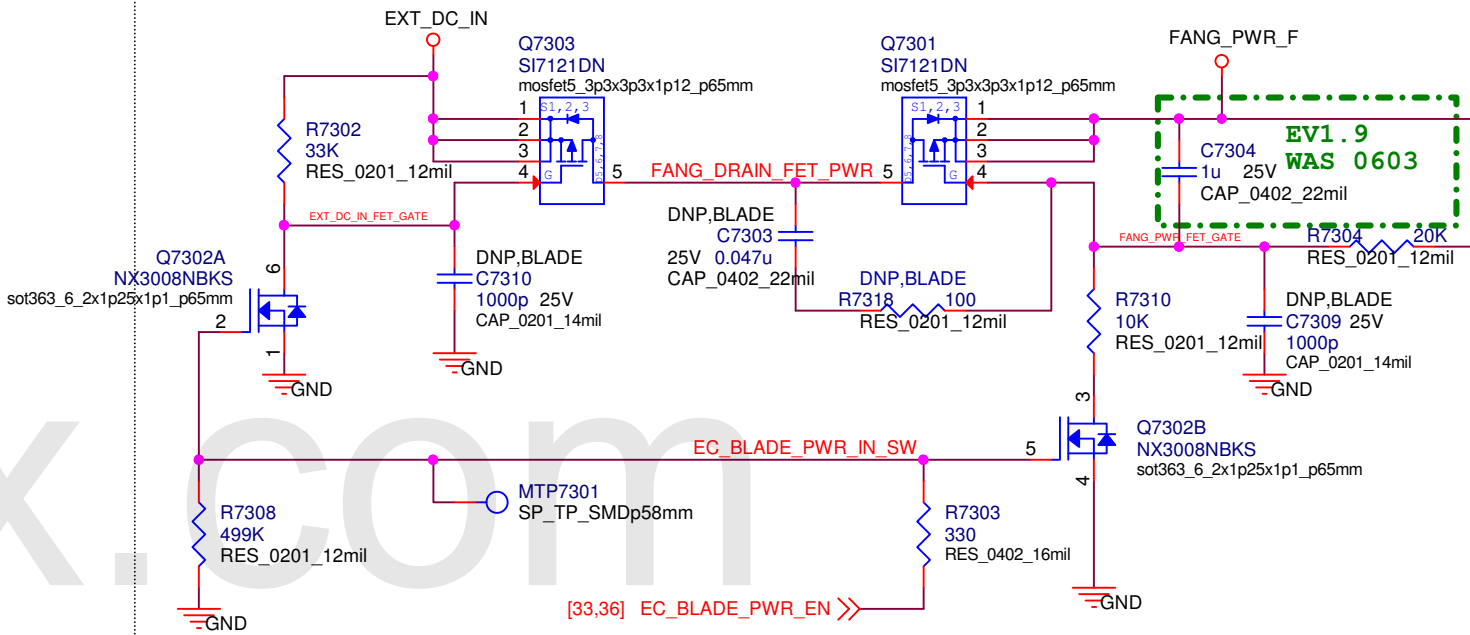
+5V_KB_CONN
Imax = 0.5A

BLADE Connector



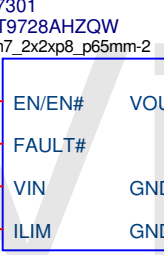
eFang power = 3.5A max
using +1 rule

[In] BLADE 6-12V PWR to EXT DC IN Imax=4.5A

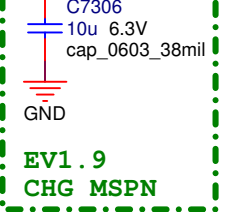


Rds(on) = 120mOhm (typ)
Iq = 170uA

+5V_SHA_CONN
Imax = 75mA



Imax = 1.4A
50mA <= ILIM (connected to VIN) <= 100mA

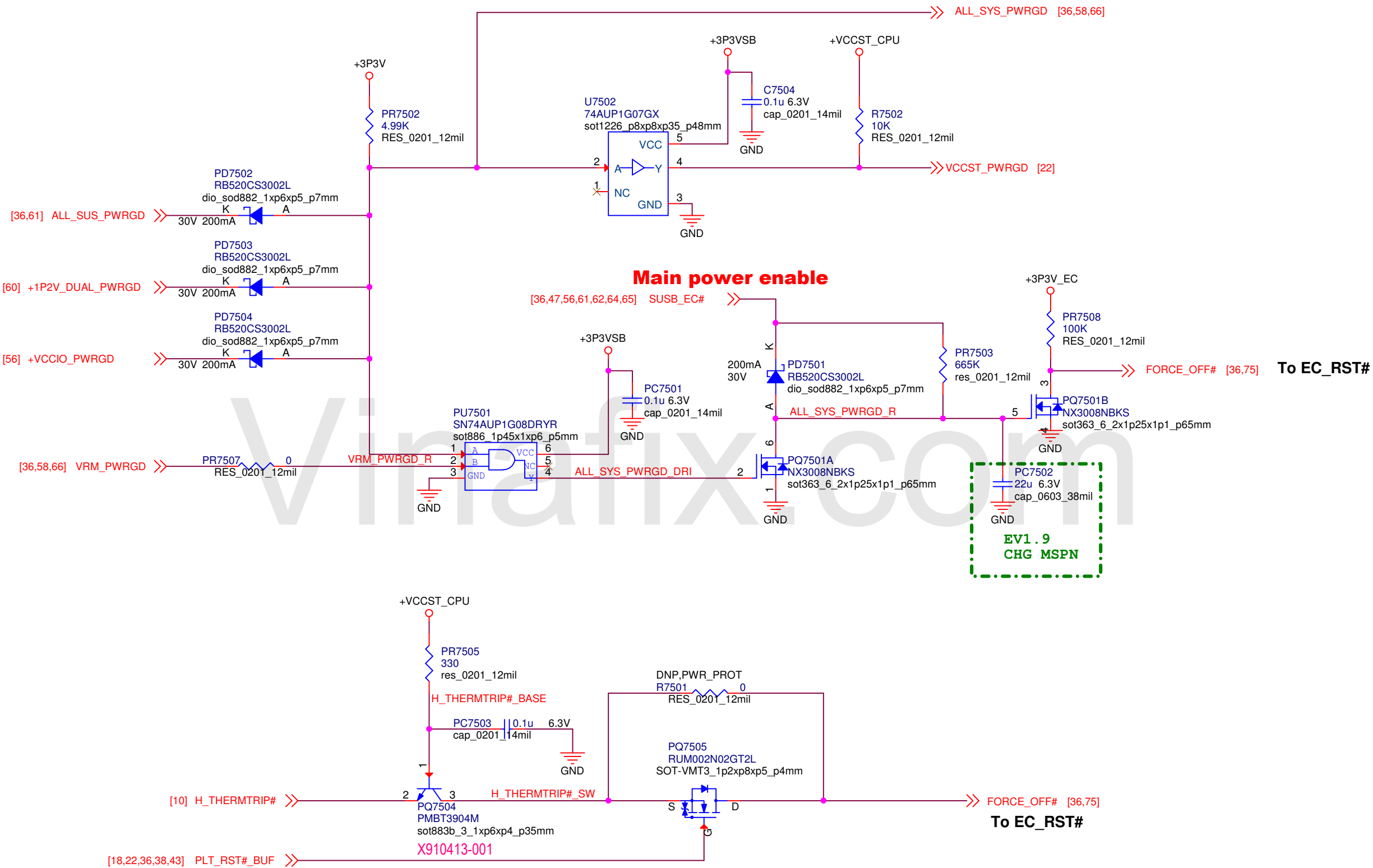


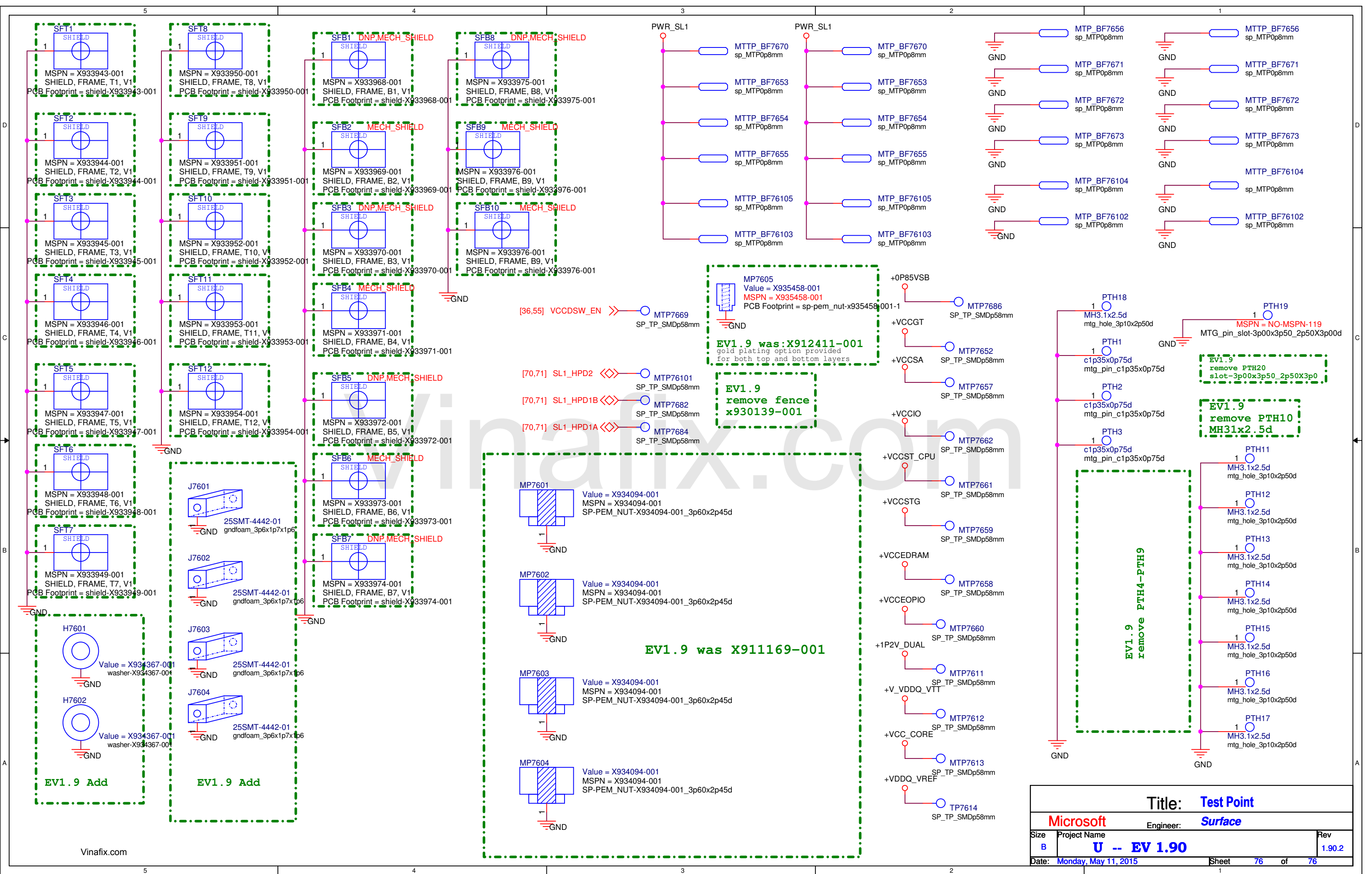
V{operating} = 4.5 to 13.8 Max

current = 3A

LTE eFANG PWR = 2.10A(min)
2.47A(nom)
2.84A(max)

Title: BLADE PWR		
Microsoft		Engineer: Surface
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 73	of 76





Title: Test Point		
Microsoft Engineer: Surface		
Size B	Project Name U -- EV 1.90	Rev 1.90.2
Date: Monday, May 11, 2015	Sheet 76 of 76	